

RL78/L23

Bank swapping demo

Abstract

This application note describes how to store a 24-hour clock display program in one bank and a temperature display program in another bank, then execute the bank swap function to switch between the two banks using a long press on the user switch.

Target Device

RL78/L23

When using this application note with other MCUs, conduct careful evaluation after making modifications to meet the specifications of the alternate MCU.

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1. Specifications

RL78/L23 products equipped with 512KB or 256KB of code flash memory can divide the user area of the code memory flash into two bank areas and store a program in each bank. The bank swap function is used to switch the addresses of these two banks. After the addresses are switched—referred to as a bank swap—the program starts from the switched-in bank, referred to as the “active bank” herein.

This application note uses an RL78/L23 with a code flash memory capacity of 512KB and describes how to switch the start program area with a long press on the user switch in order to execute the programs stored in areas 00000H to 3FFFFH and 40000H to 7FFFFH.

At startup after writing the program, as described in section 8.4, the BANK1 program (24-hour clock display program) in area 00000H to 3FFFFH is executed, then “RL78/L23” followed by “BANK1 C” is displayed on the LCD. When the user switch is long pressed, “DEMO CHG” is displayed on the LCD and the bank swap function is executed. After the banks are switched and the program is restarted, the BANK2 program (temperature display program) in area 00000H to 3FFFFH is executed, then “RL78/L23” followed by “BANK2 T” is displayed on the LCD. In the same manner, if the user switch is long pressed while the BANK2 program is running, the bank swap function will be executed.

Table 1-1 lists the peripheral functions used for BANK1 and their applications, Table 1-2 lists the peripheral functions used for BANK2 and their applications, Figure 1.1 shows the operation overview, and Figure 1.2 shows the state transition diagram.

Table 1-1 BANK1 Peripheral Functions Applications

Peripheral Function	Application
LCD controller/driver	LCD display
Realtime clock (RTC)	Counts the time
Channel 1 of timer array unit 0 (TAU0_1)	Blinks display on LCD
Channel 2 of timer array unit 0 (TAU0_2)	Determines short/long press on user switch
Channel 3 of timer array unit 0 (TAU0_3)	Counts wait time
Channel 4 of timer array unit 0 (TAU0_4)	Counts time period to prevent chattering
Channel 5 of timer array unit 0 (TAU0_5)	Determines continuous touch (long press) on touch button
Capacitive Touch Sensing Unit (CTS2La)	Measures capacitance generated on touch electrode Changes time using touch buttons
External interrupt INTPO	Detects input from user switch and switches to the time change state

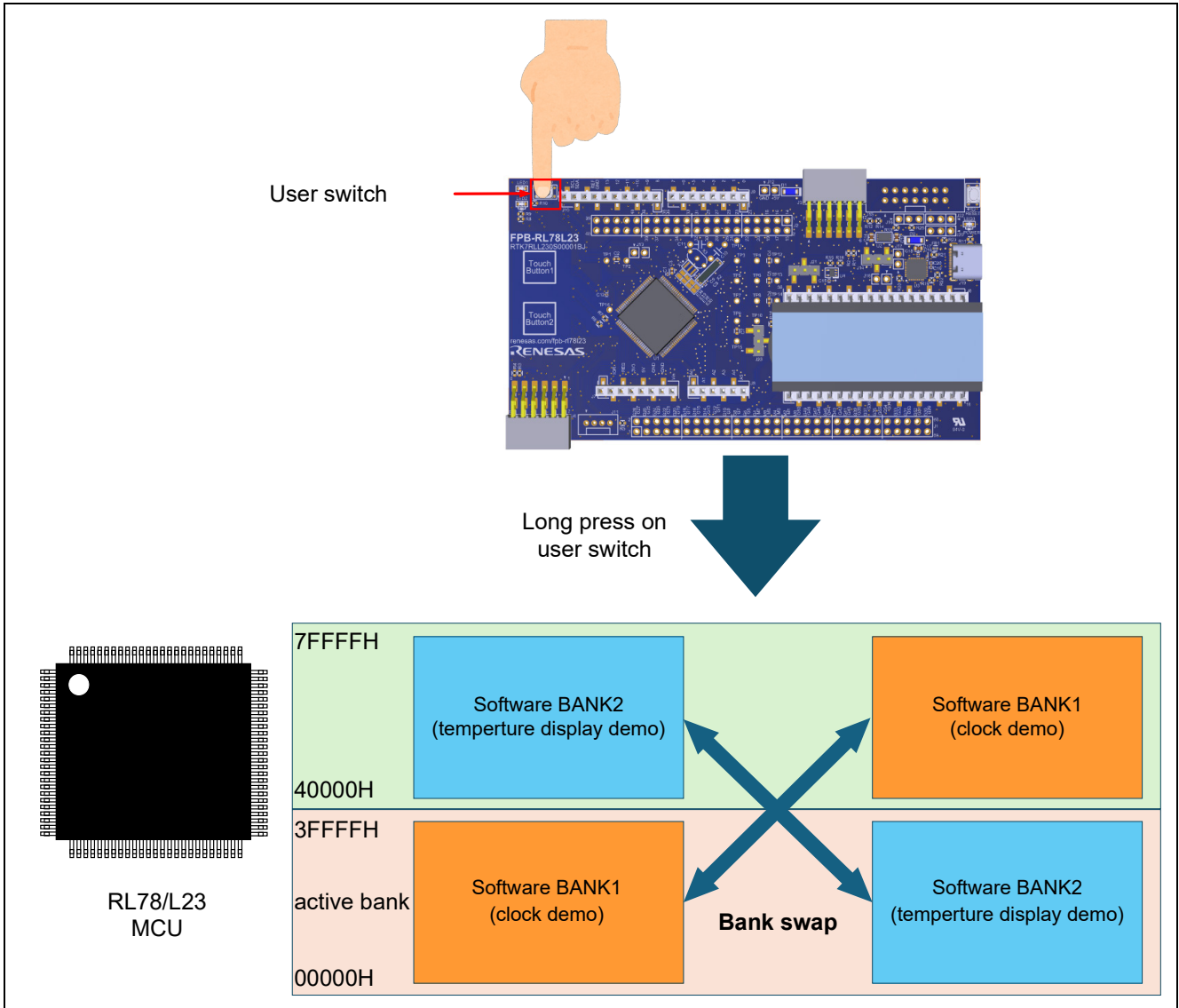
Table 1-2 BANK2 Peripheral Functions Applications

Peripheral Function	Application
LCD controller/driver	LCD display
Realtime clock (RTC)	Determines short/long press on user switch Determines wait state transition period
Channel 3 of timer array unit 0 (TAU0_3)	Counts wait time
Channel 5 of timer array unit 0 (TAU0_5)	Determines continuous touch (long press) on touch button
Capacitive Touch Sensing Unit (CTS2La)	Measures capacitance generated on the touch electrode
External interrupt INTPO	Detects input from user switch and switches to the temperature change state

The RL78/L23 LCD controller/driver can use external resistance division, internal voltage boosting, or capacitor split to generate LCD drive voltage. For details, refer to 3.3 LCD Drive Voltage Generator.

The sample code uses capacitor split for the LCD drive voltage generator.

Figure 1.1 Operation Overview

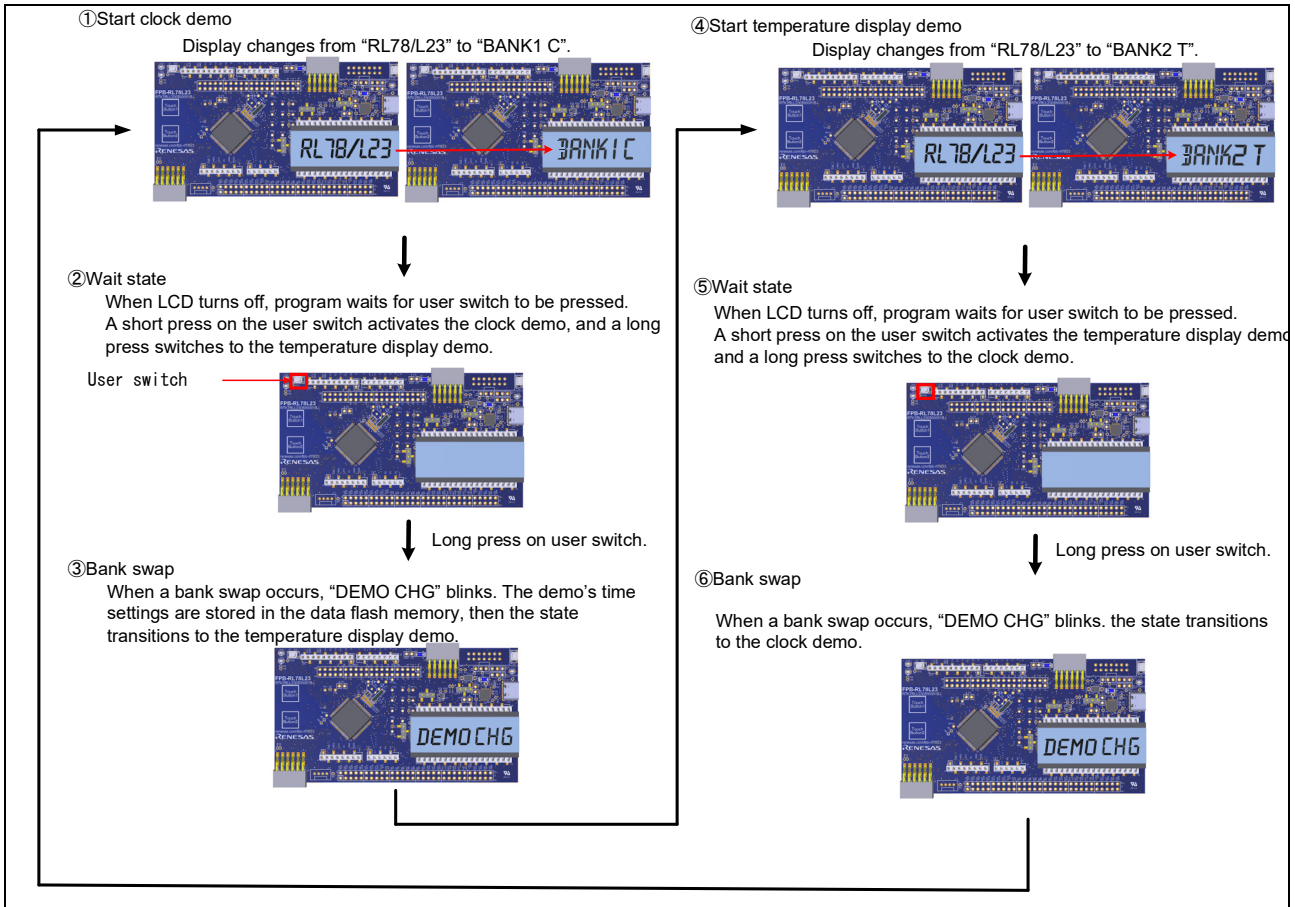


User Switch	State
Long press	Bank swap operation

For details on BANK1 and BANK2 software, refer to the following application notes.

- Reference application note for BANK1
RL78/L23 LCD Display (Clock Demo) (R01AN7852)
(The latest versions can be downloaded from the Renesas Electronics website.)
- Reference application note for BANK2
RL78/L23 LCD Display (Temperature Display Demo) (R01AN7853)
(The latest versions can be downloaded from the Renesas Electronics website.)

Figure 1.2 State Transition Diagram



2. Operation Confirmation Conditions

The sample code accompanying this application note has been run and confirmed under the conditions below.

Table 2-1 shows the confirmation conditions that operate on BANK1, and Table 2-2 shows the confirmation conditions that operate on BANK2.

Table 2-1 BANK1 Operation Confirmation Conditions

Item	Contents
MCU used	RL78/L23(R7F100LPL3CFB)
Operating frequencies	<ul style="list-style-type: none"> • High-speed on-chip oscillator clock (f_{HOCO}) : 32MHz(typ.) • CPU/peripheral hardware clock (f_{CLK}) : 32MHz • Subsystem clock XR (f_{SXR}) : 32.768kHz
Operating voltage	3.3V LVD operation(V_{LVD0}) : in reset mode is 2.97 V at the rising edge or 2.91 V at the falling edge.
Integrated development environment (CS+)	CS+ for CC V8.14.00 from Renesas Electronics Corp.
C compiler (CS+)	Renesas CC-RL V1.15.01 from Renesas Electronics Corp.
Integrated development environment (e ² studio)	e ² studio Version 2025-07 from Renesas Electronics Corp.
C compiler (e ² studio)	Renesas CC-RL V1.15.01 from Renesas Electronics Corp.
Integrated development environment (IAR)	IAR Systems IAR Embedded Workbench for Renesas RL78 V 5.20.1
C compiler (IAR)	
Writing tools	Renesas Flash Programmer V3.20.00 from Renesas Electronics Corp.
Smart Configurator	RL78 Smart Configurator V1.14.0 from Renesas Electronics Corp.
Development support tool for the capacitive touch sensor	QE for Capacitive Touch V4.2.0
Board support package (BSP)	V1.91 Smart Configurator.
TOUCH Driver	V2.20 from Renesas Electronics Corp.
CTSU Driver	V2.20 from Renesas Electronics Corp.
Board used	RL78/L23 Fast Prototyping Board (RTK7RLL230S00001BJ)
LCD module	Varitronix VIM-878-DP-FC-S-LV 16 segments x 8 digits Header: 36-pin (18 x 2 rows) x 1 Operating voltage condition: 3V to 4.6V (When using the module with operating voltage other than 3.3V, remove the LCD panel.)

Table 2-2 BANK2 Operation Confirmation Conditions

Item	Contents
MCU used	RL78/L23(R7F100LPL3CFB)
Operating frequencies	<ul style="list-style-type: none"> • High-speed on-chip oscillator clock (f_{HOCO}) : 32MHz(typ.) • CPU/peripheral hardware clock (era) : 32MHz • Low-speed on-chip oscillator clock(f_{LL}) : 32.768kHz
Operating voltage	3.3V LVD operation(V_{LVD0}) : in reset mode is 2.97 V at the rising edge or 2.91 V at the falling edge.
Integrated development environment (CS+)	CS+ for CC V8.14.00 from Renesas Electronics Corp.
C compiler (CS+)	Renesas CC-RL V1.15.01from Renesas Electronics Corp.
Integrated development environment (e ² studio)	e ² studio Version 2025-07from Renesas Electronics Corp.
C compiler (e ² studio)	Renesas CC-RL V1.15.01 from Renesas Electronics Corp.
Integrated development environment (IAR)	IAR Systems IAR Embedded Workbench for Renesas RL78 V 5.20.1
C compiler (IAR)	
Writing tools	Renesas Flash Programmer V3.20.00 from Renesas Electronics Corp.
Smart Configurator	RL78 Smart Configurator V1.14.0 from Renesas Electronics Corp.
Development support tool for the capacitive touch sensor	QE for Capacitive Touch V4.2.0
Board support package (BSP)	V1.91 Smart Configurator.
TOUCH Driver	V2.20 from Renesas Electronics Corp.
CTSU Driver	V2.20 from Renesas Electronics Corp.
Board used	RL78/L23 Fast Prototyping Board (RTK7RLL230S00001BJ)
LCD module	Varitronix VIM-878-DP-FC-S-LV 16 segments x 8 digits Header: 36-pin (18 x 2 rows) x 1 Operating voltage condition: 3V to 4.6V (When using the module with operating voltage other than 3.3V, remove the LCD panel.)

3. Peripheral Function

This chapter describes the LCD controller/driver.

For more information on the operation, refer to section 22 LCD Controller/Driver in RL78/L23 User's Manual: Hardware (R01UH1082).

3.1 Basic Features of RL78/L23 LCD Controller/Driver

RL78/L23 LCD controller/driver includes the following features:

- Waveform A or B selectable
- LCD driver voltage generator can be switched between internal voltage boosting, capacitor split, or external resistance division
- Segment and common signals can be output automatically by reading the LCD display data register automatically Reference voltage generated when the voltage boost circuit is operating can be selected from 23 levels (contrast adjustment)
- LCD blinking is available

3.2 LCD Controller/Driver Display Mode

LCD controller/driver display modes are combinations of the LCD drive waveform and LCD voltage generator. Table 3-1, Table 3-2 and Table 3-3 list the maximum number of pixels in each display mode.

Table 3-1 Maximum Number of Pixels for an 100-pin Package(waveform A)(1/2)

Drive Waveform for LCD Driver	LCD Driver Voltage Generator		Bias Mode	Number of Time Slices	Maximum Number of Pixels	
waveform A	External resistance division		-	Static	56 (56 segment signals × 1 common signals)	
			1/2	2	112 (56 segment signals × 2 common signals)	
				3	168 (56 segment signals × 3 common signals)	
			1/3	3	224 (56 segment signals × 4 common signals)	
				4	324 (54 segment signals × 6 common signals)	
				6	416 (52 segment signals × 8 common signals)	
				8	416 (52 segment signals × 8 common signals)	
			1/4	8	416 (52 segment signals × 8 common signals)	
	Internal voltage Boosting		VL1 Reference	1/3	3	168 (56 segment signals × 3 common signals)
				4	224 (56 segment signals × 4 common signals)	
				6	324 (54 segment signals × 6 common signals)	
				8	416 (52 segment signals × 8 common signals)	
				1/4	6	324 (54 segment signals × 6 common signals)
					8	416 (52 segment signals × 8 common signals)
			VL2 Reference	1/3	3	168 (56 segment signals × 3 common signals)
					4	224 (56 segment signals × 4 common signals)
				1/4	6	324 (54 segment signals × 6 common signals)
					8	416 (52 segment signals × 8 common signals)
					6	324 (54 segment signals × 6 common signals)
					8	416 (52 segment signals × 8 common signals)

Table 3-2 Maximum Number of Pixels for an 100-pin Package(waveform A)(2/2)

Drive Waveform for LCD Driver	LCD Driver Voltage Generator		Bias Mode	Number of Time Slices	Maximum Number of Pixels		
waveform A	Capacitor split	V_{DD} Reference	1/3	3	168 (56 segment signals × 3 common signals)		
				4	224 (56 segment signals × 4 common signals)		
				6	324 (54 segment signals × 6 common signals)		
				8	416 (52 segment signals × 8 common signals)		
			1/4	6	324 (54 segment signals × 6 common signals)		
				8	416 (52 segment signals × 8 common signals)		
				V_{L4} Reference	1/3	3	168 (56 segment signals × 3 common signals)
						4	224 (56 segment signals × 4 common signals)
	6	324 (54 segment signals × 6 common signals)					
	8	416 (52 segment signals × 8 common signals)					

3.3 LCD Drive Voltage Generator

The RL78/L23 LCD controller/driver can use external resistance division, internal voltage boosting, or capacitor split to generate LCD drive voltage. This chapter covers the features of each method.

Table 3-3 LCD Drive Method and Its Application

LCD Drive Method	Feature/Usage			Application
	Drive capacity	Operating current	Drive voltage	
External resistance division	High	Standard	V_{DD} - dependent	<p><u>Suitable for large format LCDs or AC power supply sets</u></p> <p>The LCD drive capacity is high and the drive voltage is generated by a resistor divider, which contributes to cost reduction. This method generates the LVD drive voltage by an external resistor divider. As the voltage is applied externally, the operating current and drive capacity can be adjusted by an external resistor.</p>
	Supports large LCDs			
Internal voltage boosting	Standard	Small	Constant	<p><u>Suitable for battery sets</u></p> <p>The operating current is small and the LCD display does not become dim as the drive voltage is constant even when the battery voltage is reduced. This method generates the reference voltage internally and boosts it by an external capacitor. As the reference voltage is adjusted by software, the LCD contrast can be adjusted from 23 levels in RL78/L23.</p>
			As the drive voltage is constant, the LCD display does not change with the battery voltage decreased	
Capacitor split	Standard	Much Smaller	Depends on V_{DD} when the reference voltage is V_{DD}	<p><u>Suitable for battery sets</u></p> <p>This method has the smallest operating current among three LCD drive modes, and thus the LCD display becomes dim with decreasing the supply voltage. Use this method to allow the screen to be dim according to the battery level. If you do not want the screen to be dim when the battery voltage is decreased, change the LCD drive method to internal voltage boosting. It works in an external circuit of the capacitor split method.</p>
			LCD display becomes dim with the supply voltage decreased	

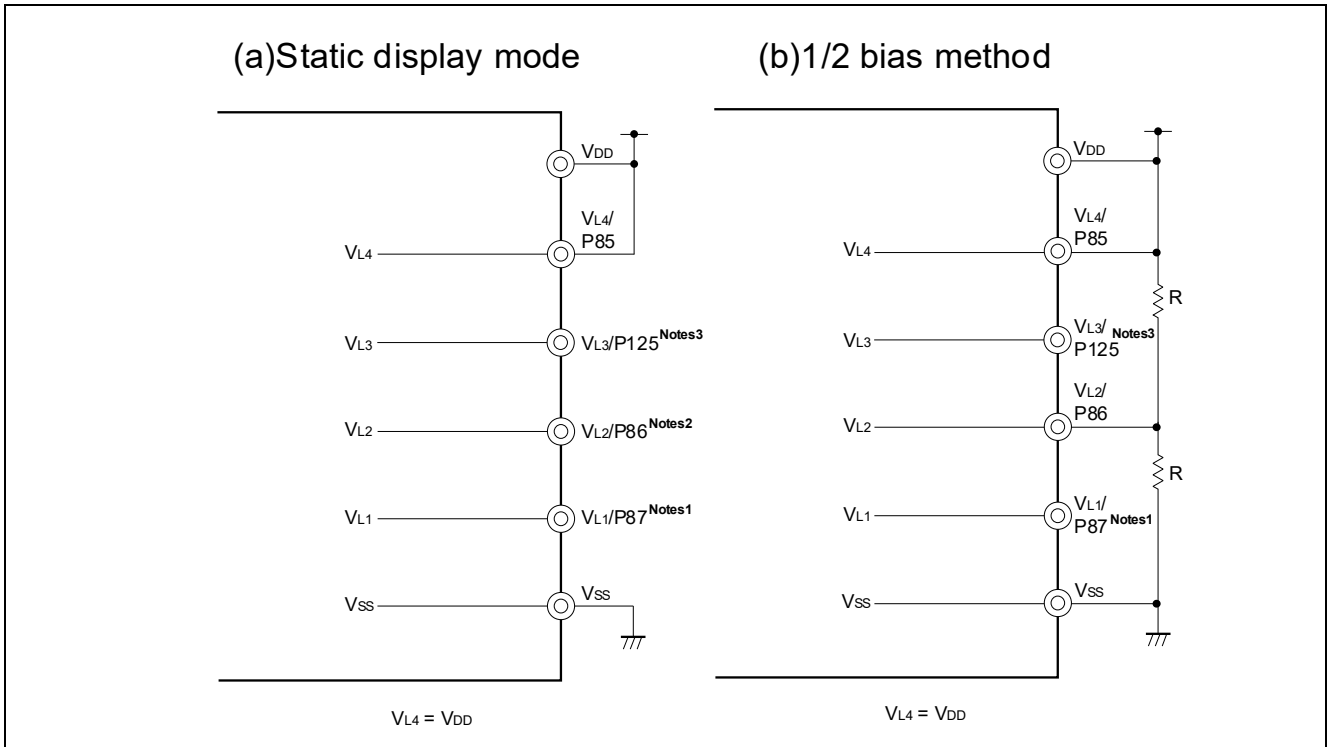
3.3.1 External Resistance Division Method

This is suitable for large format LCDs or AC power sets. As it has a large drive capacity and generates the drive voltage by a resistor divider, which contributes to cost reduction.

To be more specific, this method generates an LCD drive voltage using an external resistor divider. As the voltage is applied externally, the operating current or the drive capacity can be adjusted by the external resistor.

Figure 3.1 and Figure 3.2 show connection examples of external resistance division methods.

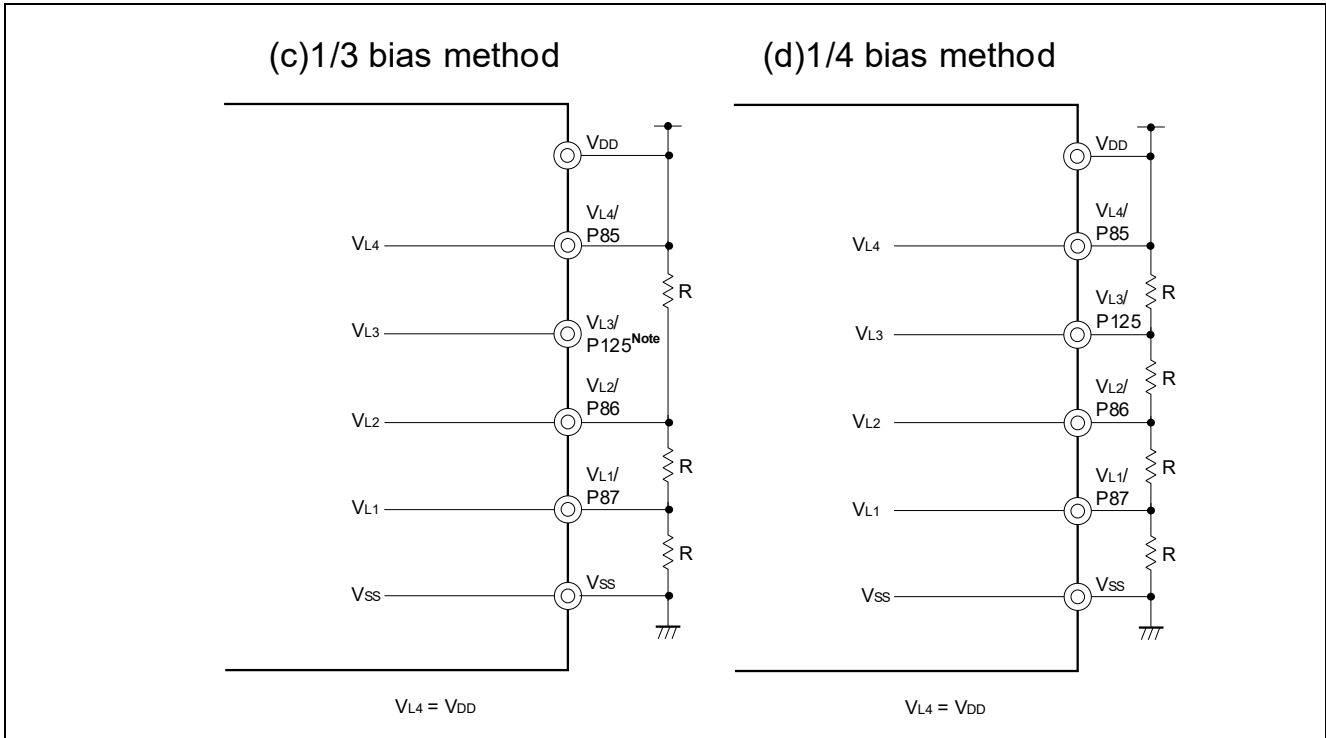
Figure 3.1 Connection Example of External Resistance Division Method (1/2)



Notes for Figure 3.1 (a) and (b).

- Notes 1. VL1 can be used as a port(P87).
- Notes 2. VL2 can be used as a port(P86).
- Notes 3. VL3 can be used as a port(P125).

Figure 3.2 Connection Example of External Resistance Division Method (2/2)



Note. VL3 can be used as a port(P125).

- Notes 1. CAPL can be used as port-pin P126 and CAPH can be used as port-pin P127.
- Notes 2. The reference resistance “R” value for external resistance division is 10 kΩ to 1 MΩ. In addition, to stabilize the potential of the VL1 to VL4 pins, connect a capacitor between each of pins VL1 to VL4 and the GND pin as needed. The reference capacitance is about 0.47 μF but it depends on the LCD panel used, the number of segment pins, the number of common pins, the frame frequency, and the operating environment. Thoroughly evaluate these values in accordance with your system and adjust and determine the capacitance.

3.3.2 Internal Voltage Boosting Method

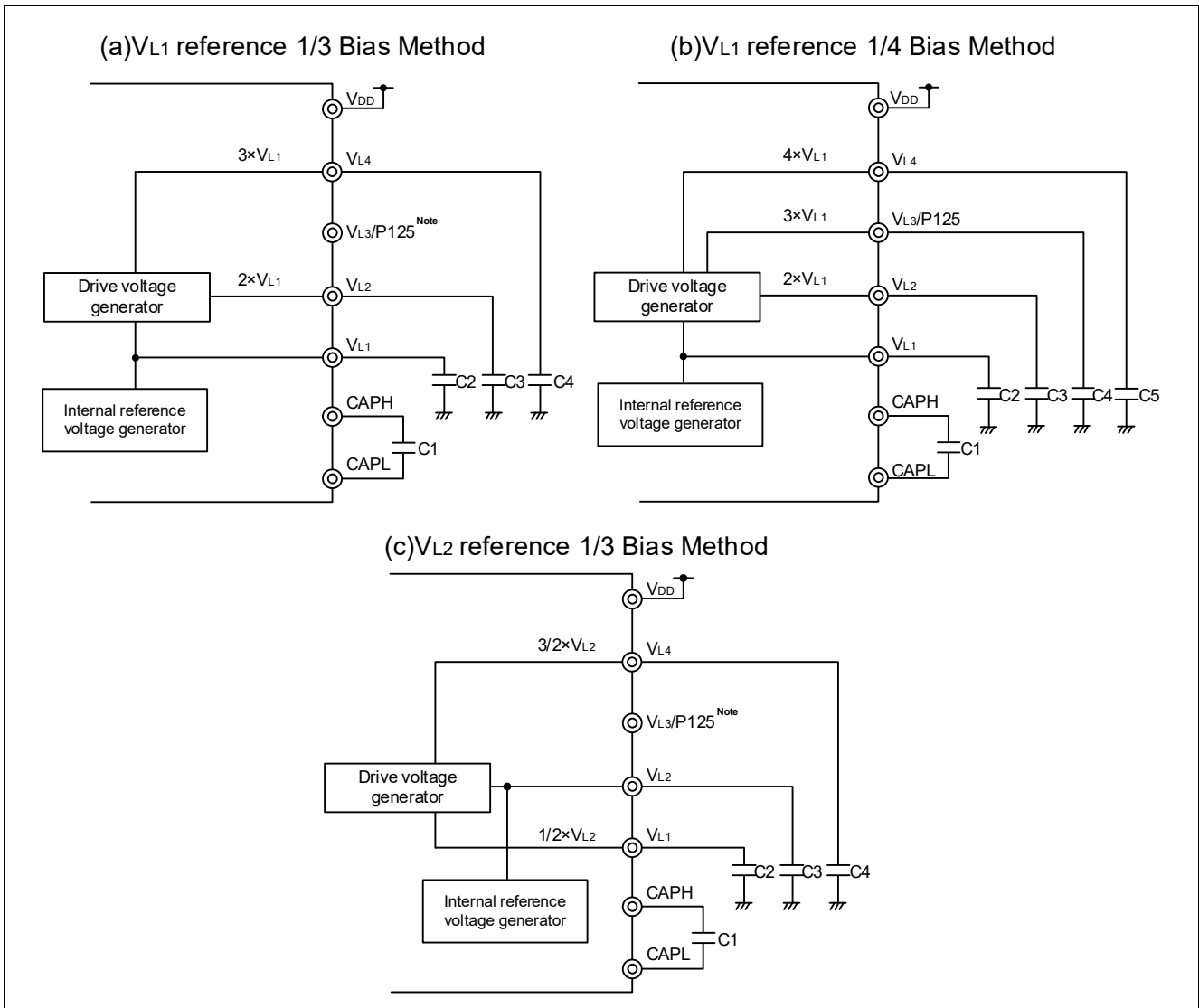
This is suitable for a battery set.

The operating current is small, and the LCD display does not become dim as the drive voltage is constant even when the battery voltage is reduced.

This method generates the reference voltage internally and boosts it by an external capacitor. As the reference voltage is adjusted by software (the LCD boost level control register, VLCD), the LCD contrast can be adjusted from 23 levels in RL78/L23.

Figure 3.3 shows a connection example of an internal voltage boosting method.

Figure 3.3 Connection Example of Internal Voltage Boosting Method



Note: V_{L3} can be used as a port(P125)

Remark: Use a capacitor with as little leakage as possible. Make sure to use a non-polar capacitor for C1.

3.3.3 Capacitor Split Method

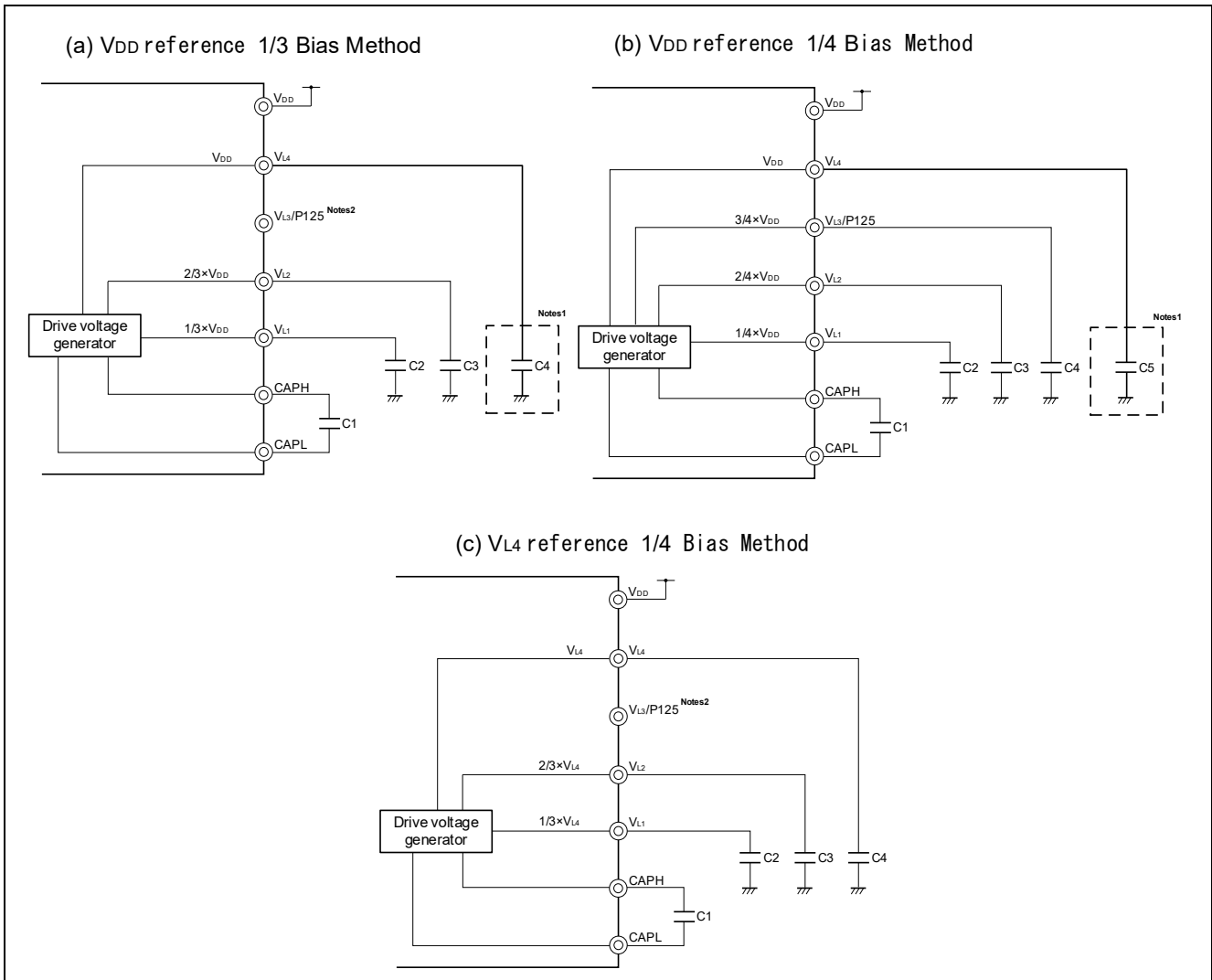
This is also suitable for a battery set.

This method has the smallest operating current among three LCD drive modes, and thus the LCD display becomes dim with the supply voltage decreased.

If you do not want the screen to be dim when the battery voltage is decreased, change the LCD drive method to internal voltage boosting method. The method works in an external circuit of the capacitor split method.

Figure 3.4 shows a connection example of capacitor split method.

Figure 3.4 Connection Example of Capacitor Split Method



Notes 1. As the V_{L4} pin is internally connected to the V_{DD} pin, the capacitor is not always essential.

Note, however, that selection of the internal voltage boosting method requires connection of this capacitor. In addition, when only capacitor split method is in use, the capacitor can be connected as a means for stabilizing the voltage supplied to the LCD.

Notes 2. V_{L3} can be used as port-pin P125

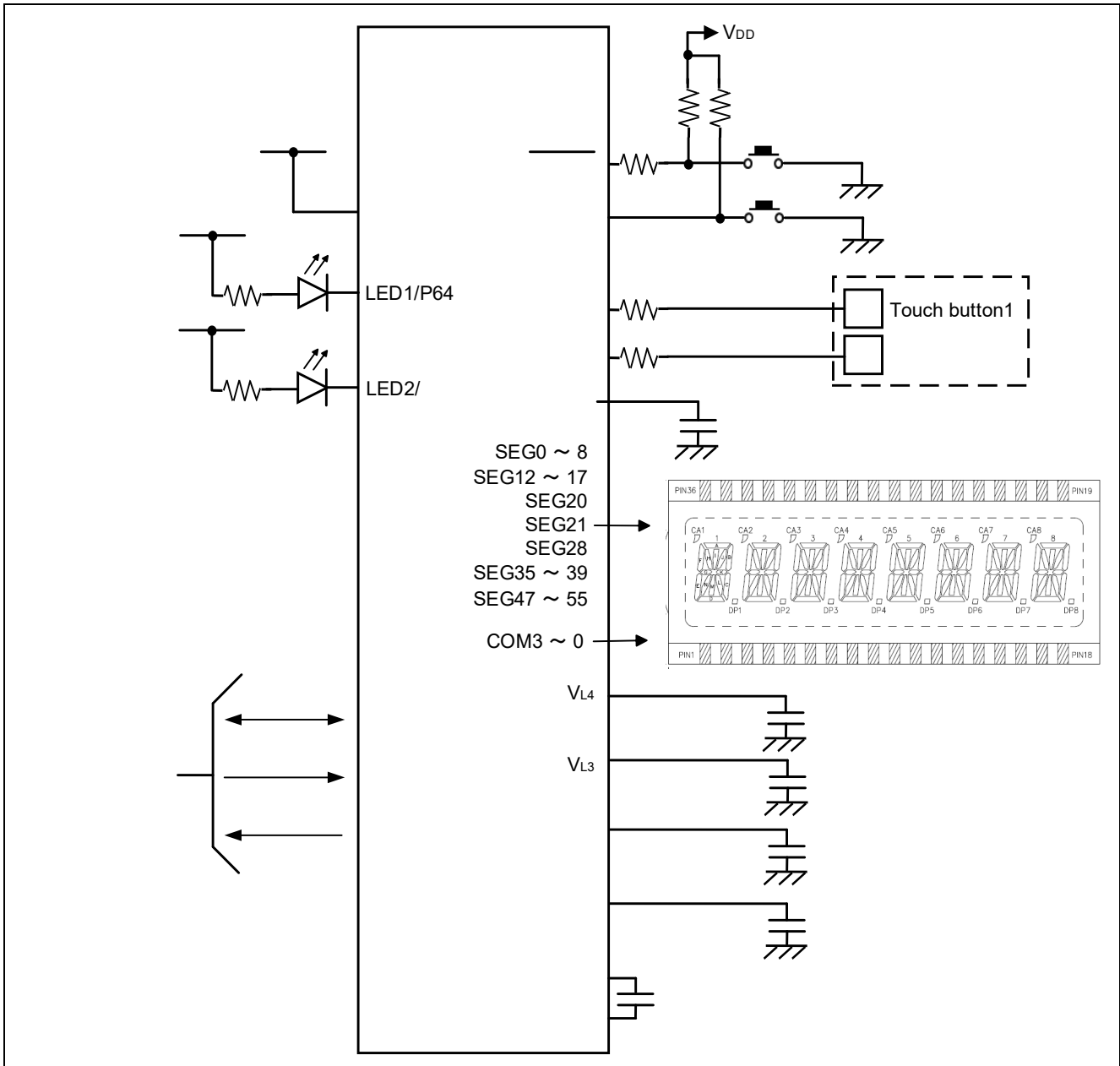
Remark: Use a capacitor with as little leakage as possible. Make sure to use a non-polar capacitor for C1.

4. Hardware

4.1 Hardware Example

Figure 4.1 shows the hardware configuration used in this application note.

Figure 4.1 Hardware Configuration



Notes 1. The above figure is simplified to show an overview of the hardware connection. When designing application circuits, make sure to handle unused pins appropriately to satisfy the electrical characteristics (connect input only ports independently to either V_{DD} or V_{SS} via resistors).

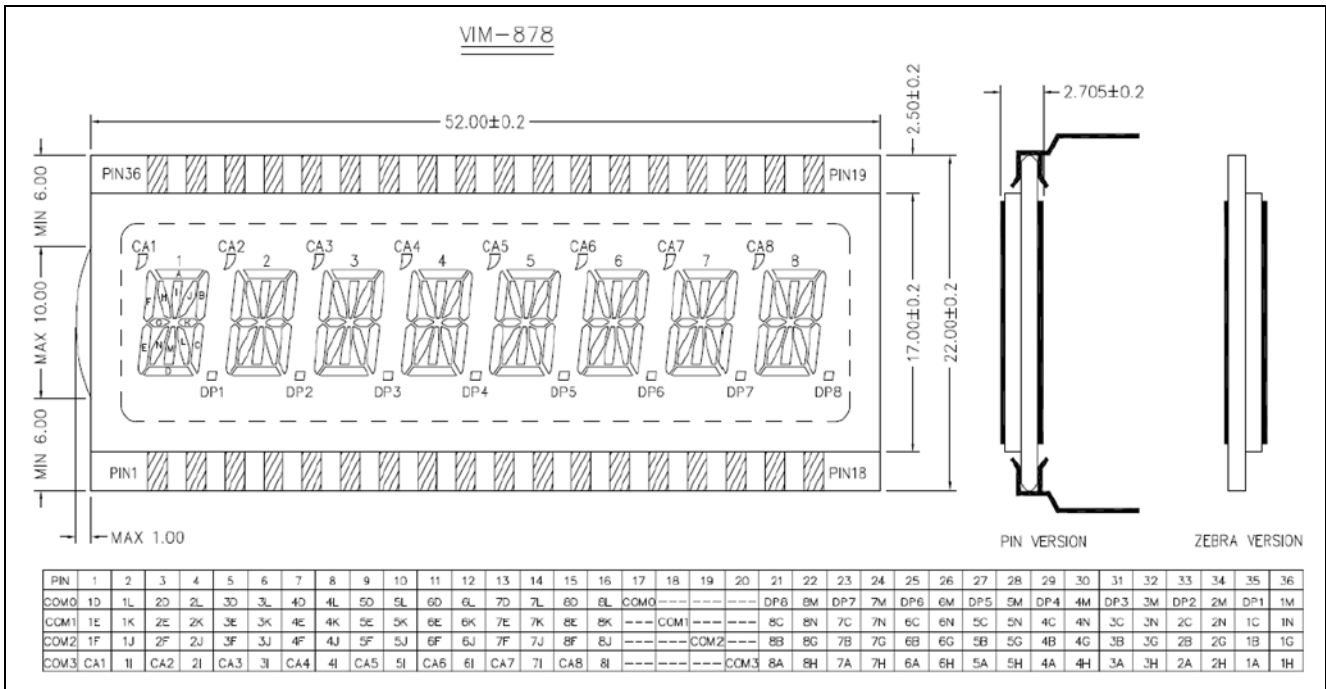
Notes 2. Make sure to set V_{DD} greater than the detection voltage (V_{LVD}) specified by the LVD.

4.2 LCD module

This section describes the LCD module used in the sample code accompanying this application note.

The RL78/L23 Fast Prototyping Board is equipped with the LCD panel (16 segments, 8 digits) with the sockets. Figure 4.2 shows the panel image and the pin allocation table. Table 4-1 and Table 4-2 show the connections between the LCD panel and RL78/L23.

Figure 4.2 LCD Panel and Pin Allocation Table



(Source : [Datasheet for VIM-878-DP-FC-S-LV Varitronix Optoelectronics | Octopart](#))

Table 4-1 J5 Socket and LCD Module Connection Table

J5 socket pin number	LCD panel pin number	Symbol	port	Symbol and port	Pin number	LCD Header
1	LCD_1	SEG8	P54	P54(SEG8)	54	J1_21
2	LCD_2	SEG7	P53	P53(SEG7)	55	J1_22
3	LCD_3	SEG6	P52	P52(SEG6)	56	J1_23
4	LCD_4	SEG5	P51	P51(SEG5)	57	J1_24
5	LCD_5	SEG4	P50	P50(SEG4)	58	J1_25
6	LCD_6	SEG3	P97	P97(SEG3)	59	J1_26
7	LCD_7	SEG2	P96	P96(SEG2)	60	J1_27
8	LCD_8	SEG1	P95	P95(SEG1)	61	J1_28
9	LCD_9	SEG0	P94	P94(SEG0)	62	J1_29
10	LCD_10	SEG50	P07	P07(SEG50)	69	J1_34
11	LCD_11	SEG49	P06	P06(SEG49)	70	J1_35
12	LCD_12	SEG48	P05	P05(SEG48)	71	J1_36
13	LCD_13	SEG47	P04	P04(SEG47)	72	J1_37
14	LCD_14	SEG39	P14	P14(SEG39)	83	J1_45
15	LCD_15	SEG38	P13	P13(SEG38)	84	J1_46
16	LCD_16	SEG37	P12	P12(SEG37)	85	J1_47
17	LCD_17	COM0	P90	P90(COM0)	66	J1_33
18	LCD_18	COM1	P91	P91(COM1)	65	J1_32

Table 4-2 J6 Socket and LCD Module Connection Table

J6 socket pin number	LCD panel pin number	Symbol	port	Symbol and port	Pin number	LCD Header
1	LCD_19	COM2	P92	P92(COM2)	64	J1_31
2	LCD_20	COM3	P93	P93(COM3)	63	J1_30
3	LCD_21	SEG36	P11	P11(SEG36)	86	J1_48
4	LCD_22	SEG35	P10	P10(SEG35)	87	J1_49
5	LCD_23	SEG55	P145	P145(SEG55)	88	J1_50
6	LCD_24	SEG54	P144	P144(SEG54)	89	J1_51
7	LCD_25	SEG53	P143	P143(SEG53)	94	J1_56
8	LCD_26	SEG52	P142	P142(SEG52)	95	J1_57
9	LCD_27	SEG51	P141	P141(SEG51)	96	J1_58
10	LCD_28	SEG28	P130	P130(SEG28)	2	J1_1
11	LCD_29	SEG21	P31	P31(SEG21)	39	J1_8
12	LCD_30	SEG20	P30	P30(SEG20)	40	J1_9
13	LCD_31	SEG17	P75	P75(SEG17)	43	J1_12
14	LCD_32	SEG16	P74	P74(SEG16)	44	J1_13
15	LCD_33	SEG15	P73	P73(SEG15)	45	J1_14
16	LCD_34	SEG14	P72	P72(SEG14)	46	J1_15
17	LCD_35	SEG13	P71	P71(SEG13)	47	J1_16
18	LCD_36	SEG12	P70	P70(SEG12)	48	J1_17

Figure 4.3 shows an example of the 8-digit LCD panel display and the segments and their corresponding segment signals used to achieve the display.

Figure 4.3 Segments and Corresponding Signals

Example of displaying "1" on DISIT 7
 The following processing is implemented based on the pin assignments indicated in Tables 4.1 and 4.2.

Segment signal SEG55 is connected to PIN23 of the LCD module.
 From the pin assignment table:
 PIN23 7C is connected to the COM1 signal
 PIN24 7B is connected to the COM2 signal

When 06H is set in the SEG55 register, 7C and 7B will turn on and DISIT 7 will display "1".

PIN	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	2
COM0	1D	1L	2D	2L	3D	3L	4D	4L	5D	5L	6D	6L	7D	7L	8D	8L	COM0	---	---	---	DP8	8M	DP7	7M	DP6	6
COM1	1E	1K	2E	2K	3E	3K	4E	4K	5E	5K	6E	6K	7E	7K	8E	8K	---	COM1	---	---	8C	8N	7C	7N	6C	6
COM2	1F	1J	2F	2J	3F	3J	4F	4J	5F	5J	6F	6J	7F	7J	8F	8J	---	---	COM2	---	8B	8G	7B	7G	6B	6
COM3	CA1	1I	CA2	2I	CA3	3I	CA4	4I	CA5	5I	CA6	6I	CA7	7I	CA8	8I	---	---	---	COM3	8A	8H	7A	7H	6A	6

(Additional info: [VIM-878.pdf](#))

Table 4-3 Segments and Corresponding Commons (DISIT 7)

LCD Module PIN No. <small>Note</small>	LCD Display Data Register <small>Note</small>	COM3	COM2	COM1	COM0
		bit3	bit2	bit1	bit0
PIN23	SEG55	A	B	C	DP
PIN13	SEG47	CA	F	E	D
PIN14	SEG39	I	J	K	L
PIN24	SEG54	H	G	N	M

Note: For other DISITs, replace with the corresponding PIN number and segment signal register name.

4.3 Capacitive Touch Sensing Unit

This section describes the capacitive touch sensing unit used in this sample code.

RL78/L23 Fast Prototyping Board is equipped with two electrodes: touch buttons 1 and 2.

The touch buttons can be enabled by using the CTSU module, the TOUCH module, and QE for Capacitive Touch (development support tool for the capacitive touch sensor). For details on how to use the touch buttons, refer to Capacitive Sensor Microcontrollers CTSU Capacitive Touch Introduction Guide (R30AN0424).

4.4 Renesas Flash Driver

This section describes the Renesas Flash Driver (RFD) used in this sample code.

Renesas Flash Driver RL78 Type11 is software that uses firmware embedded in the RL78 microcontroller to rewrite the data in the flash memory.

The sample code for BANK1 implements the bank swap function and writes to the data flash. The sample code for BANK2 implements the bank swap function.

For details on Renesas Flash Driver RL78 Type11, refer to Renesas Flash Driver RL78 Type11 User's Manual (R20UT5539).

4.5 Pins Used

Table 4-4 Pins Used and Their Functions (1/2)

Pin name	I/O	Function
P137/INTP0	Input	Detects input from the user switch and enters hour, minute or second setting mode
P57/TSCAP	-	Secondary power supply capacitor connection pin for measurement
P56/TS17	Input-Output	Detects input from the touch button 1 and increments hours, minutes and seconds displayed on the LCD
P55/TS18	Input-Output	Detects input from the touch button 2 and decrements hours, minutes and seconds displayed on the LCD
P94/SEG0	Output	LCD controller/driver common signals
P95/SEG1		
P96/SEG2		
P97/SEG3		
P50/SEG4		
P51/SEG5		
P52/SEG6		
P53/SEG7		
P54/SEG8		
P70/SEG12		
P71/SEG13		
P72/SEG14		
P73/SEG15		
P74/SEG16		
P75/SEG17		
P30/SEG20		
P31/SEG21		
P130/SEG28		
P10/SEG35		
P11/SEG36		
P12/SEG37		
P13/SEG38		
P14/SEG39		
P04/SEG47		
P05/SEG48		
P06/SEG49		
P07/SEG50		
P141/SEG51		
P142/SEG52		
P143/SEG53		
P144/SEG54		
P145/SEG55		

Table 4-5 Pins Used and Their Functions (2/2)

Pin name	I/O	Function
P90/COM0	Output	LCD controller/driver common signals
P91/COM1		
P92/COM2		
P93/COM3		
P87/V _{L1}	-	LCD drive voltage
P86/V _{L2}		
P85/V _{L4}		
P126/CAPL	-	Capacitor connection for LCD controller/driver
P127/CAPH		
P40/TOOL0	Input-Output	COM Port debugging
P17/TOOLRxD	Input	COM Port debugging
P00/TOOLTxD	Output	COM Port debugging

The following connections of unused pins are applied to P123 and P124 for BANK2.
 The CSC register is set by the `qe_touch_main` function in `qe_touch_sample.c`. The CMC register is set by the `mcu_clock_setup` function in `mcu_clocks.c` as shown in Figure 4.4.

Figure 4.4 Editing the mcu_clocks.c File

```

844
845
846
847
848
849
850
851
    /* Clock operation mode control register(CMC) setting */
    cmc_tmp &= 0xDF; /* Connection of unused pins for P123 and P124 */
    cmc_tmp |= 0x10; /* Connection of unused pins for P123 and P124 */
    CMC = cmc_tmp;
    
```

Caution If you change the version of the "r_bsp" component in the Smart Configurator, `mcu_clocks.c` will be overwritten and any code added by the user will be erased. Therefore, whenever you change the version of the "r_bsp" component, you will need to add the code for the above settings.

5. BANK1 Software

5.1 Operation Overview

The sample code uses the LCD controller/driver to display the 24-hour clock. The time measured by RTC is stored in the LCD display data memory area, and the time is changed every time an RTC periodic interrupt occurs (1 second).

In addition, pressing the user switch (short press) allows you to cycle through the time units in order of second, minute, hour, and back to second; pressing the touch button adjusts the time and displays the set time. When adjusting the seconds, minutes, or hours, the LCD display blinks the corresponding digits.

The clock frequency, I/O ports, RTC, and LCD controller/driver are configured in the initial settings.

After the initial settings are complete, the sample code displays "RL78/L23" and "BANK1 C" on the LCD consecutively and transitions to the wait state. The wait state is released by a short press on the user switch (both edges of INTPO detected) and the time is displayed. When the RTC periodic interrupt occurs, the time display changes every second. You can set any time to be displayed by pressing the user switch.

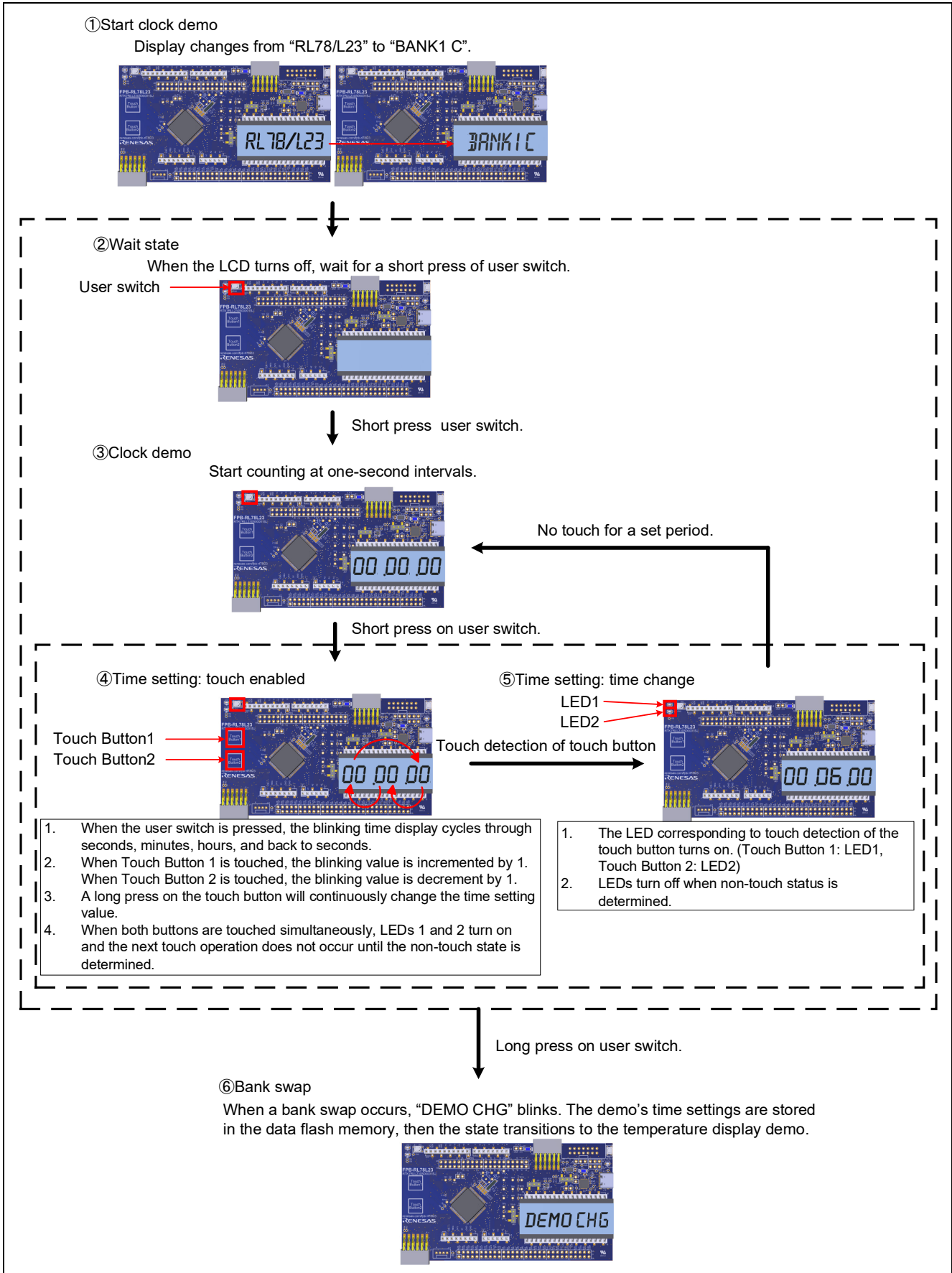
The touch buttons are disabled in the time display state, and available only in second, minute, and hour adjustment states. The measurement cycle is 20ms.

The first, second, and third presses on the user switch allow you to adjust the seconds, minutes, and hours, respectively. The fourth press returns to the position for seconds in a cyclical manner. If the user switch is not pressed and no touch detection of the touch buttons occurs within a certain time, the sample code returns to the time display state to display the set time. In the time adjustment state, touch detection of touch button 1 increases the value by 1 second, 1 minute, or 1 hour according to the selected time unit. Touch detection of touch button 2 decreases the value by 1 second, 1 minute, or 1 hour. The adjusted value changes continuously when touch detection of a touch button is held.

A long press on the user switch displays "DEMO CHG" on the LCD and executes the bank swap function. Before switching the banks, the current displayed time data is stored in the data flash. The stored time data is displayed the next time the banks are switched.

Refer to the state transition diagram in Figure 5.1 for more details.

Figure 5.1 State Transition Diagram



5.2 File Composition

Table 5-1 and Table 5-2 list the files used in the BANK1 sample code. Files generated by the integrated development environment are not included in this table.

Table 5-1 Files Used in the Sample Code(1/2)

Folder and file name	Description	Smart Configurator Usage
¥bank1_clock<DIR>	Sample code folder	
¥src<DIR>	Source folder	
¥bank1_clock.c	BANK1 source folder	
¥clock.c	Clock source file	
¥clock.h	Clock header file	
¥lcd_segdata.c	LCD display source file	
¥include<DIR>	RFD include folder	
¥sample<DIR>	RFD sample folder	
¥source<DIR>	RFD source folder	
¥userown<DIR>	RFD user processing folder	
¥smc_gen<DIR>	Smart configurator generation components storage folder	✓
¥Config_INTC<DIR>	External interrupt components folder	✓
¥Config_LCD<DIR>	LCD components folder	✓
¥Config_PORT<DIR>	PORT components folder	✓
¥Config_RTC<DIR>	RTC components folder	✓
¥Config_TAU0_1<DIR>	TAU0_1 components folder	✓
¥Config_TAU0_3<DIR>	TAU0_3 components folder	✓
¥Config_TAU0_4<DIR>	TAU0_4 components folder	✓
¥Config_TAU0_5<DIR>	TAU0_5 components folder	✓
¥r_ctsu<DIR>	CTSU driver folder	✓
¥rm_touch<DIR>	TOUCH driver folder	✓

Table 5-2 Files Used in the Sample Code(2/2)

Folder and file name	Description	Smart Configurator Usage
¥bank1_clock<DIR>	Sample code folder	
¥qe_gen<DIR>	QE for Capacitive Touch generation file	
¥qe_touch_config.c	QE generation configuration source file	
¥qe_touch_config.h	QE generation configuration header file	
¥qe_touch_define.h	QE generation definition header file	
¥qe_touch_sample.c	Main function source file including touch operation	
¥QE_Touch<DIR>	QE configuration folder	

Precaution regarding Table 5-1 and Table 5-2.

Note: The sample code of the IAR version has a different configuration. Check the sample code of the IAR version for details. In addition, stores bank1_clock.ipcf. For details, refer to "RL78 Smart Configurator User's Guide: IAREW (R20AN0581)".

5.3 Smart Configurator Settings

Shows the smart configurator settings for BANK1.

Figure 5.2 shows the clock settings of the Smart Configurator.

Figure 5.2 Clock Settings

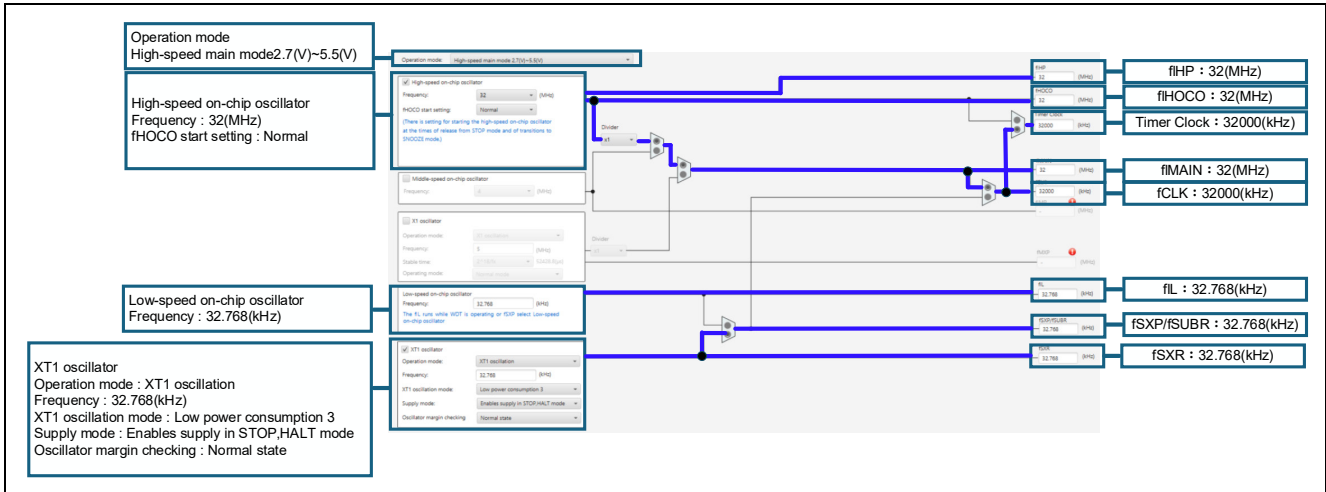


Figure 5.3 shows the system settings of the Smart Configurator.

Figure 5.3 System Settings

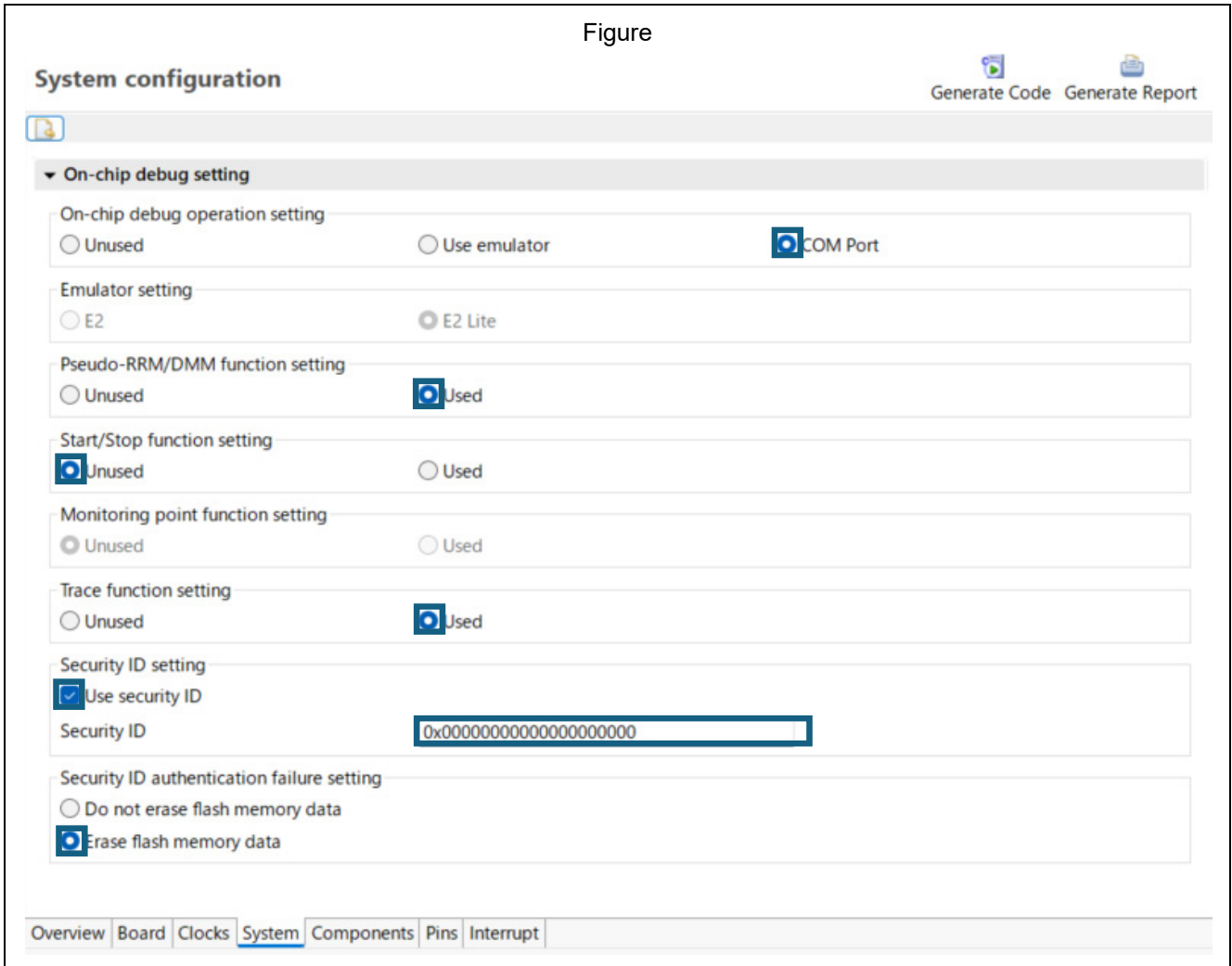


Figure .5.4 shows the LVD components (Config_LVD0) .

Figure .5.4 LVD Components (Config_LVD0) Settings

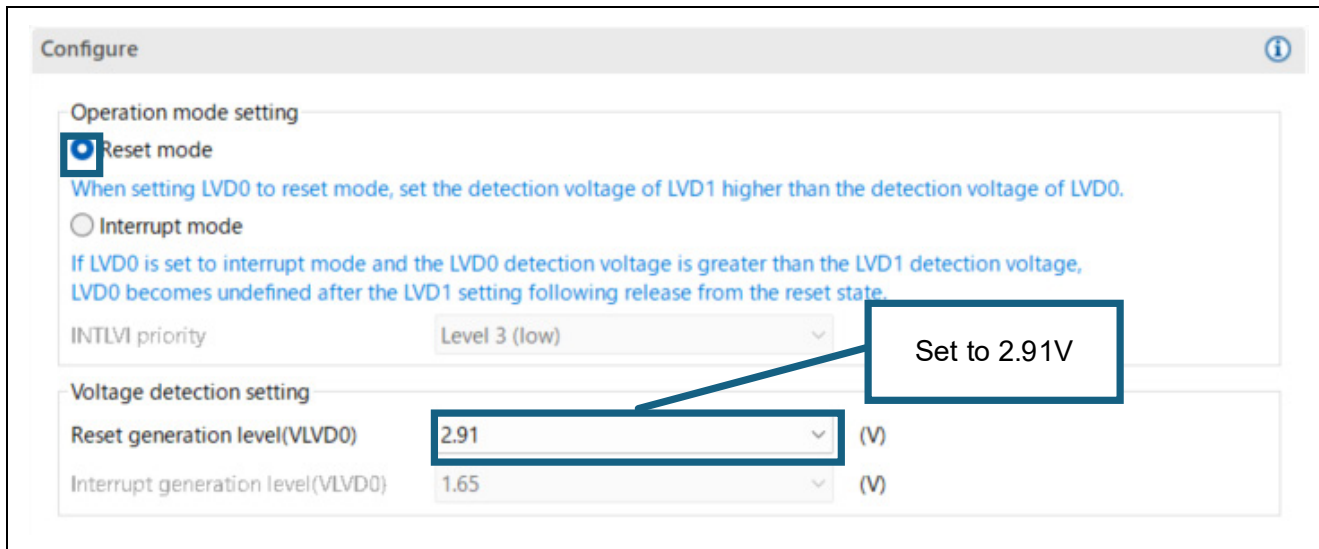


Figure 5.5 shows the settings of external interrupt components (Config_INTC).

Figure 5.5 external interrupt Components (Config_INTC) Settings

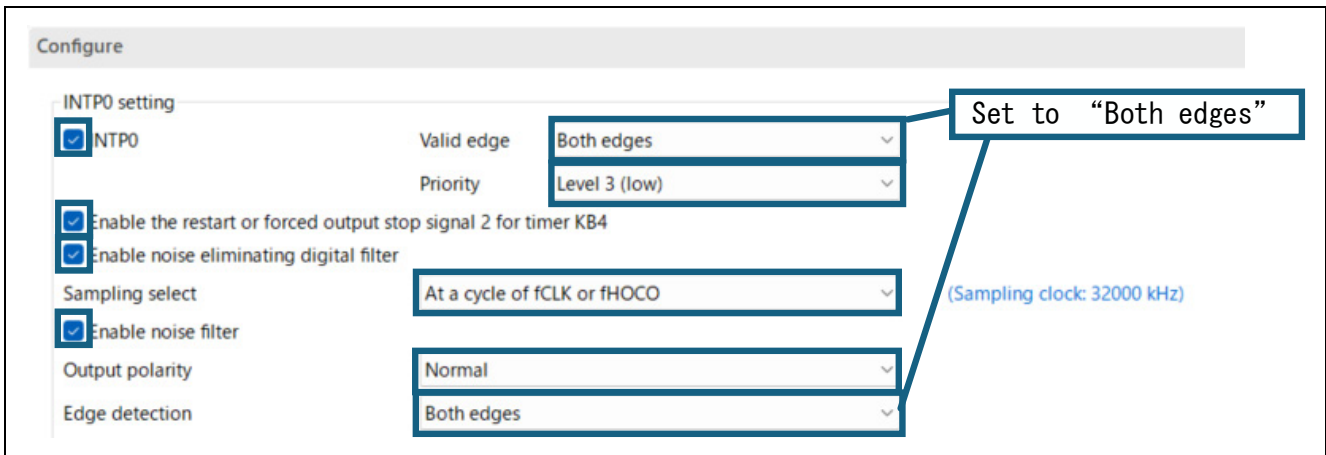


Figure 5.6 shows the settings of RTC components (Config_RTC).

Figure 5.6 RTC Components (Config_RTC)Settings

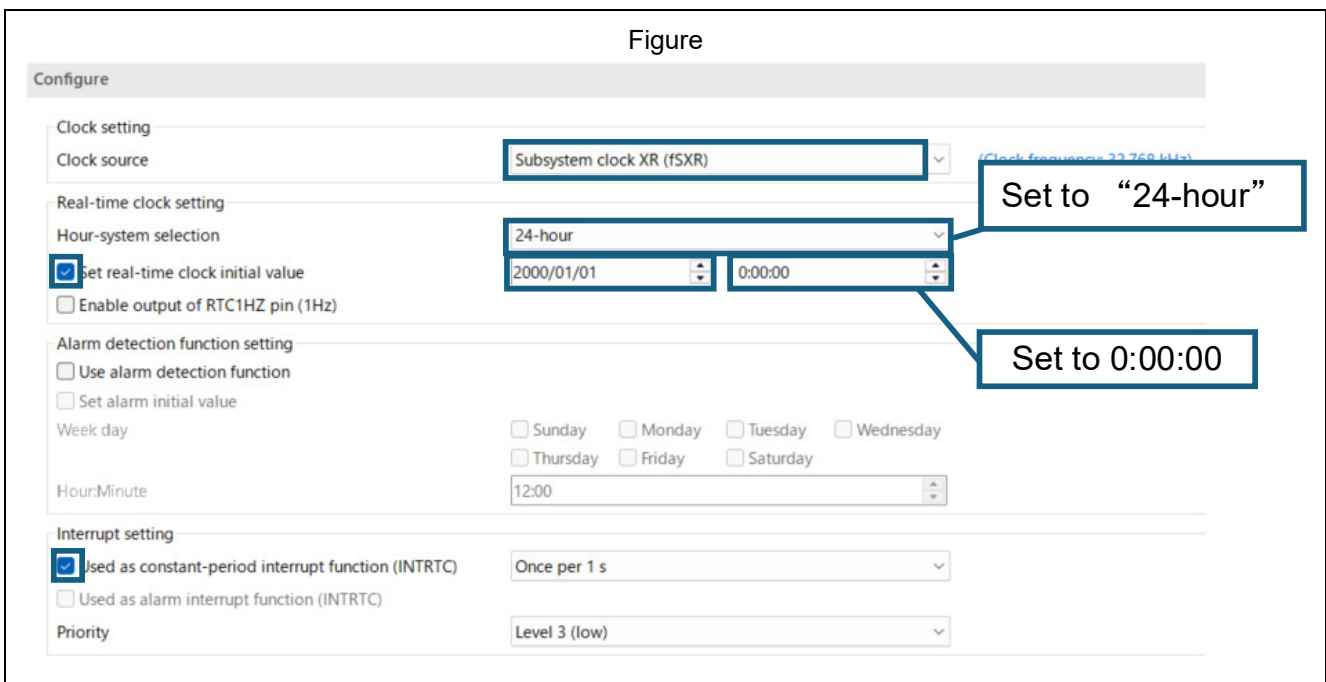


Figure 5.7 shows settings of TAU0_1 components (Config_TAU0_1).

Figure 5.7 TAU0_1 Components (Config_TAU0_1) Settings

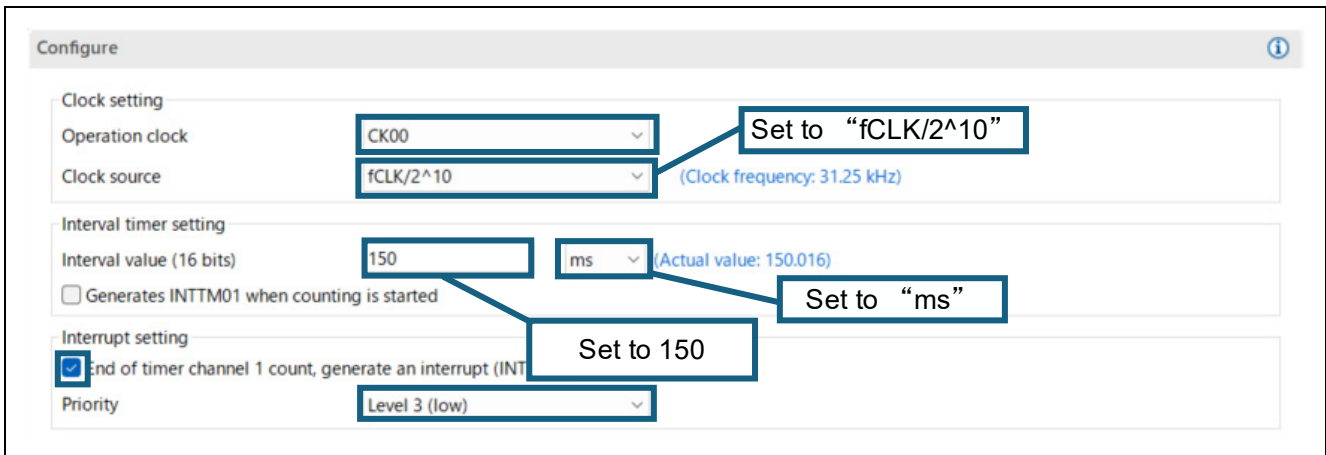


Figure 5.8 shows settings of TAU0_1 components (Config_TAU0_1).

Figure 5.8 TAU0_2 Components (Config_TAU0_2) Settings

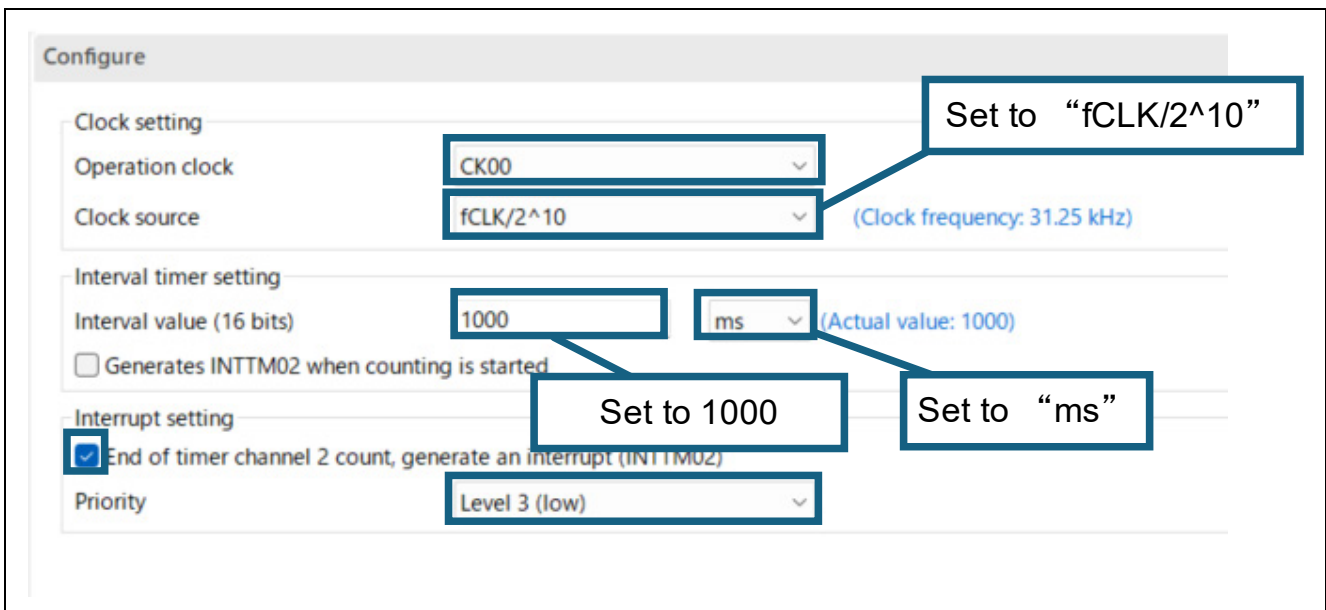


Figure 5.9 shows the settings of TAU0_3 components (Config_TAU0_3).

Figure 5.9 TAU0_3 Components (Config_TAU0_3) Settings

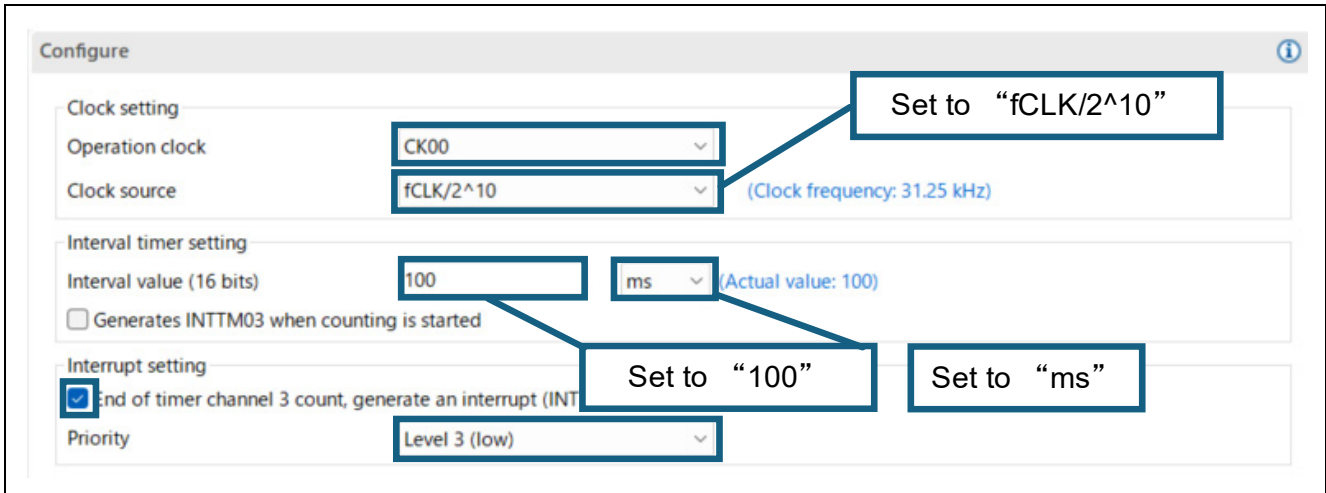


Figure 5.10 shows the settings of TAU0_4 components (Config_TAU0_4).

Figure 5.10 TAU0_4 Components (Config_TAU0_4)Setting

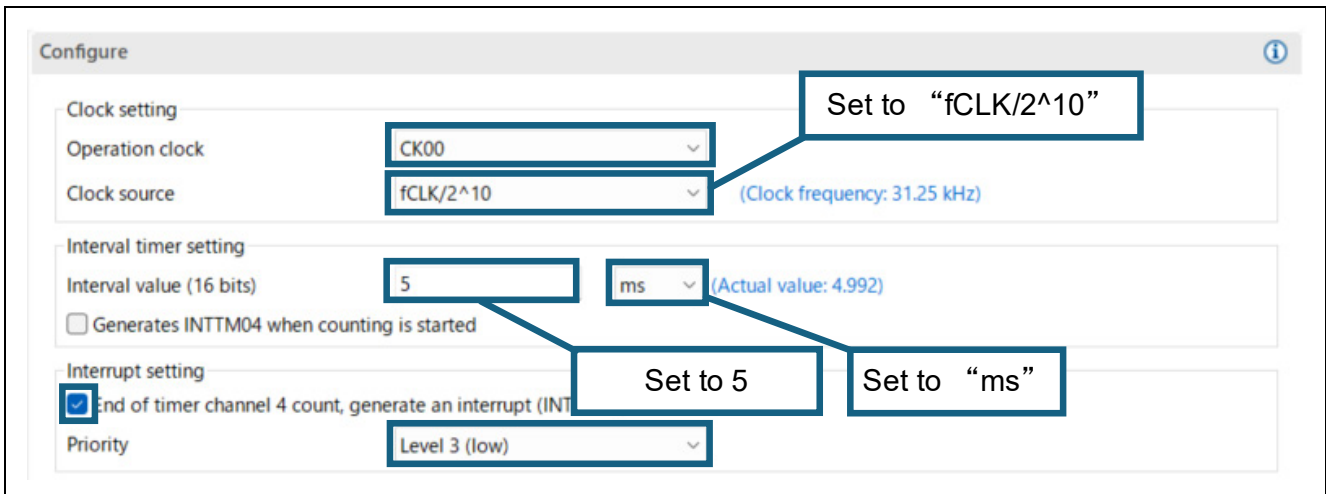


Figure 5.11 shows the settings of TAU0_5 components (Config_TAU0_5).

Figure 5.11 TAU0_5 Components Settings

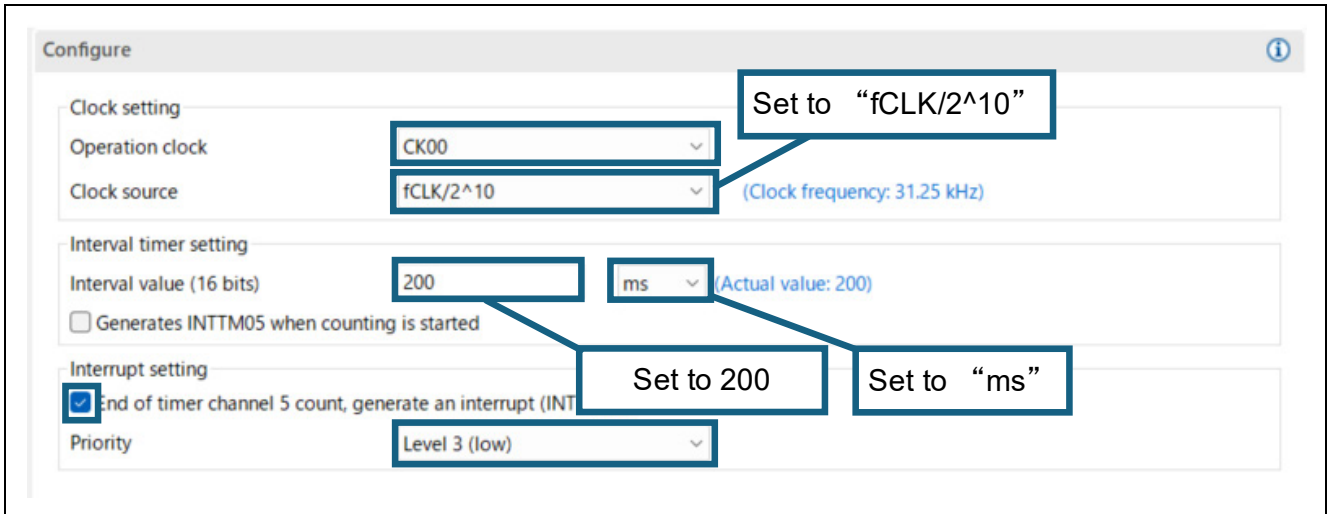


Figure 5.12 shows the settings of LCD components (Config_LCD).

Figure 5.12 LCD Components (Config_LCD) Setting

The screenshot displays the 'Configure' settings for LCD components. The settings are organized into several sections:

- Display waveform setting:** Type A waveform is selected.
- Drive voltage generator setting:** Driving voltage generator method is set to 'Capacitor split method for the VDD reference'.
- Display mode setting:** Number of time slices is set to '4 (1/3 bias mode)'.
- Display data area setting:** Display data area selection is set to 'A-pattern area data'.
- Control initial value of voltage boosting pin:** VDD >= 2.7 V is selected.
- Reference voltage setting:** VLCD voltage (VL1 Voltage) is 1.01 V, VLCD voltage (VL2 Voltage) is 2.02 V, and VLCD voltage (VL4 Voltage) is 3.03 V.
- Segment output pin setting:** A grid of checkboxes for segments SEG0/COM4 through SEG55. Most are checked, including SEG0/COM4, SEG1/COM5, SEG2/COM6, SEG3/COM7, SEG4, SEG5, SEG6, SEG7, SEG8, SEG12, SEG13, SEG14, SEG15, SEG16, SEG17, SEG20, SEG21, SEG28, SEG35, SEG36, SEG37, SEG38, SEG39, SEG45, SEG46, SEG47, SEG48, SEG49, SEG50, SEG51, SEG52, SEG53, SEG54, and SEG55.
- Clock setting:** Clock source is 'fSXR', Frequency divider is 'fSXR/2^7', and Frame frequency is '64.000 Hz'.

Callouts in the image highlight specific settings:

- 'Set to "Capacitor split method for the VDD reference"' points to the driving voltage generator method.
- 'Set to "fSXR"' points to the clock source.
- 'Set to "fSXR/2^7"' points to the frequency divider, with a note '(Clock frequency: 256 Hz)'.

Figure 5.13 and Figure 5.14 show the settings of PORT components (Config_PORT).

Figure 5.13 PORT Components (Config_PORT) Settings

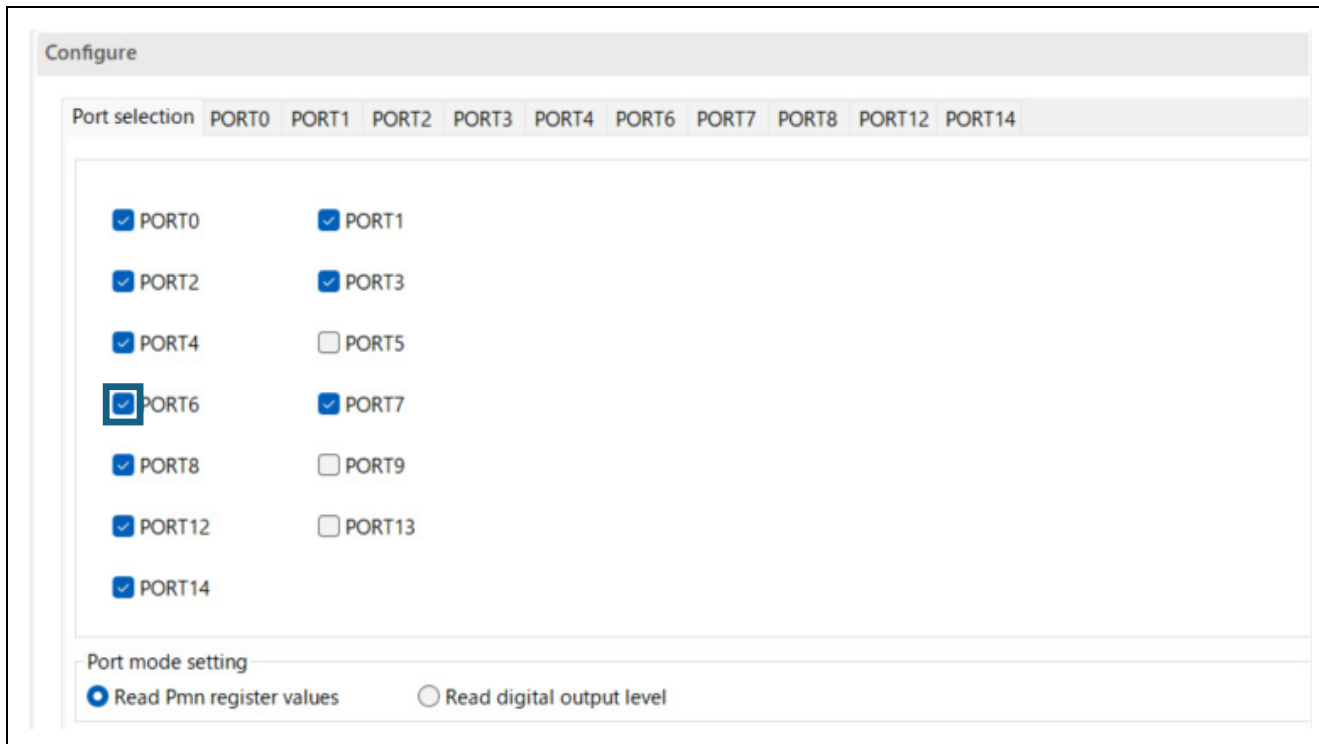
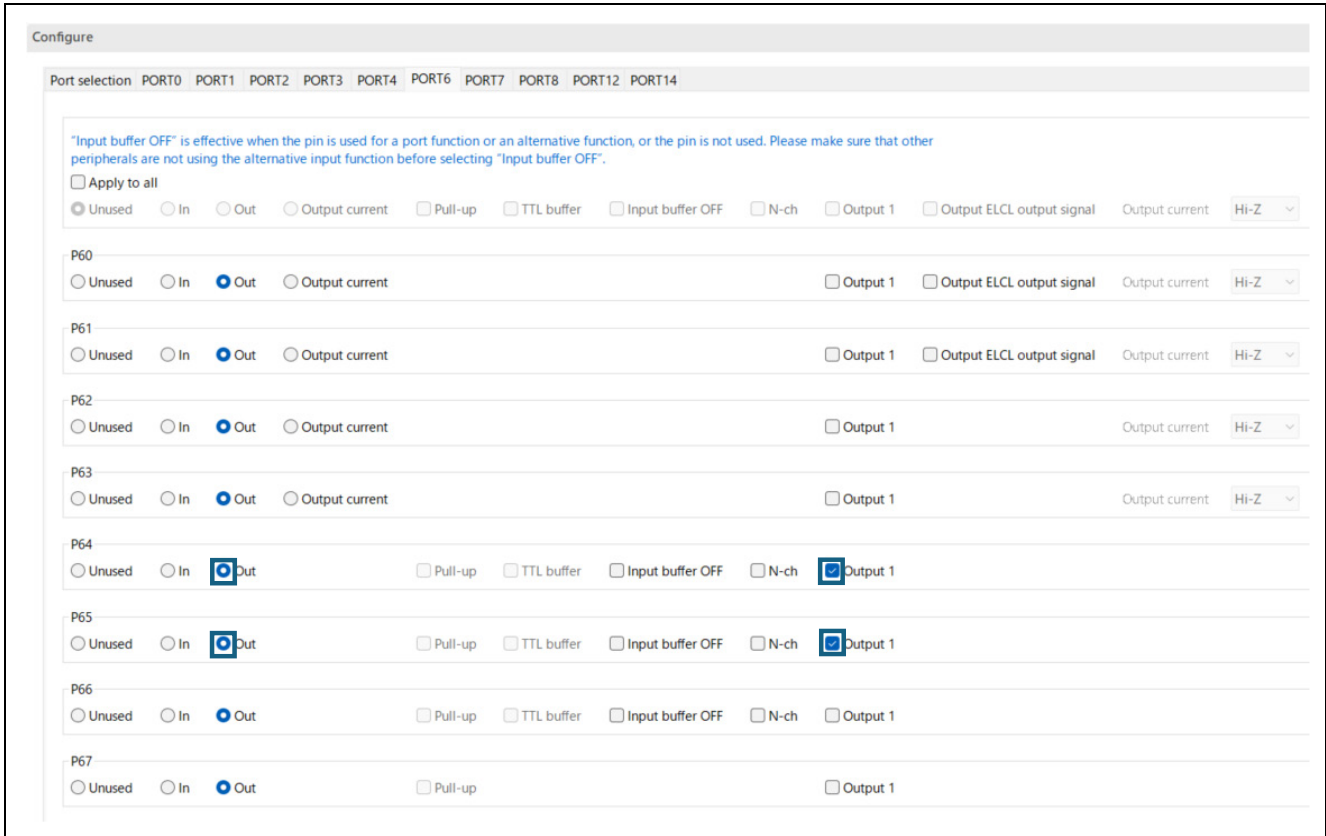


Figure 5.14 PORT6 Setting



Note: Only P64 and P65 are specified as LED ports in this document. Other ports are set to prevent unnecessary current consumption caused by the floating state. Settings to prevent unnecessary current consumption by ports floating are applied to ports other than these. Refer to "2.3 Connection of Unused Pins" in RL78/L23 User's Manual: Hardware (R01UH1082) for details on how to properly handle the application's unused ports and design your application to meet the electric characteristics.

Figure 5.15 shows the CTSU driver (r_ctsu) settings.

Figure 5.15 CTSU Driver (r_ctsu) Settings

The screenshot displays the 'Configure' interface for the CTSU driver. It is divided into two main sections: 'Configurations' and 'Resources'.

Configurations:


- Parameter check:** Use system default
- Data transfer of INTCTSUWR and INTCTSURD:** Interrupt handler
- DTC setting:** Setting in r_ctsu
- Select auto judgement:** Disable
- Data storage address settings:** Various hexadecimal values (e.g., 0xFF300, 0xFF400, 0xFF500, 0xFF600, 0xFF700, 0xFF800, 0xFF900, 0xFFA00, 0xFFB00, 0xFFC00).
- Auto-judgment function in Snooze mode using SMS:** Disable
- Data storage address settings for CTSURD and CTSUWR:** 0xFF500 and 0xFF800.
- Interrupt levels:** Level 2 for INTCTSUWR, INTCTSURD, and INTCTSUFN.
- External trigger settings:** PORT14, BIT0, and INTPT1.

Resources:

- CTSU Resource:** A list of 36 pins (TS00 to TS35). Each pin has a checkbox labeled 'Used'. Pins TS00 through TS16, TS17, and TS18 are checked, indicating they are used. Pins TS19 through TS35 are unchecked.

Figure 5.16 shows the settings of the TOUCH driver (rm_touch).

Figure 5.16 TOUCH Driver (rm_touch) Settings

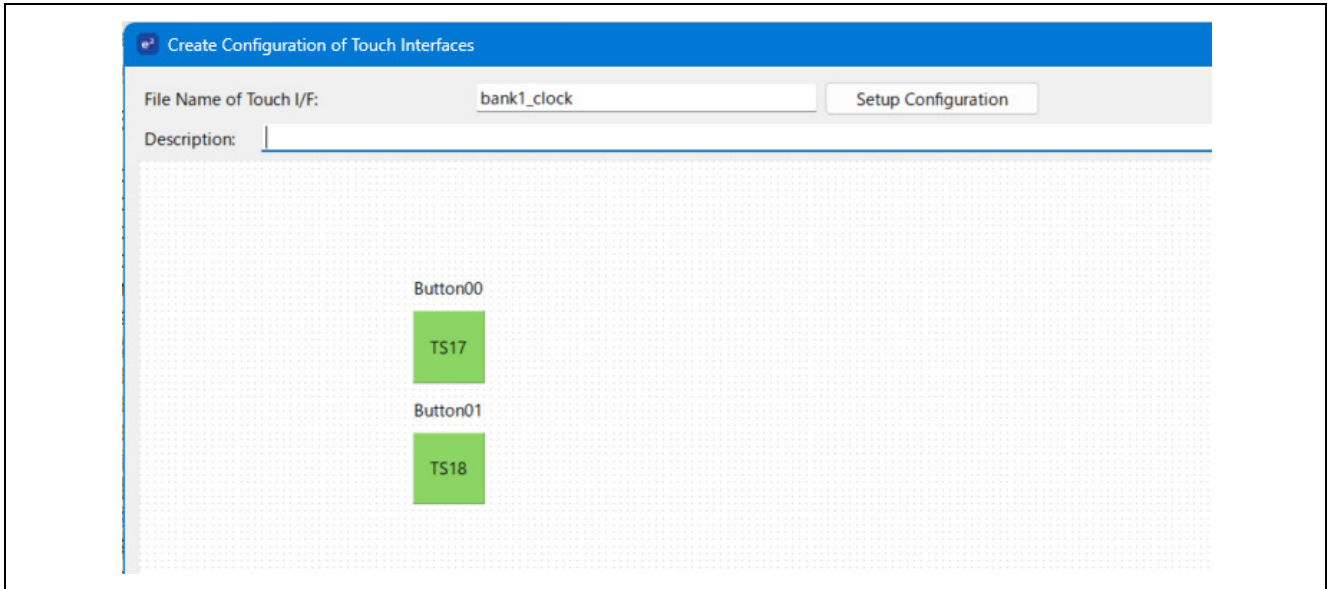
Configure	
type filter text (* = any string, ? = any character)	
Property	Value
<ul style="list-style-type: none"> ▼  Configurations 	
# Parameter check	Use system default
# Support QE monitor using UART	Disable
# Support QE tuning using UART	Disable
# UART channel	UART0
# Type of chattering suppression	TypeA : Counter of exceed threshold is hold within hysteresis range.

5.4 Capacitive Touch Settings

5.4.1 Touch Interface Configuration

Figure 5.17 shows the touch interface configuration. TS17 and TS18 are measured with the self-capacitance method.

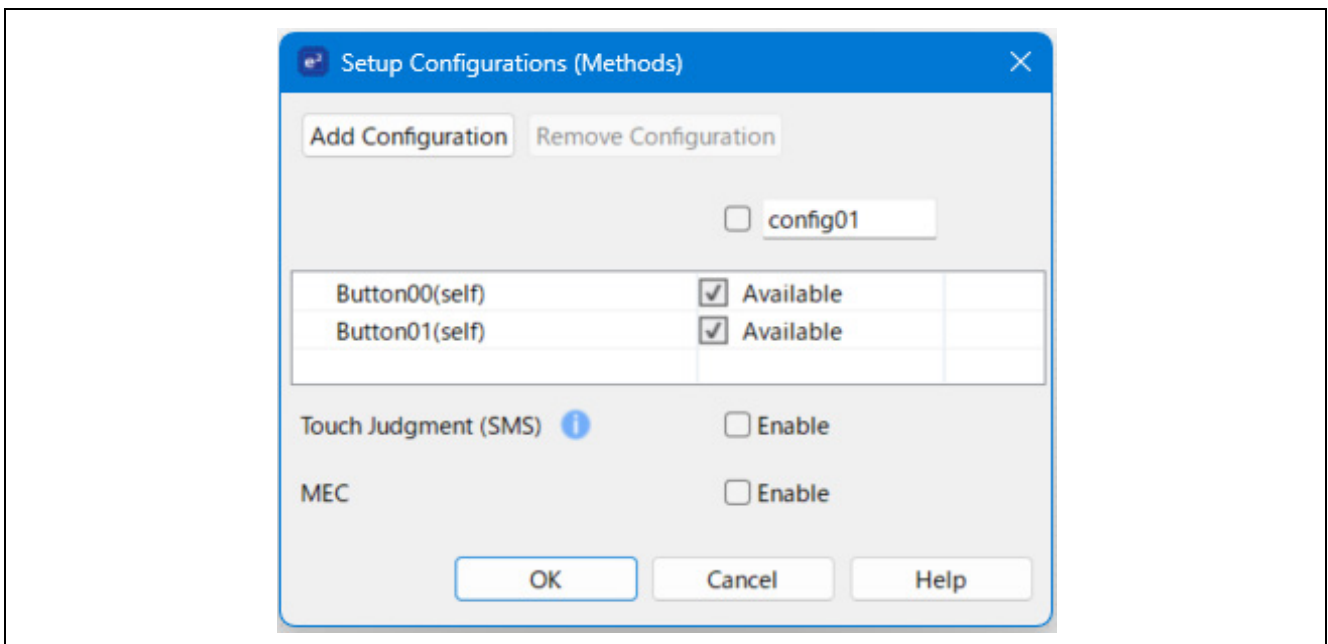
Figure 5.17 Touch Interface Configuration



5.4.2 Configuration (Methods) Settings

Figure 5.18 shows the touch interface configuration (methods) settings.

Figure 5.18 Configuration (Methods) Settings



5.4.3 Tuning Results

Figure 5.19 shows the QE tuning results of the touch interface. This sample code operates with the setting values shown in the figure below.

The tuning results depend on the operating environment when QE tuning is performed. Thus, if QE tuning is performed again, these values may change.

Figure 5.19 QE Tuning Results

Tuning Gesture								
Touch I/F Configuration: bank1_clock								
Method	Kind	Name	Touch Sensor	Parasitic Capacitance[pF]	Sensor Drive Pulse Frequency[MHz]	Threshold	Scan Time[ms]	Overflow
config01	Button(self)	Button00	TS17	7.632	5.361	3928	0.576	None
config01	Button(self)	Button01	TS18	7.41	5.489	4072	0.576	None

5.5 Constants

Table 5-3 lists the constants used in the sample code.

Table 5-3 Constants Used in the Sample Code

Constant Name	Setting Value	Contents
MAX_SEC_MIN	59	Clock maximum minute and second values
MAX_HOUR	23	Clock maximum hour value
MIN_SEC_MIN_HOUR	0	Clock minimum values (0) of hour, minute and second
UNIT_SEC	0	Clock unit of seconds
UNIT_MIN	1	Clock unit of minutes
UNIT_HOUR	2	Clock unit of hours
TIME_SETTING_FINISH	5	Time to end time setup (sec)
LONG_PRESS_SEC	3	Continuous touch detection time (sec)
COUNTINUOUS_START_NUM	3	Continuous touch detection count
TIME_DATA_ADDRESS	0x000F1000uL	The starting address of the memory where the time data is stored.
WRITE_DATA_LENGTH	3u	Time data size for data flash

5.6 Variables

Table 5-4 and Table 5-5 lists the static variables.

Table 5-4 Static Variables Used in the Sample Code (1/2)

Type	Variable Name	Contents	Function Used
uint8_t	g_rtc_interrupt_flag	RTC interrupt flag	r_rtc_callback r_change_time
uint8_t	g_show_segdata[40][4]	Array to store characters displayed on the LCD	r_lcd_show
uint8_t	g_digit_segdata[8][4]	Array to store the LCD display digits	r_lcd_show
uint8_t	g_touch_button_flag	Flag to enable the touch function	r_rtc_callback r_time_unit_change r_tau0_2_long_press_callback
uint8_t	s_lcd_seconds	Variable to store the clock second value	r_rtc_callback r_time_show r_change_time r_read_dataflash r_df_write
uint8_t	s_lcd_minutes	Variable to store the clock minute value	r_rtc_callback r_time_show r_change_time r_read_dataflash r_df_write
uint8_t	s_lcd_hours	Variable to store the clock hour value	r_rtc_callback r_time_show r_change_time r_read_dataflash r_df_write
uint8_t	sp_time_address[3]	Array to store clock second, minute, and hour variables	r_touch_plus_set_time r_touch_minus_set_time
uint8_t	s_unit	Variable to store clock unit	r_touch_plus_set_time r_touch_minus_set_time r_blink_set_time r_time_unit_change
uint8_t	s_clock_mode	Variable to store clock mode	r_rtc_callback r_time_unit_change
uint8_t	s_blink_flag	Flag to blink the selected unit on the LCD	r_tau0_1_blink_callback
uint8_t	s_set_time_limit_count	Flag to count time to end of time setup state	r_userswitch_callback r_rtc_callback r_touch_plus_set_time r_touch_minus_set_time r_touch_both_buttons
uint8_t	s_clock_start_flag	Flag to indicate start of LCD time display	r_bank1_clock_start r_userswitch_release r_userswitch_callback

Table 5-5 Static Variables Used in the Sample Code (2/2)

Type	Variable Name	Contents	Function Used
uint8_t	s_100ms_count	Flag to count a wait time every 100ms	r_tau0_3_delay_callback r_delay_100ms
uint8_t	s_chattering_flag	Flag to count time of long press on the user switch	r_userswitch_callback r_tau0_4_chattering_callback
uint8_t	s_prev_button1_flag	Flag to store the previous state of touch button 1	r_touch_plus_set_time r_touch_both_buttons r_no_touch
uint8_t	s_prev_button2_flag	Flag to store the previous state of touch button 2	r_touch_minus_set_time r_touch_both_buttons r_no_touch
uint8_t	s_demo_change_flag	Flag to switch demos	r_change_demo r_tau0_2_long_press_callback
uint8_t	s_demo_change_count	Flag that counts the length of time the user switch is held down	r_userswitch_callback r_tau0_2_long_press_callback
uint8_t	s_continuous_touch_flag	Flag to determine an interval of continuous touch on the touch button	r_tau0_5_continuous_callback r_touch_plus_set_time r_touch_minus_set_time r_touch_both_buttons r_no_touch
uint8_t	s_continuous_touch_count	Flag to determine continuous touch start count on the touch button	r_tau0_5_continuous_callback r_touch_plus_set_time r_touch_minus_set_time
uint8_t	s_userswitch_on_off_flag	Flag to determine ON/OFF state of the user switch	r_userswitch_release r_userswitch_callback

5.7 Functions

Table 5-6 lists the functions used in the sample code for BANK1 (clock.c).

Table 5-6 Functions Used in the Sample Code

Function Name	Outline
void r_bank1_clock_start(void)	BANK1 clock start processing
void r_change_demo(void)	Demo switch processing
void r_userswitch_release(void)	User switch detection processing
void r_change_to_sub(void)	Transition to the sub-system clock operation
void r_change_to_main(void)	Transition to the main system clock operation
void r_userswitch_callback(void)	Callback for user switch press interrupt
void r_rtc_callback(void)	Callback for RTC interrupt
void r_tau0_1_blink_callback(void)	Callback for TAU0_1 interrupt
void r_tau0_2_long_press_callback(void)	Callback for TAU0_2 interrupt
void r_tau0_3_delay_callback(void)	Callback for TAU0_3 interrupt
void r_tau0_4_chattering_callback(void)	Callback for TAU0_4 interrupt
void r_tau0_5_continuous_callback(void)	Callback for TAU0_5 interrupt
void r_touch_plus_set_time(void)	Processing for touch detection of touch button 1
void r_touch_minus_set_time(void)	Processing for touch detection of touch button 2
void r_touch_both_buttons(void)	Processing for simultaneous touch detection of touch buttons 1 and 2
void r_no_touch(void)	Touch release detection processing
static void r_lcd_show(uint8_t value, uint8_t digit)	Display of LCD values
static void r_time_show(void)	Display of time on the LCD
static void r_change_time(void)	Acquisition of time from the RTC register
static void r_blink_set_time(void)	Blinking of the selected unit during time setup
static void r_array_show(uint8_t* array, uint8_t num, uint8_t delay)	Sequential display processing of array data on LCD
static void r_clear_show(void)	Clearing of LCD display
static void delay_100ms(uint8_t num)	Delay processing
static void r_read_dataflash(void)	Reading of clock data
static void r_time_unit_change(void)	Change of time unit to be set
static uint8_t r_bank_swap(void)	Bank swap processing
static uint8_t r_df_write(void)	Write clock data

5.8 Function Specifications

The following tables list the function specifications for BANK1 (clock.c) sample code.

r_bank1_clock_start

Outline	BANK1 clock start processing
Header	clock.h
Declaration	void r_bank1_clock_start(void)
Description	Displays "RL78/L23" and "BANK1 C" on the LCD when the demo starts.
Arguments	None
Return Value	None
Remarks	None

r_change_demo

Outline	Demo switch processing
Header	clock.h
Declaration	void r_change_demo(void)
Description	Switching is performed by detecting a long press of the user switch.
Arguments	None
Return Value	None
Remarks	None

r_userswitch_release

Outline	User switch detection processing
Header	clock.h
Declaration	void r_userswitch_release(void)
Description	Changes the corresponding flag depending on release of the user switch.
Arguments	None
Return Value	None
Remarks	None

r_change_to_sub

Outline	Transition to the sub-system clock operation
Header	clock.h
Declaration	void r_change_to_sub(void)
Description	Switches the current clock from the main system clock to the sub-system clock.
Arguments	None
Return Value	None
Remarks	None

r_change_to_main

Outline	Transition to the main system clock operation
Header	clock.h
Declaration	void r_change_to_main(void)
Description	Switches the current clock from the sub-system clock to the main system clock.
Arguments	None
Return Value	None
Remarks	None

r_userswitch_callback

Outline	Callback for user switch press interrupt
Header	clock.h
Declaration	void r_userswitch_callback(void)
Description	With short press, starts time setup and calls r_time_unit_change.
Arguments	None
Return Value	None
Remarks	None

r_rtc_callback

Outline	Callback for RTC interrupt
Header	clock.h
Declaration	void r_rtc_callback(void)
Description	Counts time up every time an interrupt occurs. Counts to return to clock when performing time setup by pressing the user switch.
Arguments	None
Return Value	None
Remarks	None

r_tau0_1_blink_callback

Outline	Callback for TAU0_1 interrupt
Header	clock.h
Declaration	void r_tau0_1_blink_callback(void)
Description	Blinks the selected unit of time on the LCD when setting time.
Arguments	None
Return Value	None
Remarks	None

r_tau0_2_long_press_callback

Outline	Callback for TAU0_2 interrupt
Header	clock.h
Declaration	void r_tau0_2_long_press_callback(void)
Description	Detects long press of user switch for bank swap switching.
Arguments	None
Return Value	None
Remarks	None

r_tau0_3_delay_callback

Outline	Callback for TAU0_3 interrupt
Header	clock.h
Declaration	void r_tau0_3_delay_callback(void)
Description	Increments the delay count variable with the timer (TAU0 channel 3).
Arguments	None
Return Value	None
Remarks	None

r_tau0_4_chattering_callback

Outline	Callback for TAU0_4 interrupt
Header	clock.h
Declaration	void r_tau0_4_chattering_callback(void)
Description	Disables external interrupts for a certain time period to prevent chattering.
Arguments	None
Return Value	None
Remarks	None

r_tau0_5_continuous_callback

Outline	Callback for TAU0_5 interrupt
Header	clock.h
Declaration	void r_tau0_5_continuous_callback(void)
Description	Determines continuous touch on the touch button
Arguments	None
Return Value	None
Remarks	None

r_touch_plus_set_time

Outline	Processing for touch detection of touch button 1
Header	clock.h
Declaration	void r_touch_plus_set_time(void)
Description	Adds 1 to the LCD display of the currently set time unit when touch detection of touch button 1 occurs.
Arguments	None
Return Value	None
Remarks	None

r_touch_minus_set_time

Outline	Processing for touch detection of touch button 2
Header	clock.h
Declaration	void r_touch_minus_set_time(void)
Description	Adds 1 to the LCD display of the currently set time unit when touch detection of touch button 2 occurs.
Arguments	None
Return Value	None
Remarks	None

r_touch_both_buttons

Outline	Processing for simultaneous touch detection of touch buttons 1 and 2
Header	clock.h
Declaration	void r_touch_both_buttons(void)
Description	Stops the timer and resets control variables when simultaneous touch detection of touch buttons 1 and 2 occurs.
Arguments	None
Return Value	None
Remarks	None

r_array_show

Outline	Sequential display processing of array data on LCD	
Header	None	
Declaration	static void r_array_show(uint8_t * array, uint8_t num, uint8_t delay)	
Description	Displays the numerals and characters on the LCD that correspond to the numbers stored in the array.	
Arguments	uint8_t * array	Pointer to the value to be displayed
	uint8_t num	Number of elements to be displayed
	uint8_t delay	Wait time after each display(every 100ms)
Return Value	None	
Remarks	None	

r_clear_show

Outline	Clearing of LCD display	
Header	None	
Declaration	static void r_clear_show(void)	
Description	Displays blank for all 8 digits on the LCD to clear all displayed contents.	
Arguments	None	
Return Value	None	
Remarks	None	

r_delay_100ms

Outline	Delay processing	
Header	None	
Declaration	static void r_delay_100ms(uint8_t num)	
Description	Generates 100ms delay.	
Arguments	uint8_t num	Wait time in 100ms unit, e.g. 300ms wait when num = 3
Return Value	None	
Remarks	None	

r_read_dataflash

Outline	Reading of clock data	
Header	None	
Declaration	static void r_read_dataflash(void);	
Description	Read clock data from data flash and set it to RTC.	
Arguments	None	
Return Value	None	
Remarks	None	

r_time_unit_change

Outline	Change of time unit to be set	
Header	None	
Declaration	static void r_time_unit_change(void)	
Description	Changes unit of time to be set (sec -> minute -> hour -> sec).	
Arguments	None	
Return Value	None	
Remarks	None	

r_bank_swap

Outline	Bank swap processing	
Header	None	
Declaration	static uint8_t r_bank_swap(void)	
Description	Perform bank swap processing.	
Arguments	None	
Return Value	Execution result status	
	SAMPLE_ENUM_RET_STS_OK	Successful completion
	SAMPLE_ENUM_RET_ERR_PARAMETER	Parameter error
	SAMPLE_ENUM_RET_ERR_MODE_MISMATCHED	Mode mismatched error
	SAMPLE_ENUM_RET_ERR_CONFIGURATION	Configuration error
	SAMPLE_ENUM_RET_ERR_CHECK_WRITE_DATA	Check write data error
	SAMPLE_ENUM_RET_ERR_CMD_ERASE	Erase command error
	SAMPLE_ENUM_RET_ERR_CMD_WRITE	Write command error
	SAMPLE_ENUM_RET_ERR_CMD_BLANKCHECK	Blankcheck command error
	SAMPLE_ENUM_RET_ERR_CMD_SET_EXTRA_AREA	Set extra area command (boot flag) error
Remarks	None	

r_df_write

Outline	Writing of clock data	
Header	None	
Declaration	static uint8_t r_df_write(void)	
Description	Write current clock data to data flash	
Arguments	None	
Return Value	Execution result status	
	SAMPLE_ENUM_RET_STS_OK	Successful completion
	SAMPLE_ENUM_RET_ERR_PARAMETER	Parameter error
	SAMPLE_ENUM_RET_ERR_MODE_MISMATCHED	Mode mismatched error
	SAMPLE_ENUM_RET_ERR_CONFIGURATION	Configuration error
	SAMPLE_ENUM_RET_ERR_CHECK_WRITE_DATA	Check write data error
	SAMPLE_ENUM_RET_ERR_CMD_ERASE	Erase command error
	SAMPLE_ENUM_RET_ERR_CMD_WRITE	Write command error
	SAMPLE_ENUM_RET_ERR_CMD_BLANKCHECK	Blankcheck command error
Remarks	None	

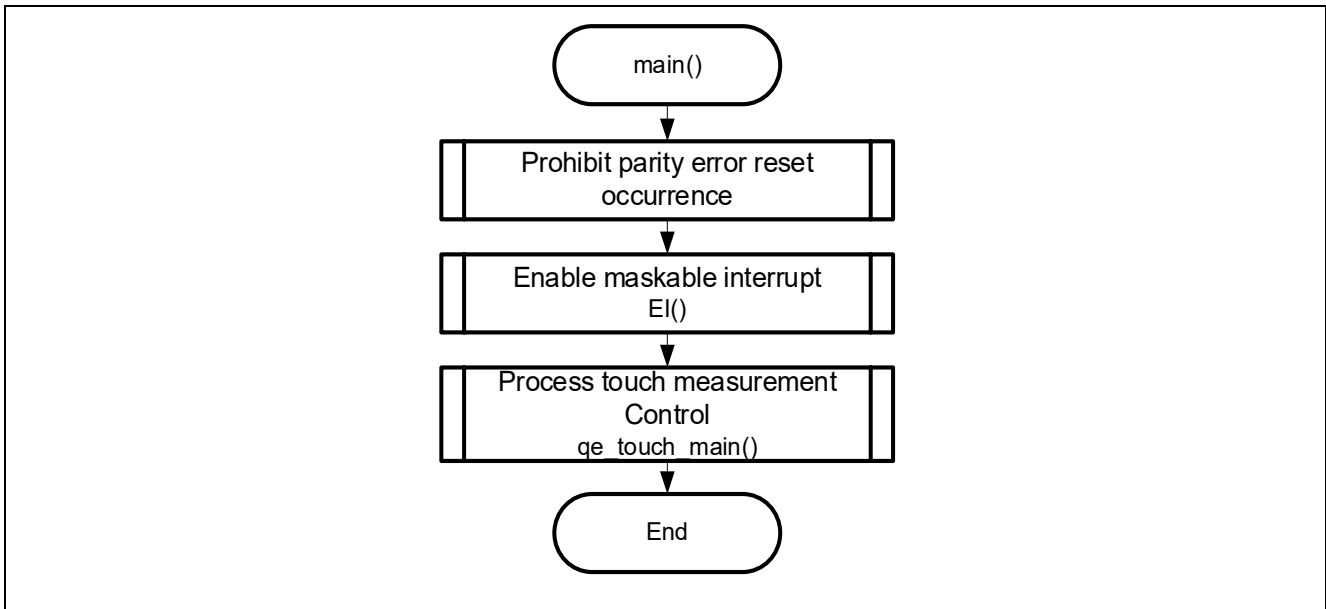
5.9 Flowcharts

The flowchart of the main functions showing the flow of this sample code (BANK1) is shown below.

5.9.1 main Function

Figure 5.20 shows a flowchart of the main function.

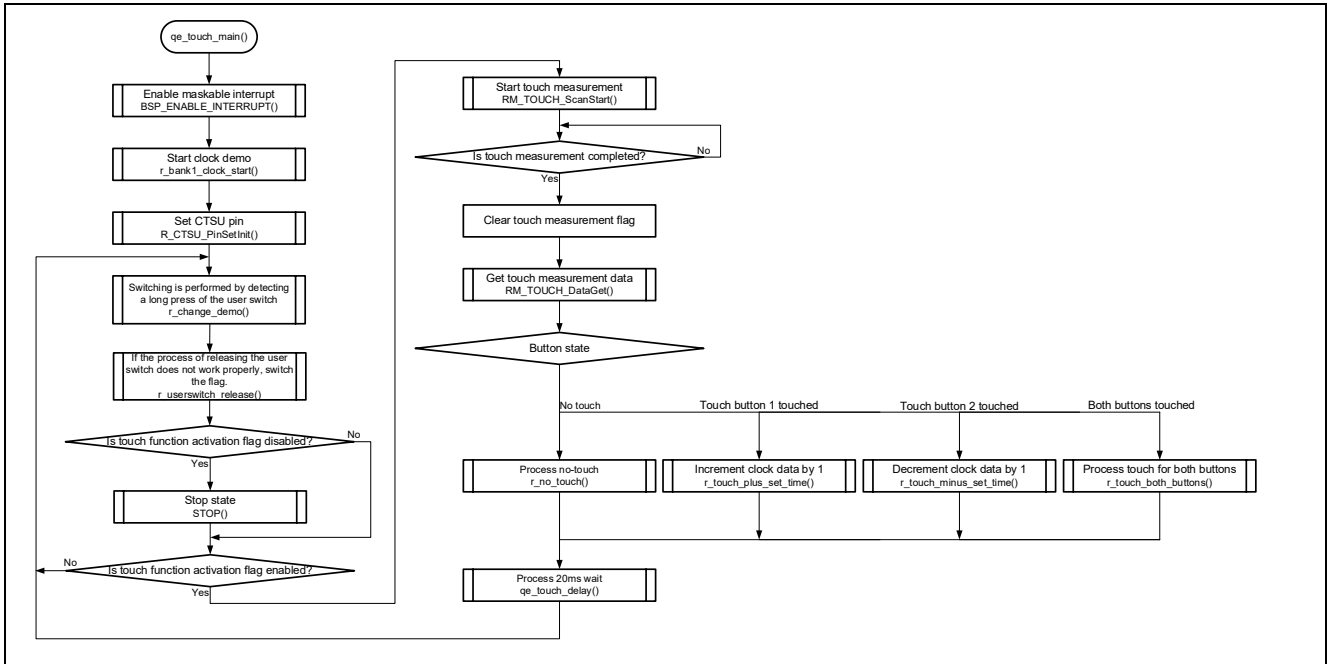
Figure 5.20 main Function Flowchart



5.9.2 qe_touch_main Function

Figure 5.21 shows a flowchart of the qe_touch_main function.

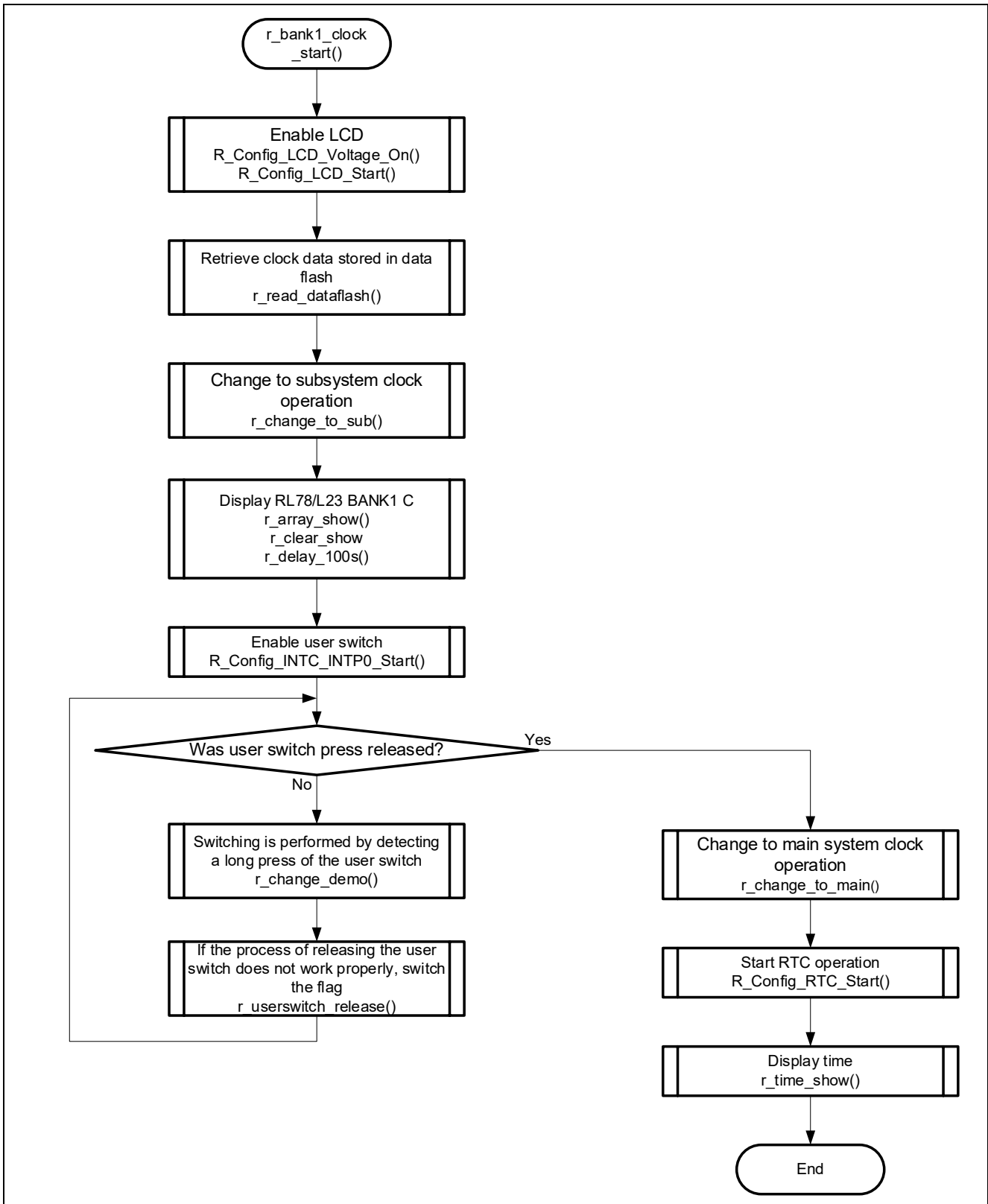
Figure 5.21 qe_touch_main Function Flowchart



5.9.3 r_bank1_clock_start Function

Figure 5.22 shows a flowchart of the r_bank1_clock_start function.

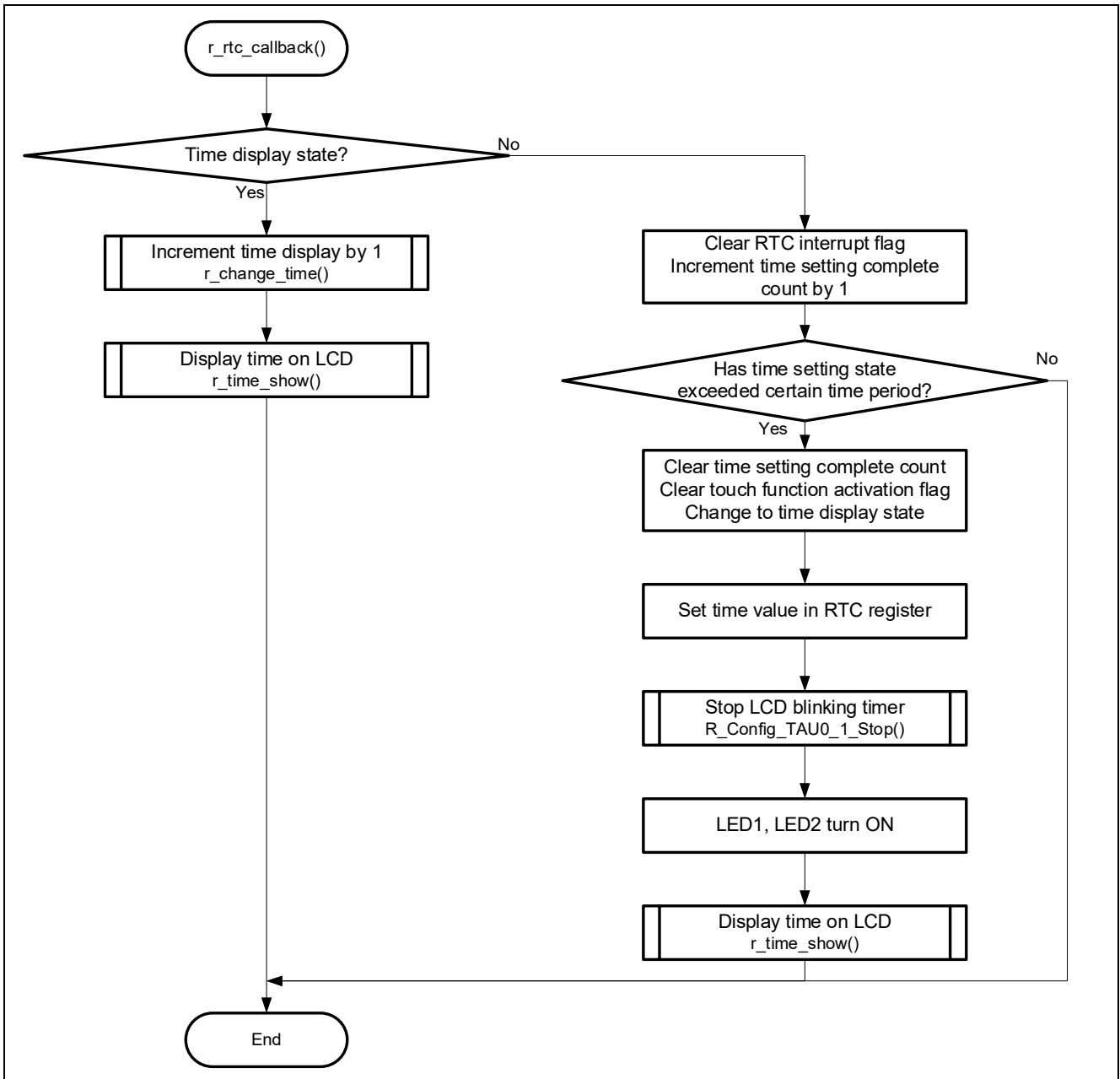
Figure 5.22 r_bank1_clock_start Function Flowchart



5.9.4 r_rtc_callback Function

Figure 5.23 shows a flowchart of the r_rtc_callback function.

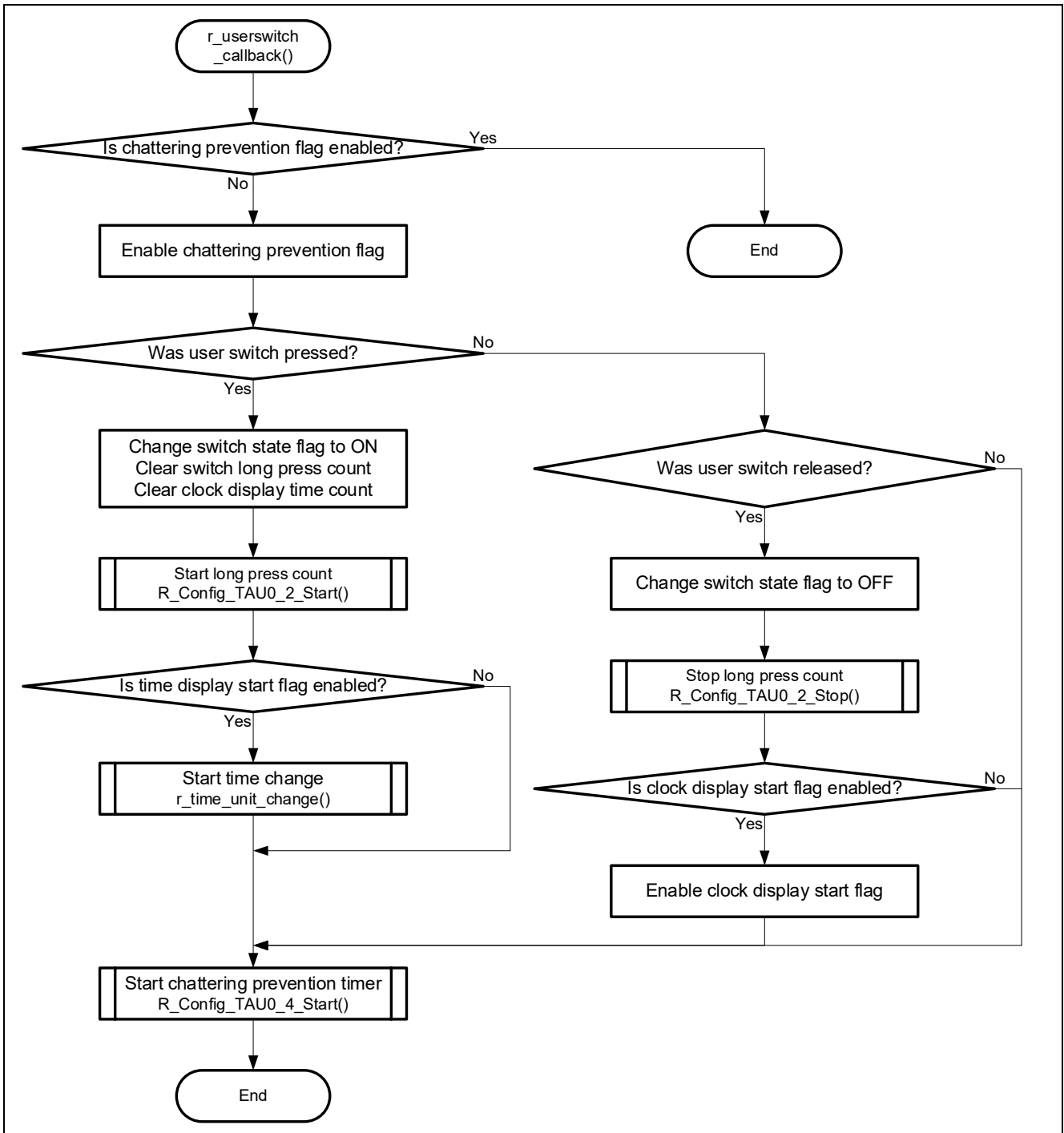
Figure 5.23 r_rtc_callback Function Flowchart



5.9.5 r_userswitch_callback Function

Figure 5.24 shows a flowchart of the r_userswitch_callback function.

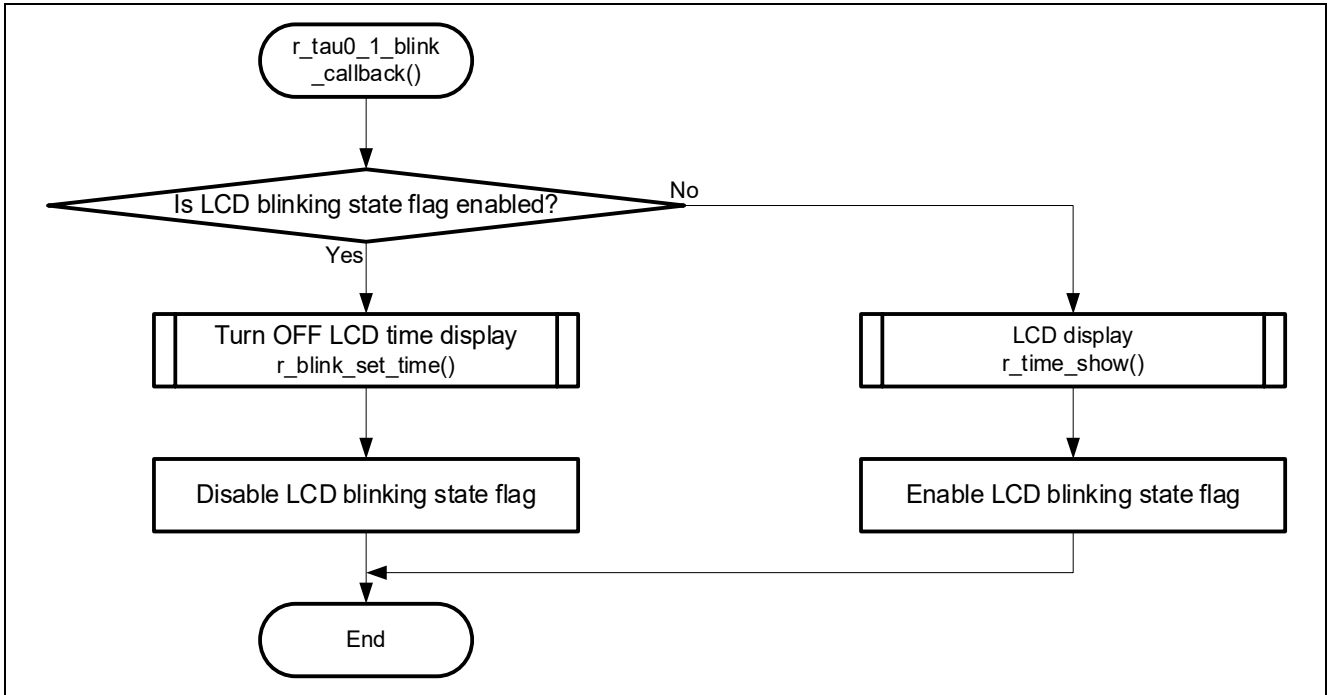
Figure 5.24 r_userswitch_callback Function Flowchart



5.9.6 r_tau0_1_blink_callback Function

Figure 5.25 shows a flowchart of the r_tau0_1_blink_callback function.

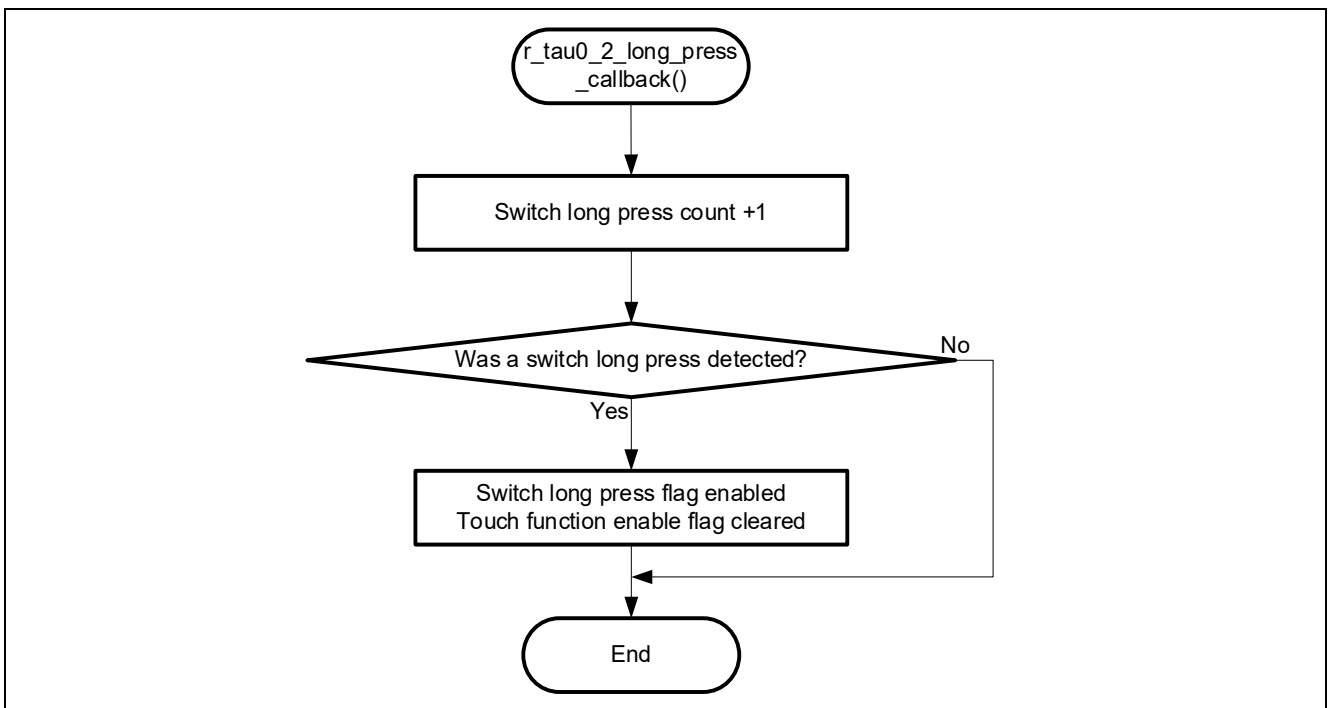
Figure 5.25 r_tau0_1_blink_callback Function Flowchart



5.9.7 r_tau0_2_long_press_callback Function

Figure 5.26 shows a flowchart of the r_tau0_2_long_press_callback function.

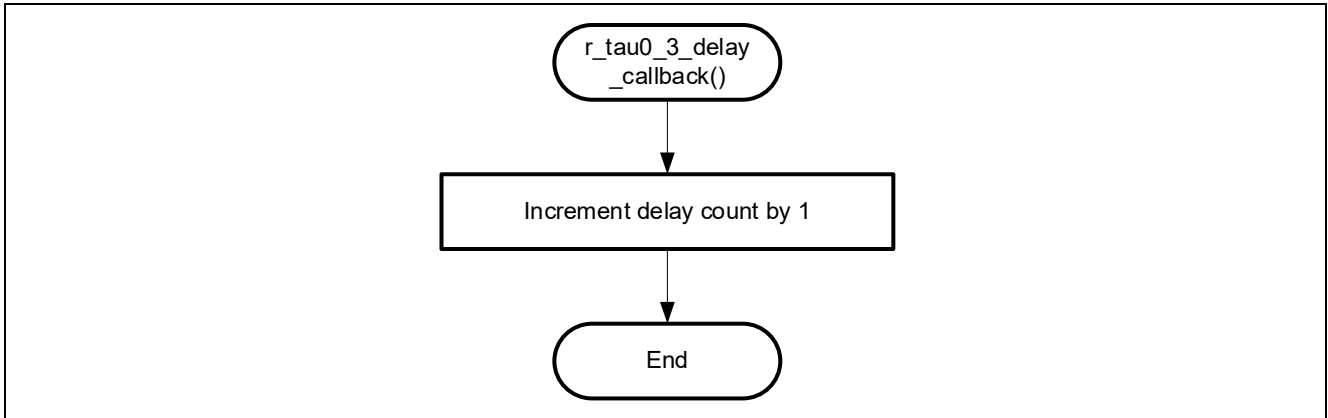
Figure 5.26 r_tau0_2_long_press_callback Function Flowchart



5.9.8 **r_tau0_3_delay_callback Function**

Figure 5.27 shows a flowchart of the r_tau0_3_delay_callback function.

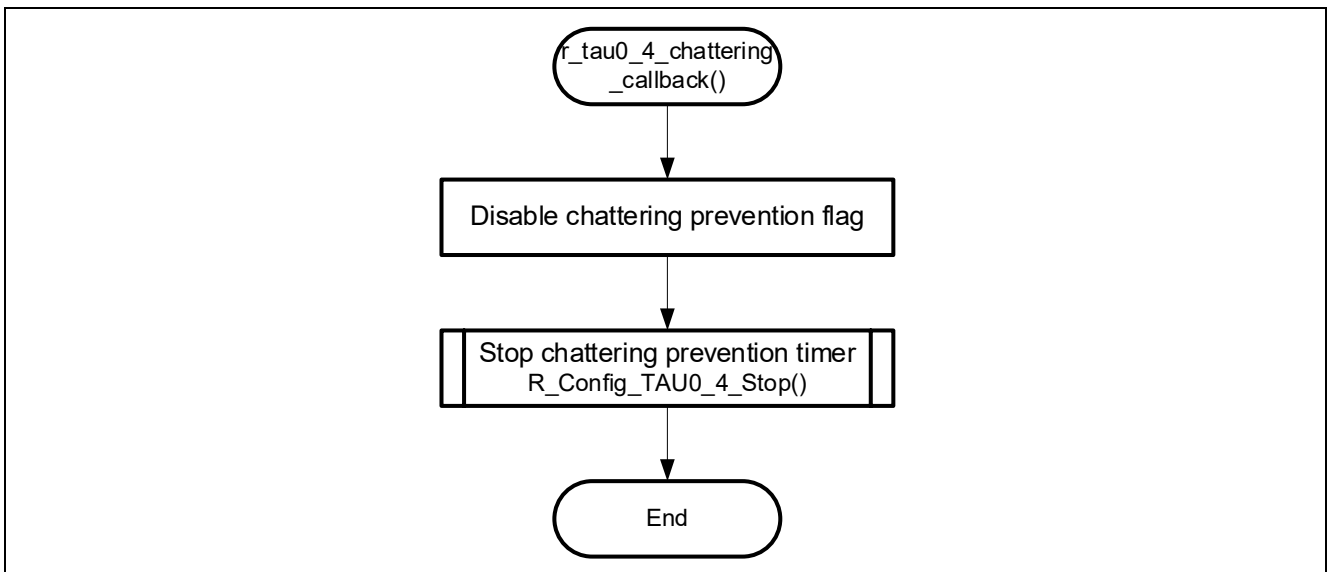
Figure 5.27 r_tau0_3_delay_callback Function Flowchart



5.9.9 **r_tau0_4_chattering_callback Function**

Figure 5.28 shows a flowchart of the r_tau0_4_chattering_callback function.

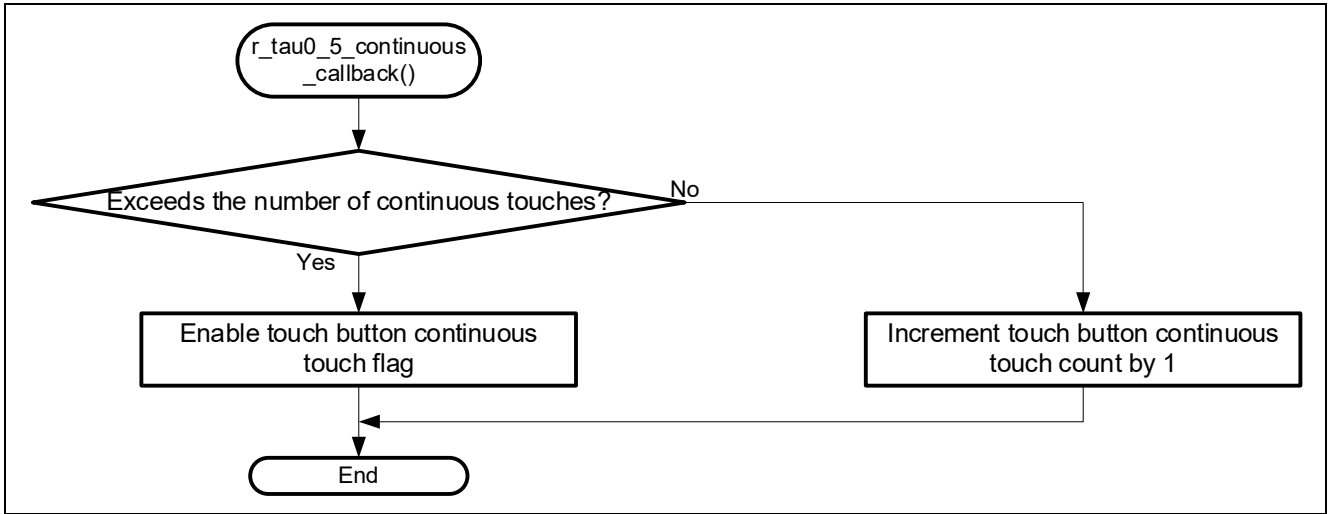
Figure 5.28 r_tau0_4_chattering_callback Function Flowchart



5.9.10 r_tau0_5_continuous_callback Function

Figure 5.29 shows a flowchart of the r_tau0_5_continuous_callback function.

Figure 5.29 r_tau0_5_continuous_callback Function Flowchart



6. BANK2 Software

6.1 Operation Overview

The sample code uses the RL78/L23 LCD controller/driver to display assumed temperature data on the remote controller. The temperature data is displayed on the LCD using the user switch operation and the displayed temperature data is changed with the touch buttons. When the user switch and touch buttons are not touched for a set period, the LCD display turns off.

The clock frequency, I/O ports, RTC and LCD controller/driver are configured in the initial settings.

After the initial settings are complete, the sample code displays "RL78/L23" and "BANK2 T" on the LCD consecutively, and transitions to the wait state. The wait state is released by a short press on the user switch (both edges of INTPO detected), and the state is transitioned to the temperature data adjustment state.

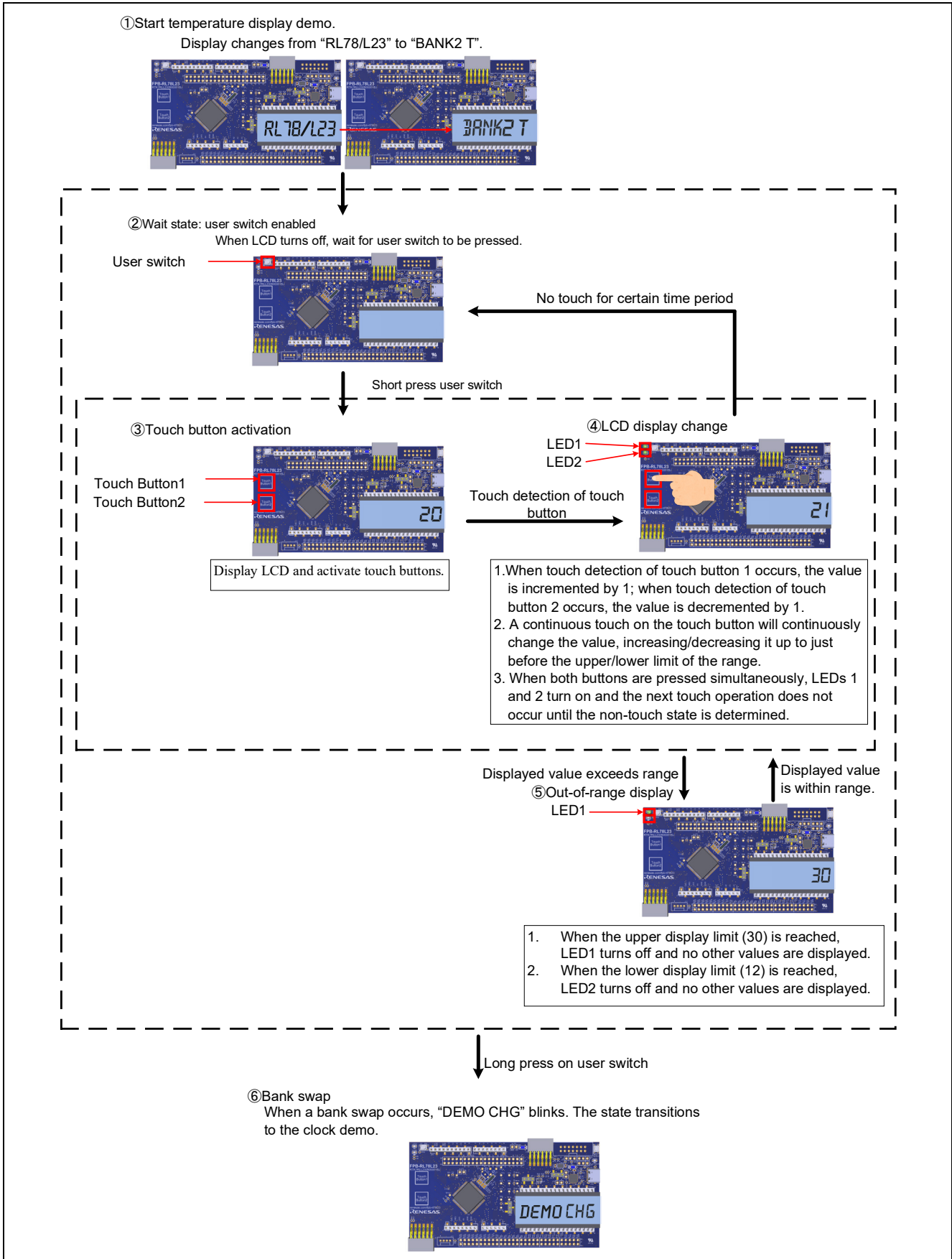
The touch buttons are disabled in the wait state, and available only in the temperature data adjustment state.

In the temperature data adjustment state, the temperature data is adjusted in the range of 12°C and 30°C, and the adjusted data is displayed on the LCD. The initial value of the temperature data is 20°C. Touch detection of touch button 1 increases the temperature data by 1, and touch detection of touch button 2 decreases the temperature data by 1. The temperature data can be changed continuously by touching the touch button continuously (long press). When the user switch is not pressed and no touch detection of the touch buttons occurs for a certain period, the state returns to the wait state and the LCD display turns off. Note that when the temperature is 12°C or 30°C, the program is not returned to the wait state.

A long press on the user switch displays "DEMO CHG" on the LCD and executes the bank swap function.

Refer to the state transition diagram in Figure 6.1 for more details.

Figure 6.1 State Transition Diagram



6.2 File Composition

Table 6-1 and Table 6-2 list the files used in the BANK2 sample code. Files generated by the integrated development environment are not included in this table.

Table 6-1 Files Used in the Sample Code(1/2)

Folder and file name	Description	Smart Configurator Usage
¥bank2_temp<DIR>	Sample code folder	
¥src<DIR>	Source folder	
¥bank2_temp.c	BANK2 source file	
¥temp.c	Temperature display source file	
¥temp.h	Temperature display header file	
¥lcd_segdata.c	LCD display source file	
¥include<DIR>	RFD include folder	
¥sample<DIR>	RFD sample folder	
¥source<DIR>	RFD source folder	
¥userown<DIR>	RFD user processing folder	
¥smc_gen<DIR>	Smart configurator generation components storage folder	✓
¥Config_INTC<DIR>	External interrupt components folder	✓
¥Config_ITL000<DIR>	ITL000 components folder	✓
¥Config_LCD<DIR>	LCD components folder	✓
¥Config_PORT<DIR>	PORT components folder	✓
¥Config_RTC<DIR>	RTC components folder	✓
¥Config_TAU0_3<DIR>	TAU0_3 components folder	✓
¥Config_TAU0_5<DIR>	TAU0_5 components folder	✓
¥r_ctsu<DIR>	CTSU driver folder	✓
¥rm_touch<DIR>	TOUCH driver folder	✓

Table 6-2 Files Used in the Sample Code(2/2)

Folder and file name	Description	Smart Configurator Usage
¥bank2_temp<DIR>	Sample code folder	
¥qe_gen<DIR>	QE for Capacitive Touch generation file	
¥qe_touch_config.c	QE generation configuration source file	
¥qe_touch_config.h	QE generation configuration header file	
¥qe_touch_define.h	QE generation definition header file	
¥qe_touch_sample.c	Main function source file including touch operation	
¥QE_Touch<DIR>	QE configuration folder	

Precaution regarding and.

Note: The sample code of the IAR version has a different configuration. Check the sample code of the IAR version for details. In addition, stores bank2_temp.ipcf. For details, refer to "RL78 Smart Configurator User's Guide: IAREW (R20AN0581)".

6.3 Smart Configurator Settings

Shows the smart configurator settings for BANK2.

Figure 6.2 shows the clock settings of the Smart Configurator.

Figure 6.2 Clock Settings

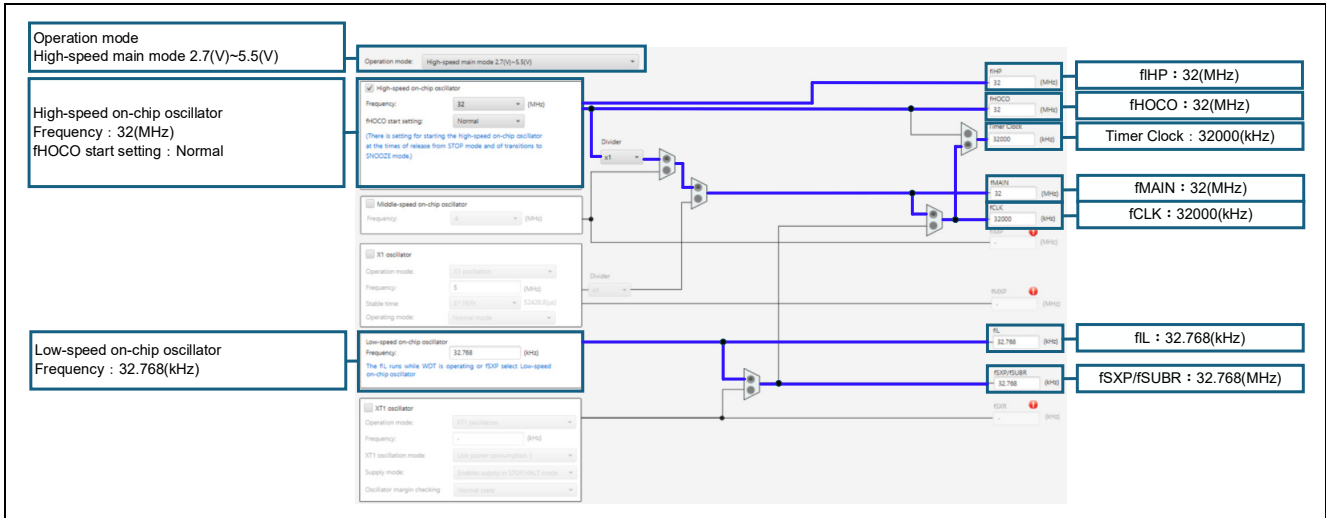


Figure 6.3 shows the system settings of the Smart Configurator.

Figure 6.3 System Settings

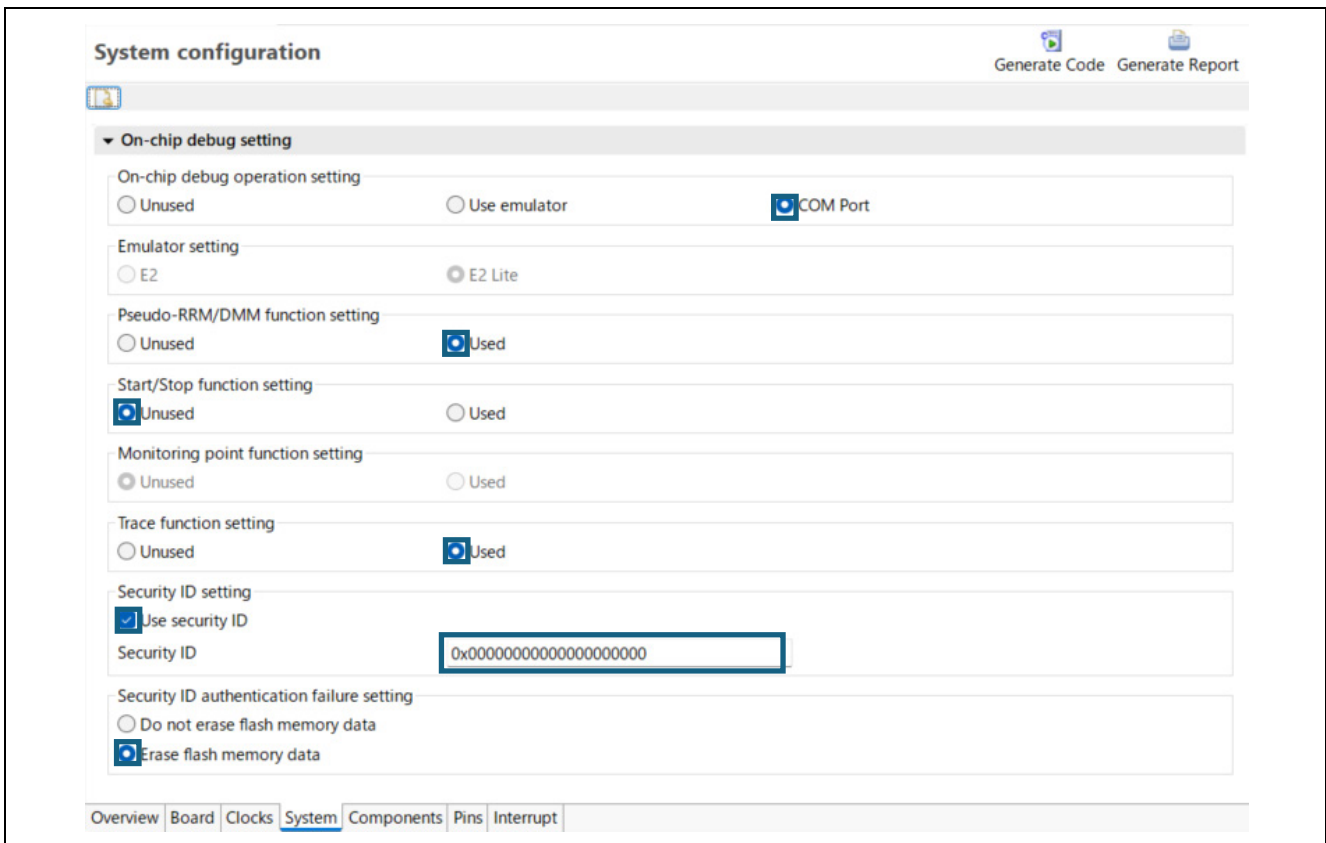


Figure 6.4 shows the LVD components (Config_LVD0) settings.

Figure 6.4 LVD Components (Config_LVD0) Settings

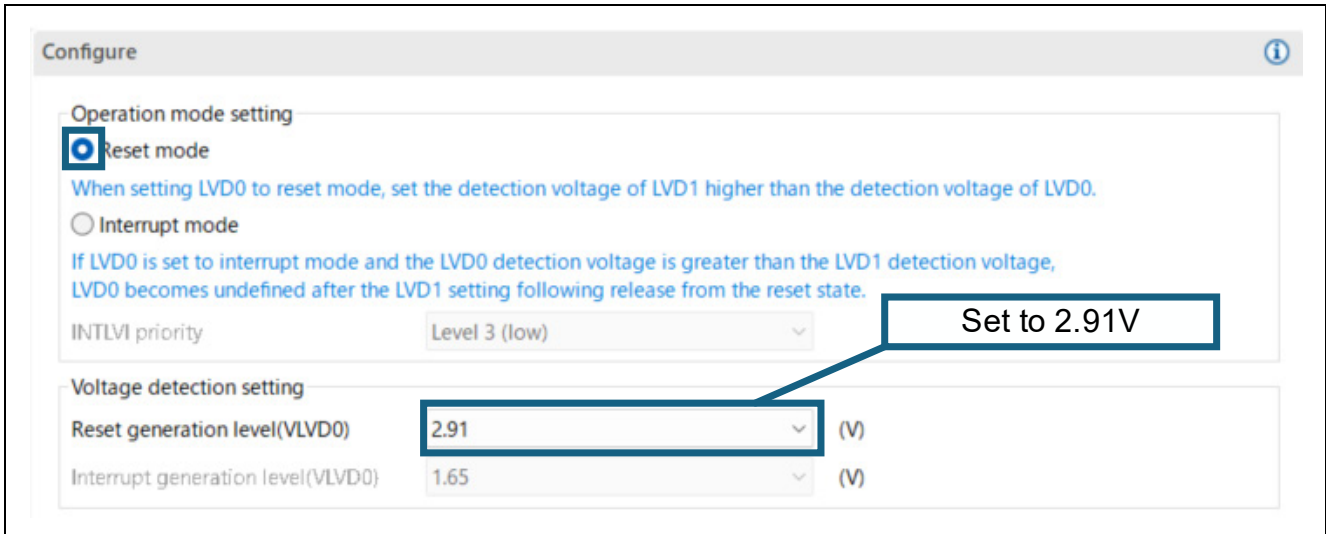


Figure 6.5 shows the settings of external interrupt components (Config_INTC).

Figure 6.5 External Interrupt Components (Config_INTC) Settings

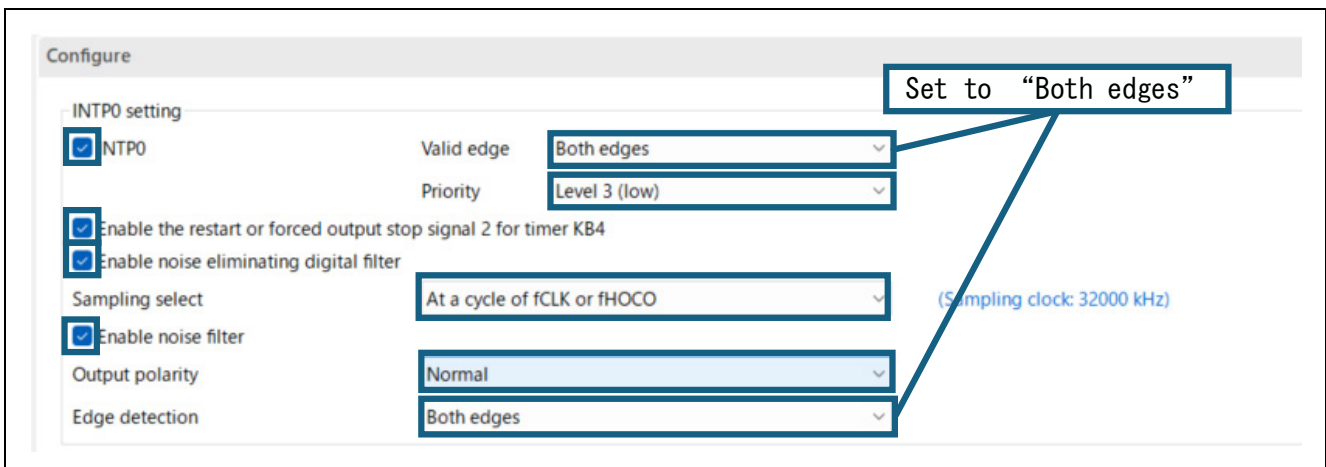


Figure 6.6 shows the settings of RTC Components (Config_RTC).

Figure 6.6 RTC Components (Config_RTC)Settings

The screenshot shows the 'Configure' window for the RTC components. It is divided into several sections:

- Clock setting:** The 'Clock source' dropdown is set to 'Low-speed on-chip oscillator clock (fIL)'. A callout box points to this dropdown with the text 'Set to "Low-speed on-chip oscillator clock (fIL)".' The clock frequency is noted as 32.768 kHz.
- Real-time clock setting:** 'Hour-system selection' is set to '24-hour'. There are options to set the initial value (date: 2000/01/01, time: 12:00:00) and enable the 1Hz output.
- Alarm detection function setting:** There are checkboxes for 'Use alarm detection function' and 'Set alarm initial value'. The 'Week day' section has checkboxes for Sunday through Saturday. The 'Hour:Minute' field is set to 12:00. A callout box points to this field with the text 'Set to "Once per 1 s"'. Note that this callout is positioned over the 'Hour:Minute' field but points to the 'Once per 1 s' value in the interrupt setting section below.
- Interrupt setting:** The checkbox 'Used as constant-period interrupt function (INTRTC)' is checked. The 'Once per 1 s' dropdown is selected. The 'Priority' dropdown is set to 'Level 3 (low)'.

Figure 6.7 shows the settings of TAU0_3 Components (Config_TAU0_3).

Figure 6.7 TAU0_3 Components (Config_TAU0_3) Settings

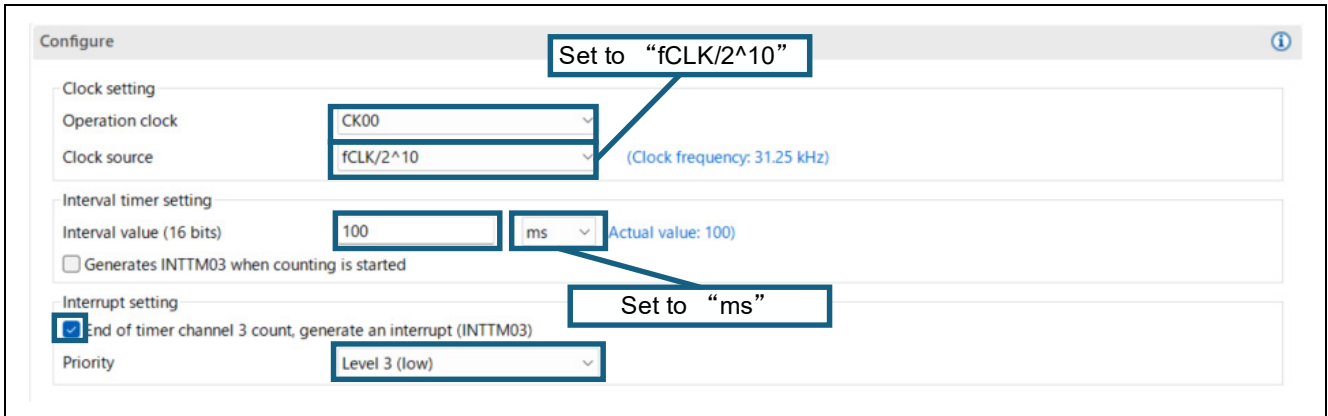


Figure 6.8 shows the settings of TAU0_5 components (Config_TAU0_5).

Figure 6.8 TAU0_5 Components (Config_TAU0_5) Settings

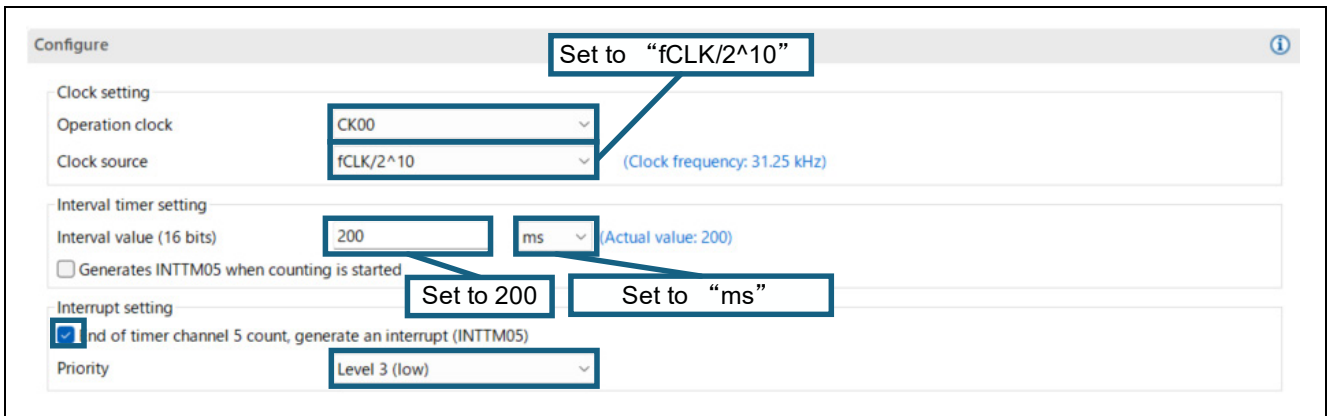


Figure 6.9 shows the settings of TAU0_5 components (Config_TAU0_5).

Figure 6.9 TAU0_5 Components Settings

The screenshot displays the configuration interface for TAU0_5 components. The settings are organized into several sections:

- Display waveform setting:** Type A waveform is selected.
- Drive voltage generator setting:** Driving voltage generator method is set to "Capacitor split method for the VDD reference".
- Display mode setting:** Number of time slices is set to "4 (1/3 bias mode)".
- Display data area setting:** Display data area selection is set to "A-pattern area data".
- Control initial value of voltage boosting pin:** VDD >= 2.7 V is selected.
- Reference voltage setting:** VLCD voltage (VL1 Voltage) is 1.01 V, VLCD voltage (VL2 Voltage) is 2.02 V, and VLCD voltage (VL4 Voltage) is 3.03 V.
- Segment output pin setting:** A grid of checkboxes for segments SEG0/COM4 through SEG55. Segments SEG0, SEG1, SEG2, SEG3, SEG4, SEG5, SEG6, SEG7, SEG8, SEG9, SEG10, SEG11, SEG12, SEG13, SEG14, SEG15, SEG16, SEG17, SEG18, SEG19, SEG20, SEG21, SEG22, SEG23, SEG24, SEG25, SEG26, SEG27, SEG28, SEG29, SEG30, SEG31, SEG32, SEG33, SEG34, SEG35, SEG36, SEG37, SEG38, SEG39, SEG40, SEG41, SEG42, SEG43, SEG44, SEG45, SEG46, SEG47, SEG48, SEG49, SEG50, SEG51, SEG52, SEG53, SEG54, and SEG55 are all checked.
- Clock setting:** Clock source is "FIL", Frequency divider is "FIL/2^7", and Frame frequency is "64,000 Hz".

Callouts in the image indicate the following settings:

- "Set to 'Capacitor split method for the VDD reference'" points to the driving voltage generator method.
- "Seto to 'FIL'" points to the clock source.
- "Set to 'FIL/2^7'" points to the frequency divider.

Figure 6.10 and Figure 6.11 show the settings of PORT components (Config_PORT).

Figure 6.10 PORT Components (Config_PORT) Settings

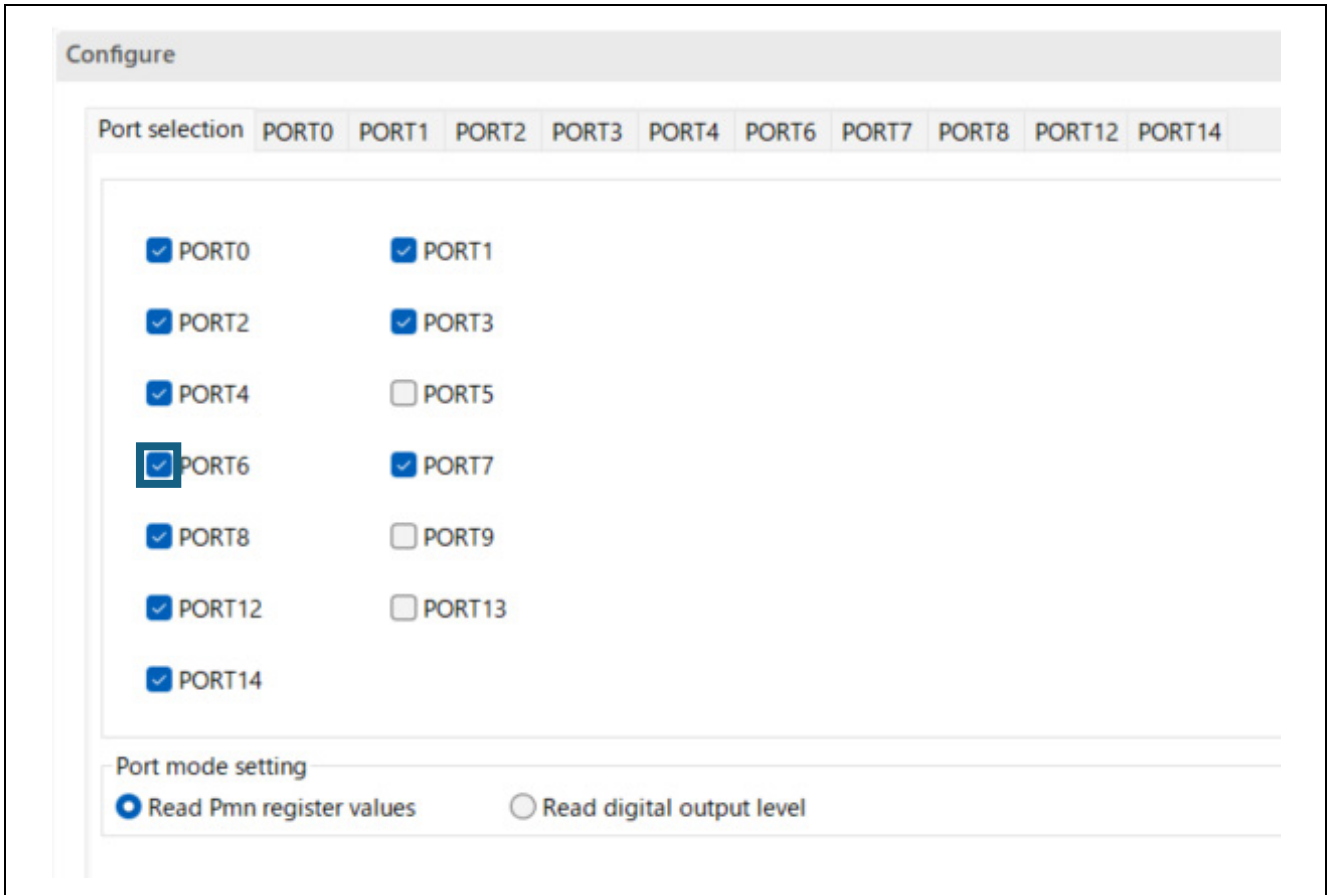


Figure 6.11 PORT6 Settings

The screenshot shows a configuration window titled "Configure" with a tab for "PORT6". A note at the top states: "Input buffer OFF" is effective when the pin is used for a port function or an alternative function, or the pin is not used. Please make sure that other peripherals are not using the alternative input function before selecting "Input buffer OFF".

Below the note, there are radio buttons for "Apply to all" (unchecked) and "Unused" (selected). A row of checkboxes includes: In, Out, Output current, Pull-up, TTL buffer, Input buffer OFF, N-ch, Output 1, Output ELCL output signal, Output current, and Hi-Z (dropdown).

Individual pin settings for P60 through P67 are listed below:

- P60:** In, Out (selected), Output current, Output 1, Output ELCL output signal, Output current, Hi-Z
- P61:** In, Out (selected), Output current, Output 1, Output ELCL output signal, Output current, Hi-Z
- P62:** In, Out (selected), Output current, Output 1, Output current, Hi-Z
- P63:** In, Out (selected), Output current, Output 1, Output current, Hi-Z
- P64:** In, Out (selected), Pull-up, TTL buffer, Input buffer OFF, N-ch, Output 1 (checked)
- P65:** In, Out (selected), Pull-up, TTL buffer, Input buffer OFF, N-ch, Output 1 (checked)
- P66:** In, Out (selected), Pull-up, TTL buffer, Input buffer OFF, N-ch, Output 1
- P67:** In, Out (selected), Pull-up, Output 1

Note: Only P64 and P65 are specified as LED ports in this document. Other ports are set to prevent unnecessary current consumption caused by the floating state. Settings to prevent unnecessary current consumption by ports floating are applied to ports other than these. Refer to "2.3 Connection of Unused Pins" in RL78/L23 User's Manual: Hardware (R01UH1082) for details on how to properly handle the application's unused ports and design your application to meet the electric characteristics.

Figure 6.12 shows the CTSU driver (r_ctsu) settings

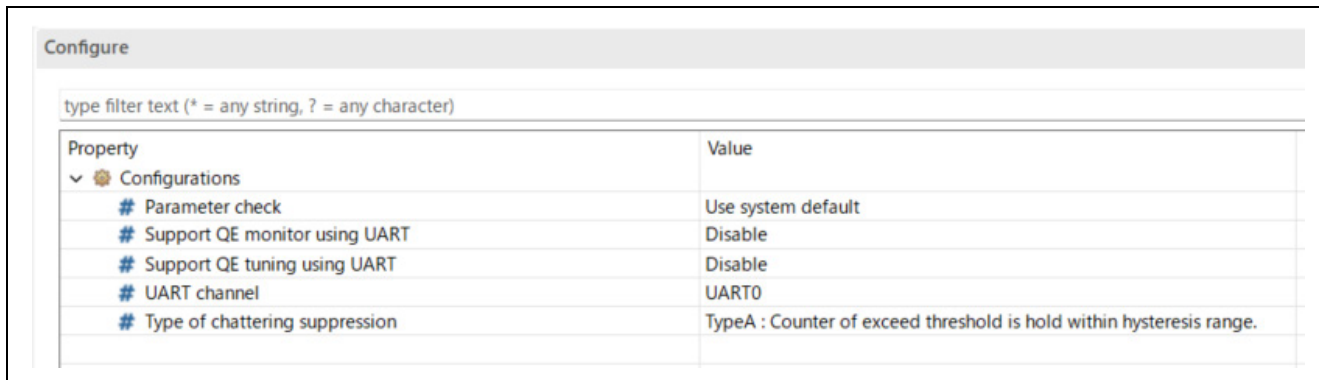
Figure 6.12 CTSU Driver (r_ctsu) Settings

The screenshot shows the 'Configure' window for the CTSU driver (r_ctsu). The window is divided into two main sections: 'Configurations' and 'Resources'. The 'Configurations' section lists various parameters and their values. The 'Resources' section lists the CTSU pins and their usage status. Several values are highlighted with blue boxes.

Property	Value
Configurations	
# Parameter check	Use system default
# Data transfer of INTCTSUWR and INTCTSURD	Interrupt handler
# DTC setting	Setting in r_ctsu
# Select auto judgement	Disable
# Data storage address setting for CTSUWR	0xFF300
# Variable address setting for g_ctsu_self_raw.	0xFF400
# Variable address setting for g_ctsu_mutual_raw	0xFF500
# Data storage address setting for CTSUAJTHR.	0xFF600
# Data storage address setting for CTSUAJMMAR.	0xFF700
# Data storage address setting for CTSUAJBLACT.	0xFF800
# Data storage address setting for CTSUAJBLAR.	0xFF900
# Data storage address setting for CTSUAJRR.	0xFFA00
# Data storage address setting for CTSUMCACT1.	0xFFB00
# Data storage address setting for CTSUMCACT2.	0xFFC00
# Auto-judgment function in Snooze mode using SMS	Disable
# Data storage address setting for CTSURD	0xFF500
# Data storage address setting for CTSUWR	0xFF800
# Interrupt level for INTCTSUWR	Level 2
# Interrupt level for INTCTSURD	Level 2
# Interrupt level for INTCTSUFN	Level 2
# Output port number for external trigger	PORT14
# Bit number for external trigger output	BIT0
# Interrupt port number for external trigger	INTP1
Resources	
CTSU	
TS00 Pin	Used
TS01 Pin	Used
TS02 Pin	Used
TS03 Pin	Used
TS04 Pin	Used
TS05 Pin	Used
TS06 Pin	Used
TS07 Pin	Used
TS08 Pin	Used
TS09 Pin	Used
TS10 Pin	Used
TS11 Pin	Used
TS12 Pin	Used
TS13 Pin	Used
TS14 Pin	Used
TS15 Pin	Used
TS16 Pin	Used
TS17 Pin	Used
TS18 Pin	Used
TS19 Pin	Used
TS20 Pin	Used
TS21 Pin	Used
TS22 Pin	Used
TS23 Pin	Used
TS24 Pin	Used
TS25 Pin	Used
TS26 Pin	Used
TS27 Pin	Used
TS28 Pin	Used
TS29 Pin	Used
TS30 Pin	Used
TS31 Pin	Used
TS32 Pin	Used
TS33 Pin	Used
TS34 Pin	Used
TS35 Pin	Used

Figure 6.13 shows the settings of the TOUCH driver (rm_touch).

Figure 6.13 TOUCH Driver (rm_touch) Settings



The screenshot displays the configuration interface for the TOUCH driver. At the top, there is a search filter labeled 'type filter text (* = any string, ? = any character)'. Below this is a table with two columns: 'Property' and 'Value'. The table lists several configuration options under a 'Configurations' section.

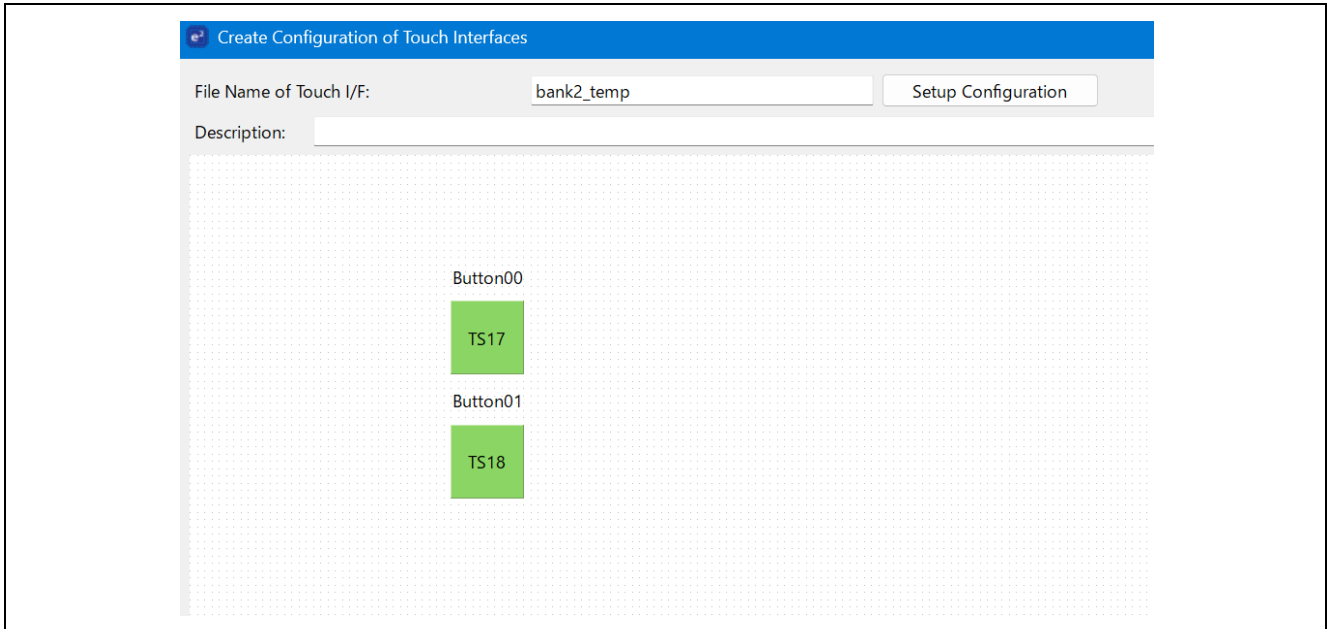
Property	Value
Configurations	
# Parameter check	Use system default
# Support QE monitor using UART	Disable
# Support QE tuning using UART	Disable
# UART channel	UART0
# Type of chattering suppression	TypeA : Counter of exceed threshold is hold within hysteresis range.

6.4 Capacitive Touch Setting

6.4.1 Touch Interface Configuration

Figure 6.14 shows the touch interface configuration. TS17 and TS18 are measured with the self-capacitance method.

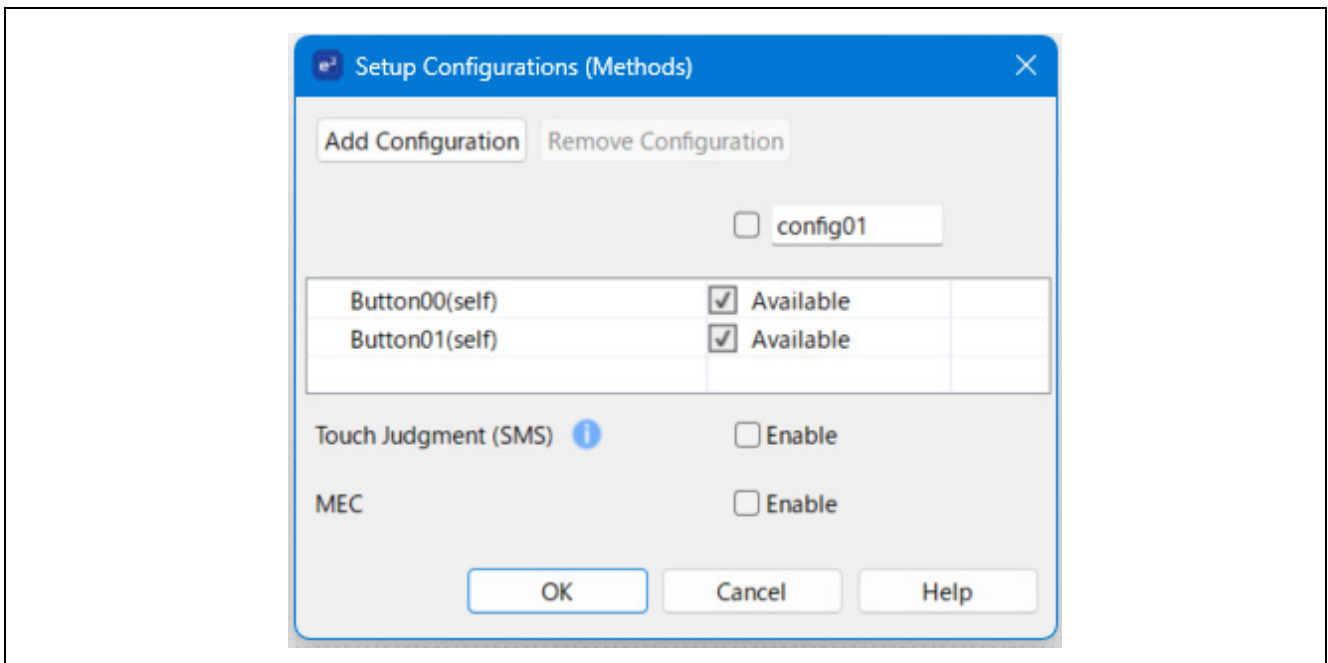
Figure 6.14 Touch Interface Configuration



6.4.2 Configuration (Methods) Settings

Figure 6.15 shows the touch interface configuration (methods) settings.

Figure 6.15 Configuration (Methods) Settings



6.4.3 Tuning Results

Figure 6.16 shows the QE tuning results of the touch interface. This sample code operates with the setting values shown in the figure below.

The tuning results depend on the operating environment when QE tuning is performed. Thus, if QE tuning is performed again, these values may change.

Figure 6.16 QE Tuning Results

Tuning		Gesture						
Touch I/F Configuration: bank2_temp								
Method	Kind	Name	Touch Sensor	Parasitic Capacitance[pF]	Sensor Drive Pulse Frequency[MHz]	Threshold	Scan Time[ms]	Overflow
config01	Button(self)	Button00	TS17	7.444	5.469	3442	0.576	None
config01	Button(self)	Button01	TS18	7.118	5.667	3546	0.576	None

6.5 Constants

Table 6-3 lists the constants used in the sample code.

Table 6-3 Constants Used in the Sample Code

Constant Name	Setting Value	Contents
MAX_VALUE	30	Maximum value of temperature display
MIN_VALUE	12	Minimum value of temperature display
DEFAULT_VALUE	20	Default setting value of temperature display
MAX_VALUE_CONTUNUOUS	29	Maximum count value of continuous touch on the touch button
MIN_VALUE_CONTUNUOUS	13	Minimum count value of continuous touch on the touch button
VALUE_SETTING_FINISH	5	Non-touch period (sec)
LONG_PRESS_SEC	3	Long press detection time (sec)
COUNTINUOUS_START_NUM	3	Continuous touch detection count

6.6 Variables

Table 6-4 and Table 6-5 lists the static variables.

Table 6-4 Static Variables Used in the Sample Code (1/2)

Type	Variable Name	Contents	Function Used
uint8_t	g_show_segdata[40][4]	Array to store characters for display on the LCD	r_lcd_show
uint8_t	g_digit_segdata[8][4]	Array to store the LCD display digits	r_lcd_show
uint8_t	g_touch_button_flag	Flag to enable the touch function	qe_touch_main r_rtc_long_press_callback r_userswitch_callback
uint8_t	g_out_of_range_main_flag	When set to 1, indicates that the temperature data is out of range (12 or less, or 30 or more) and that the main system clock is running.	qe_touch_main r_no_touch r_rtc_long_press_callback r_touch_both_buttons r_touch_normal_mode r_value_continuous r_value_out_of_range
uint8_t	s_lcd_value	LCD display value variable	r_touch_minus_value r_touch_plus_value r_value_continuous r_value_out_of_range r_value_show
uint8_t	s_100ms_count	Variable to count wait time in 100ms intervals	r_delay_100ms r_tau0_3_delay_callback
uint8_t	s_prev_button1_flag	Flag to store the previous state of touch button 1	r_no_touch r_touch_both_buttons r_touch_plus_value
uint8_t	s_prev_button2_flag	Flag to store the previous state of touch button 2	r_no_touch r_touch_both_buttons r_touch_minus_value
uint8_t	s_demo_change_flag	Flag to switch demos	r_change_demo r_rtc_long_press_callback
uint8_t	s_demo_change_count_flag	Flag to start a counter for determining changes in the demo	r_rtc_long_press_callback r_userswitch_callback r_userswitch_release
uint8_t	s_demo_change_count	Flag that counts the length of time the user switch is held down	r_rtc_long_press_callback r_userswitch_callback
uint8_t	s_standby_count_flag	Flag to start count until transition to standby state.	r_rtc_long_press_callback r_userswitch_callback r_userswitch_release
uint8_t	s_standby_count	Variable to count until transition to standby state.	r_rtc_long_press_callback r_touch_both_buttons r_touch_minus_value r_touch_plus_value r_userswitch_callback

Table 6-5 Static Variables Used in the Sample Code (2/2)

Type	Variable Name	Contents	Function Used
uint8_t	s_continuous _touch_flag	Flag to determine interval of continuous touch	r_no_touch r_tau0_5_continuous_callback r_touch_both_buttons r_touch_minus_value r_touch_plus_value
uint8_t	s_continuous _touch_count	Variable to count continuous touch star	r_tau0_5_continuous_callback r_touch_minus_value r_touch_plus_value
uint8_t	s_userswitch _on_off_flag	Flag to determine ON/OFF state of the user switch	r_userswitch_callback r_userswitch_release

6.7 Functions

Table 6-6 lists the functions used in the sample code for BANK2 (temp.c).

Table 6-6 Functions Used in the Sample Code

Function Name	Outline
void r_bank2_temp_start(void)	BANK2 temp start processing
void r_change_demo(void)	Demo switch processing
void r_userswitch_release(void);	User switch detection processing
void r_userswitch_callback(void)	Processing for user switch press
void r_rtc_long_press_callback(void)	Long press operation of user switch
void r_tau0_3_delay_callback(void)	Callback for TAU0_3 interrupt
void r_tau0_5_continuous_callback(void)	Callback for TAU0_5 interrupt
void r_touch_plus_value(void)	Callback for touch button 1
void r_touch_minus_value(void)	Callback for touch button 2
void r_touch_both_buttons(void)	Processing for simultaneous touch detection of touch buttons 1 and 2
void r_no_touch(void)	Touch release detection processing
static void r_lcd_show(uint8_t value, uint8_t digit)	Display of LCD values
static void r_value_show(void)	Display of current set temperature
static void r_array_show(uint8_t* array, uint8_t num, uint8_t delay)	Sequential display processing of array data on LCD
static void r_clear_show(void)	Clearing of LCD display
static void r_delay_100ms(uint8_t num)	Delay processing
static void r_value_out_of_range(void)	Out-of-range temperature display processing
static void r_value_continuous(void)	Temperature check during continuous touch detection of a touch button
static void r_bank_swap(void)	Bank swap processing

6.8 Function Specifications

The following tables list the function specifications for BANK2 (temp.c) sample code.

r_bank2_temp_start

Outline	BANK2 temp start processing
Header	temp.h
Declaration	void r_bank2_temp_start(void)
Description	Displays "RL78/L23" and "BANK2 T" on the LCD when the demo starts.
Arguments	None
Return Value	None
Remarks	None

r_change_demo

Outline	Demo switch processing
Header	temp.h
Declaration	void r_change_demo(void)
Description	Switching is performed by detecting a long press of the user switch.
Arguments	None
Return Value	None
Remarks	None

r_userswitch_release

Outline	User switch detection processing
Header	temp.h
Declaration	void r_userswitch_release(void)
Description	Performs processing when the user switch is released.
Arguments	None
Return Value	None
Remarks	None

void r_userswitch_callback (void);

Outline	Processing for user switch press
Header	temp.h
Declaration	void r_rtc_long_press_callback(void)
Description	Enables touch button with a short press.
Arguments	None
Return Value	None
Remarks	None

r_rtc_long_press_callback

Outline	Long press operation of user switch
Header	temp.h
Declaration	void r_rtc_long_press_callback(void)
Description	Perform a long press count, and if it is a long press, set a flag to switch to "BANK1 C." Also, determine the interval for transitioning to STOP mode.
Arguments	None
Return Value	None
Remarks	None

r_tau0_3_delay_callback

Outline	Callback for TAU0_3 interrupt
Header	temp.h
Declaration	void r_tau0_3_delay_callback(void)
Description	Increments the delay count variable with the timer (TAU0 channel 3).
Arguments	None
Return Value	None
Remarks	None

r_tau0_5_continuous_callback

Outline	Callback for TAU0_5 interrupt
Header	temp.h
Declaration	void r_tau0_5_continuous_callback(void)
Description	Determines continuous touch on the touch button
Arguments	None
Return Value	None
Remarks	None

r_touch_plus_value

Outline	Callback for touch button 1
Header	temp.h
Declaration	void r_touch_plus_value(void)
Description	Adds 1 to the LCD display when touch detection of touch button 1 occurs.
Arguments	None
Return Value	None
Remarks	None

r_touch_minus_value

Outline	Callback for touch button 2
Header	temp.h
Declaration	void r_touch_minus_value(void)
Description	Adds 1 to the LCD display when touch detection of touch button 2 occurs.
Arguments	None
Return Value	None
Remarks	None

r_array_show

Outline	Sequential display processing of array data on LCD	
Header	None	
Declaration	static void r_array_show(uint8_t * array, uint8_t num, uint8_t delay)	
Description	Displays numerals and characters on the LCD that correspond to the numbers stored in the array.	
Arguments	uint8_t * array	Pointer to the value to be displayed
	uint8_t num	Number of elements to be displayed
	uint8_t delay	Wait time after each display (in 100ms intervals)
Return Value	None	
Remarks	None	

r_clear_show

Outline	Clearing of LCD display	
Header	None	
Declaration	static void r_clear_show(void)	
Description	Displays nothing on all 8 LCD digits and clears all displayed contents.	
Arguments	None	
Return Value	None	
Remarks	None	

r_delay_100ms

Outline	Delay processing	
Header	None	
Declaration	static void r_delay _100ms(uint8_t num)	
Description	Generates 100ms delay	
Arguments	uint8_t num	Wait time in 100ms intervals e.g. 300ms wait when num = 3
Return Value	None	
Remarks	None	

r_value_out_of_range

Outline	Out-of-range temperature display processing	
Header	None	
Declaration	static void r_value_out_of_range(void)	
Description	Determines if the value is out of range and performs processing accordingly.	
Arguments	None	
Return Value	None	
Remarks	None	

r_value_continuous

Outline	Temperature check during continuous touch detection of a touch button
Header	None
Declaration	static void r_value_continuous(void)
Description	Determines the upper/lower limit of continuous touch and performs processing accordingly.
Arguments	None
Return Value	None
Remarks	None

r_bank_swap

Outline	Bank swap processing
Header	None
Declaration	static uint8_t r_bank_swap(void)
Description	Perform bank swap processing.
Arguments	None
Return Value	Execution result status
	SAMPLE_ENUM_RET_STS_OK Successful completion
	SAMPLE_ENUM_RET_ERR_PARAMETER Parameter error
	SAMPLE_ENUM_RET_ERR_MODE_MISMATCHED Mode mismatched error
	SAMPLE_ENUM_RET_ERR_CONFIGURATION Configuration error
	SAMPLE_ENUM_RET_ERR_CHECK_WRITE_DATA Check write data error
	SAMPLE_ENUM_RET_ERR_CMD_ERASE Erase command error
	SAMPLE_ENUM_RET_ERR_CMD_WRITE Write command error
	SAMPLE_ENUM_RET_ERR_CMD_BLANKCHECK Blankcheck command error
	SAMPLE_ENUM_RET_ERR_CMD_SET_EXTRA_AREA Set extra area command (boot flag) error
Remarks	None

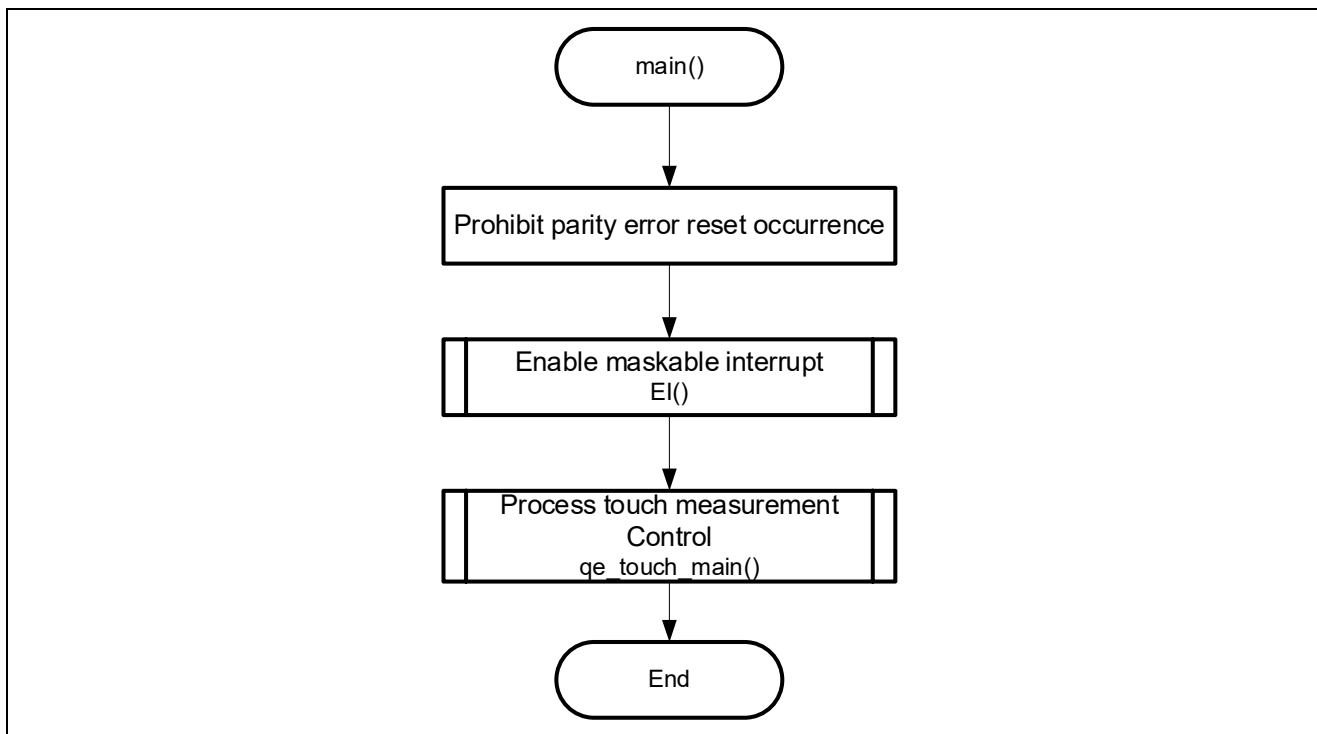
6.9 Flowchart

The flowchart of the main functions showing the flow of this sample code (BANK2) is shown below.

6.9.1 main Function

Figure 6.17 shows the main function flowchart.

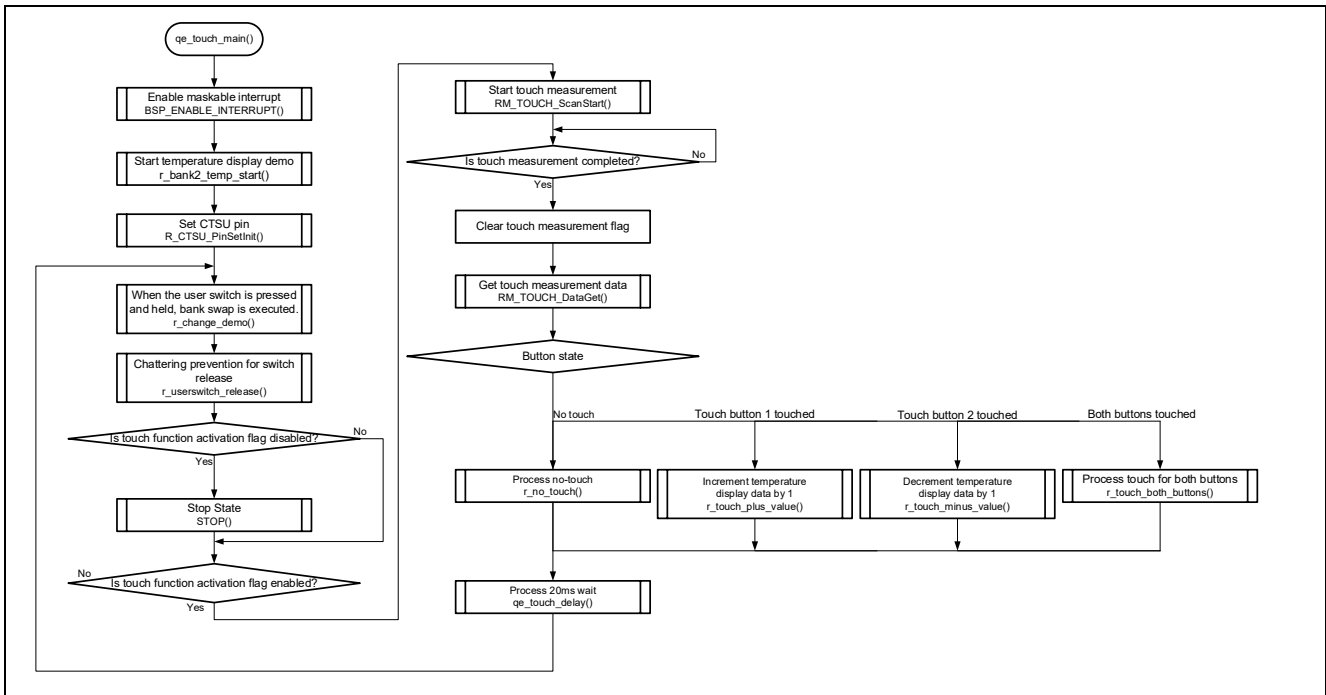
Figure 6.17 main Function Flowchart



6.9.2 qe_touch_main Function

Figure 6.18 shows the qe_touch_main function flowchart.

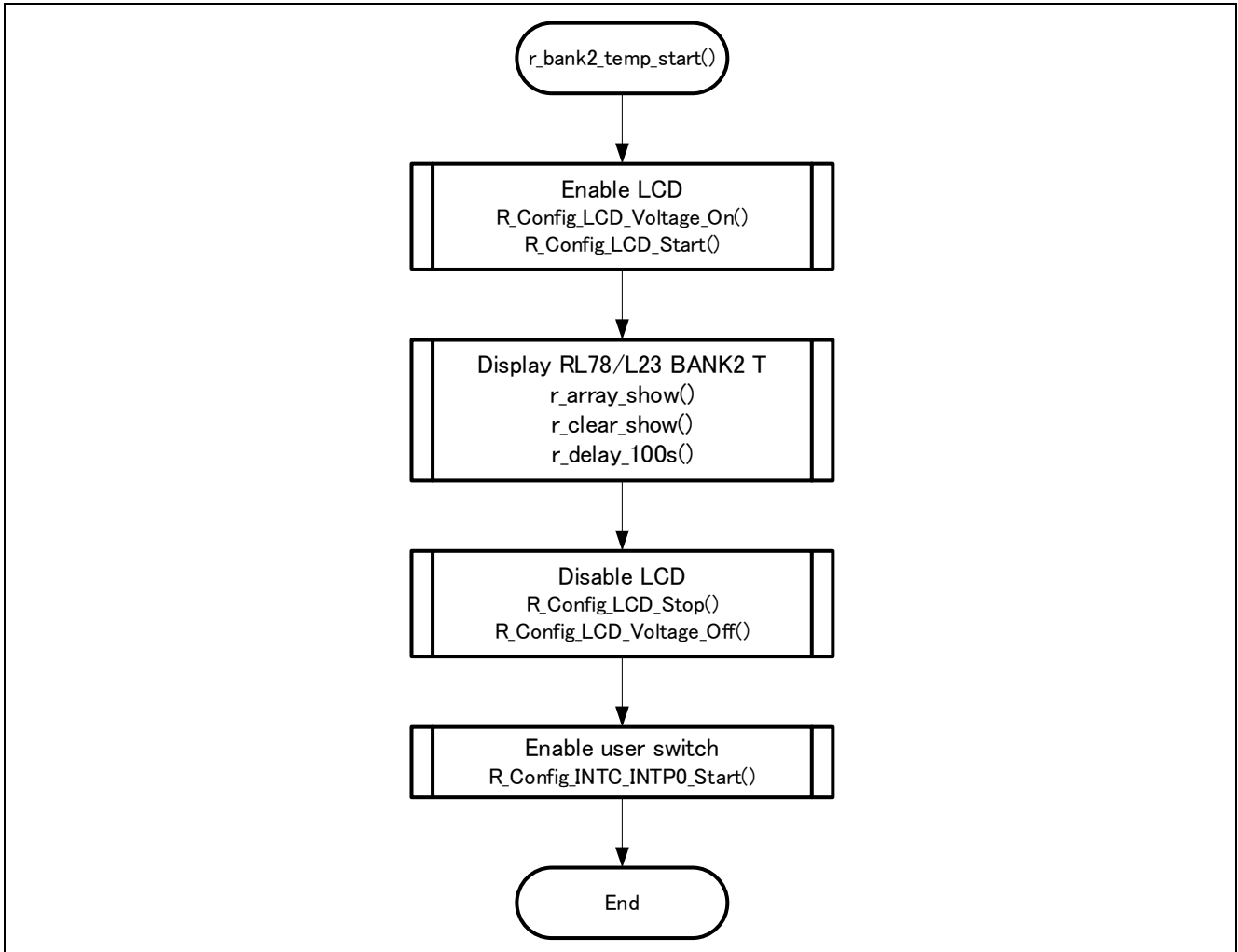
Figure 6.18 qe_touch_main Function Flowchart



6.9.3 r_bank2_temp_start Function

Figure 6.19 shows the r_bank2_temp_start function flowchart.

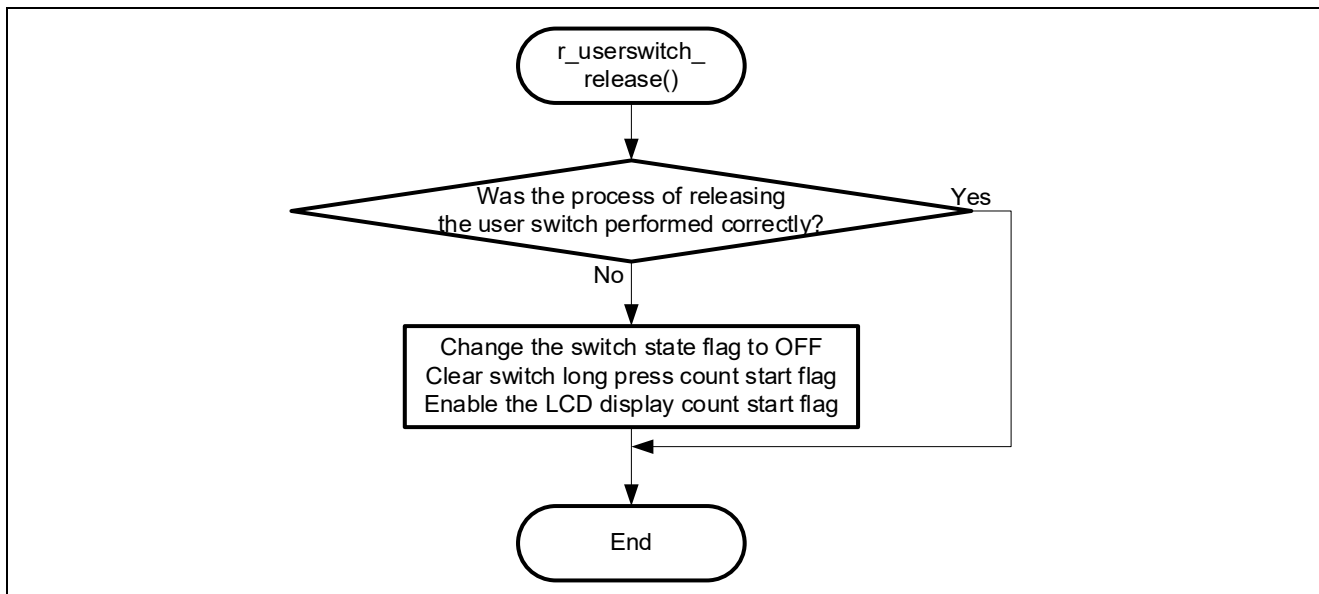
Figure 6.19 r_bank2_temp_start Function flowchart



6.9.4 r_userswitch_release Function

Figure 6.20 shows the r_userswitch_release function flowchart.

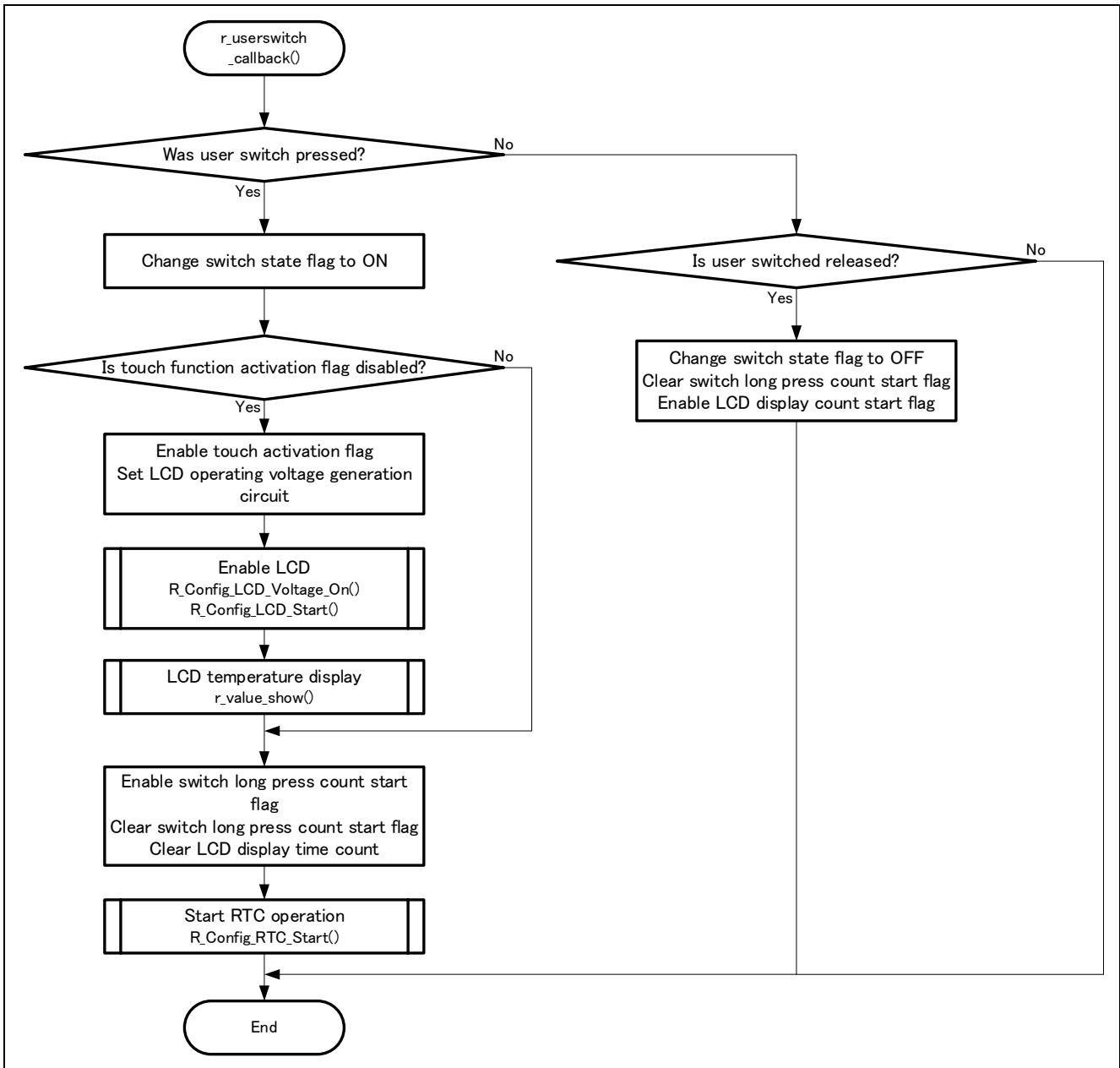
Figure 6.20 r_userswitch_release Function Flowchart



6.9.5 r_userswitch_callback Function

Figure 6.21 shows the r_userswitch_callback function flowchart.

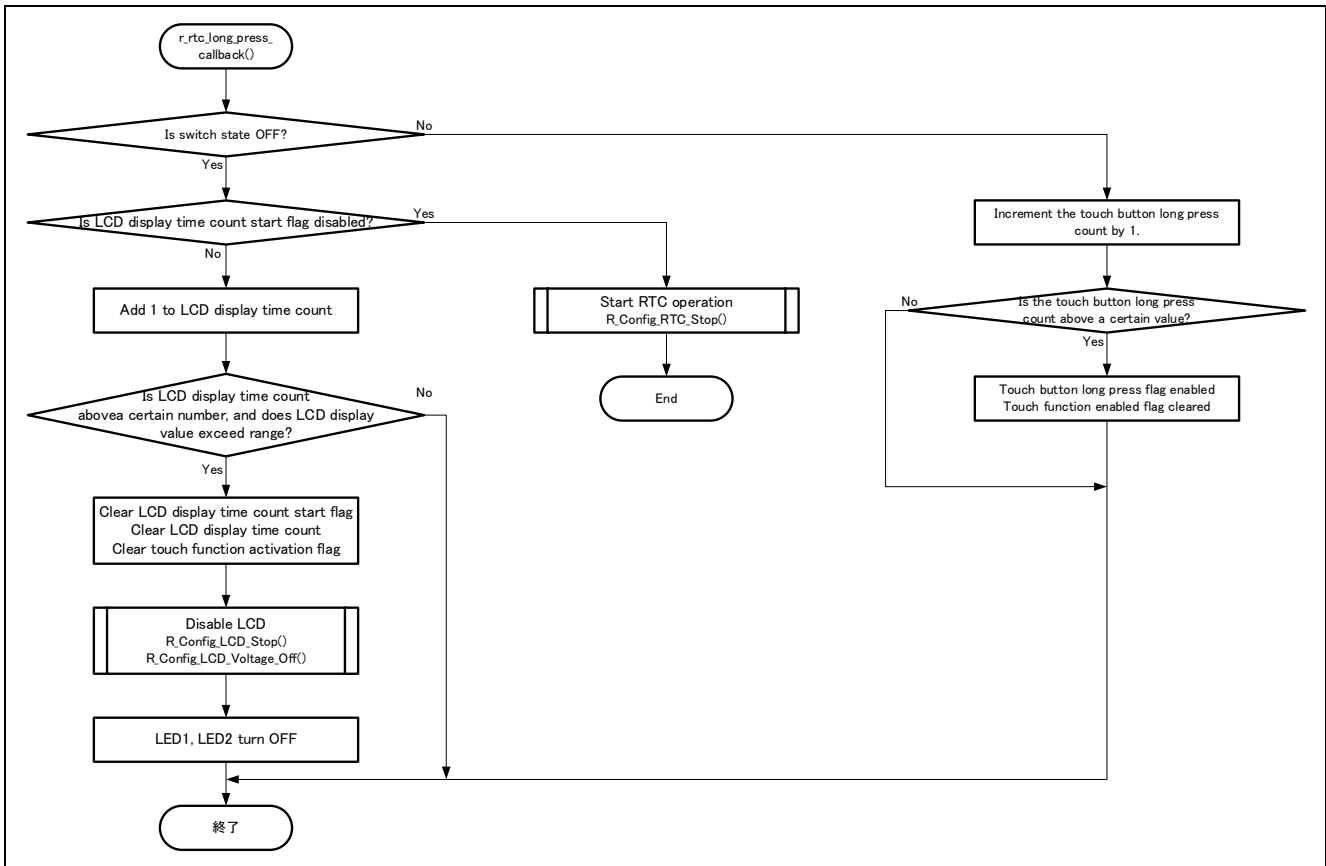
Figure 6.21 r_userswitch_callback Function Flowchart



6.9.6 r_rtc_long_press_callback Function

Figure 6.22 shows the r_rtc_long_press_callback function flowchart.

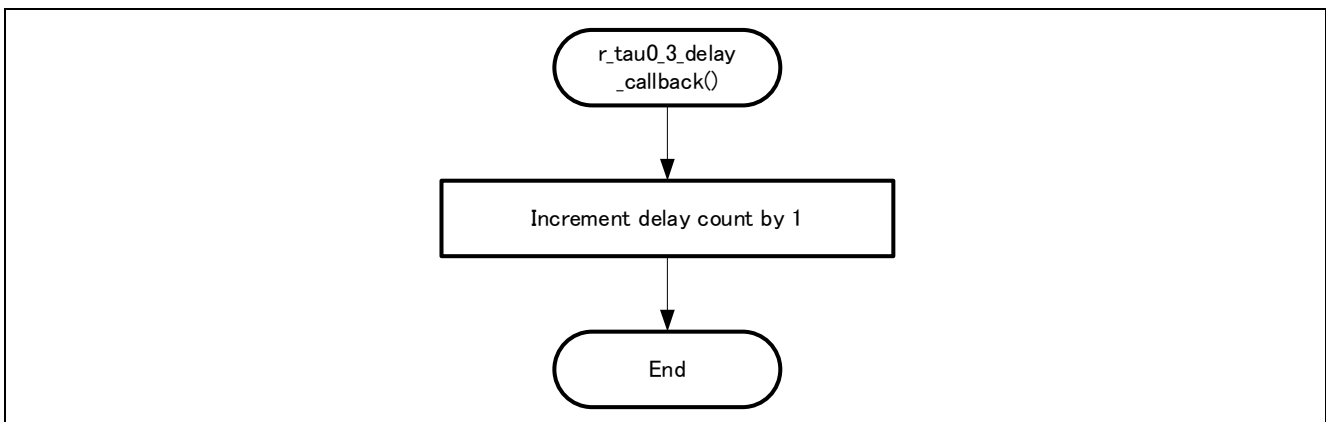
Figure 6.22 r_rtc_long_press_callback Function Flowchart



6.9.7 r_tau0_3_delay_callback Function

Figure 6.23 shows the r_tau0_3_delay_callback function flowchart.

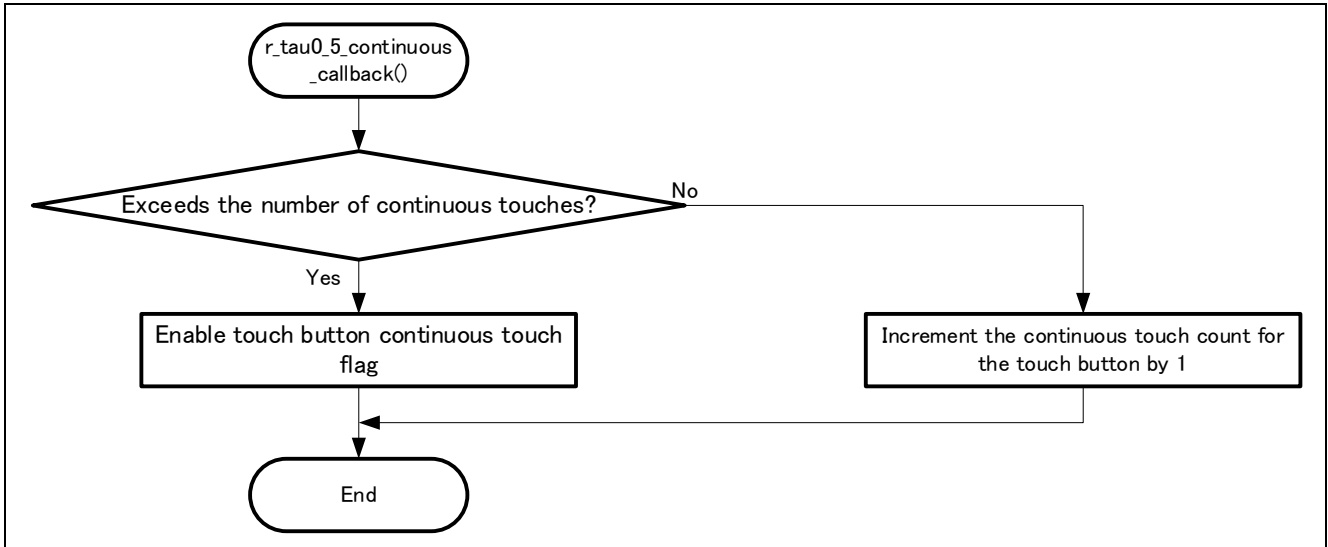
Figure 6.23 r_tau0_3_delay_callback Function Flowchart



6.9.8 r_tau0_5_continuous_callback Function

Figure 6.24 shows the r_tau0_5_continuous_callback Function Flowchart.

Figure 6.24 r_tau0_5_continuous_callback Function Flowchart



7. Importing the Project

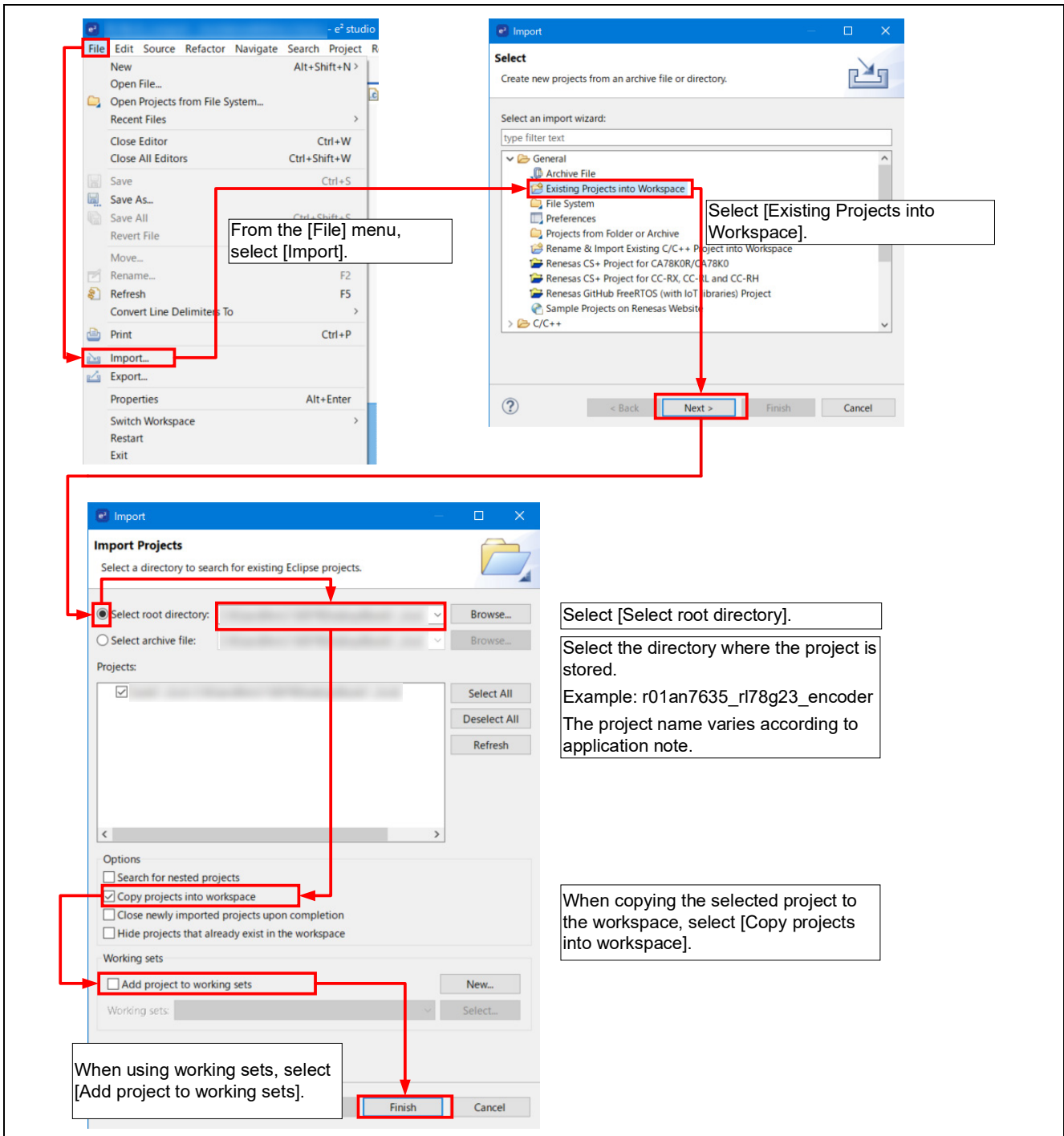
7.1 Importing with e² studio

When using the sample code with e² studio, use the following procedure to import the project in e² studio.

Note that spaces and symbols (especially \$, #, and %) cannot be included in e² studio project folder names or path to these folders.

(Dialog boxes shown in the figure may differ depending on the e² studio version used.)

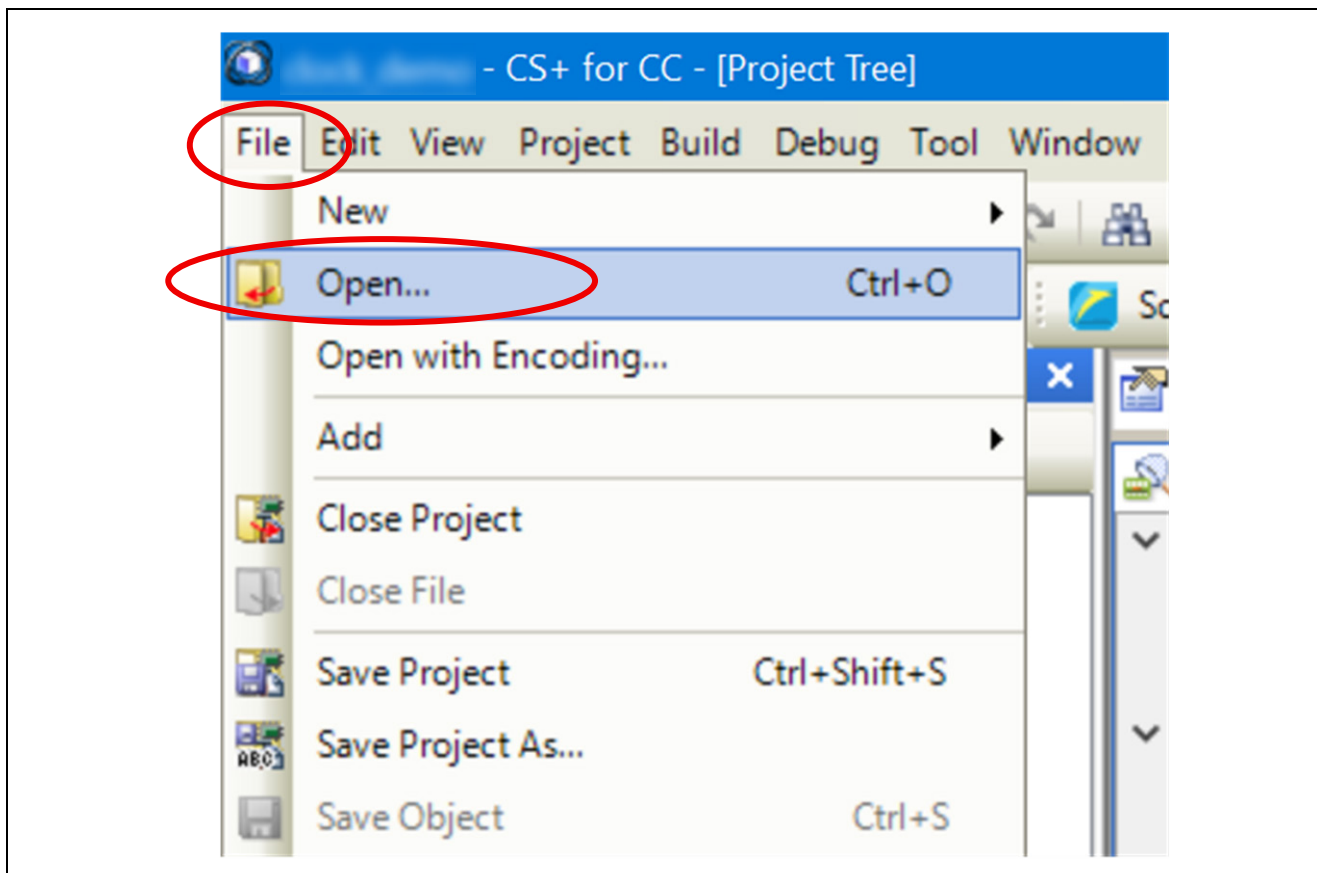
Figure 7.1 Importing the Project into e² studio



7.2 Importing with CS+

When using the sample code with CS+, open the mtpj file of the project by selecting [File] – [Open...] menu. (The image shown in the figure may differ depending on the CS+ version used.)

Figure 7.2 Importing the Project into CS+

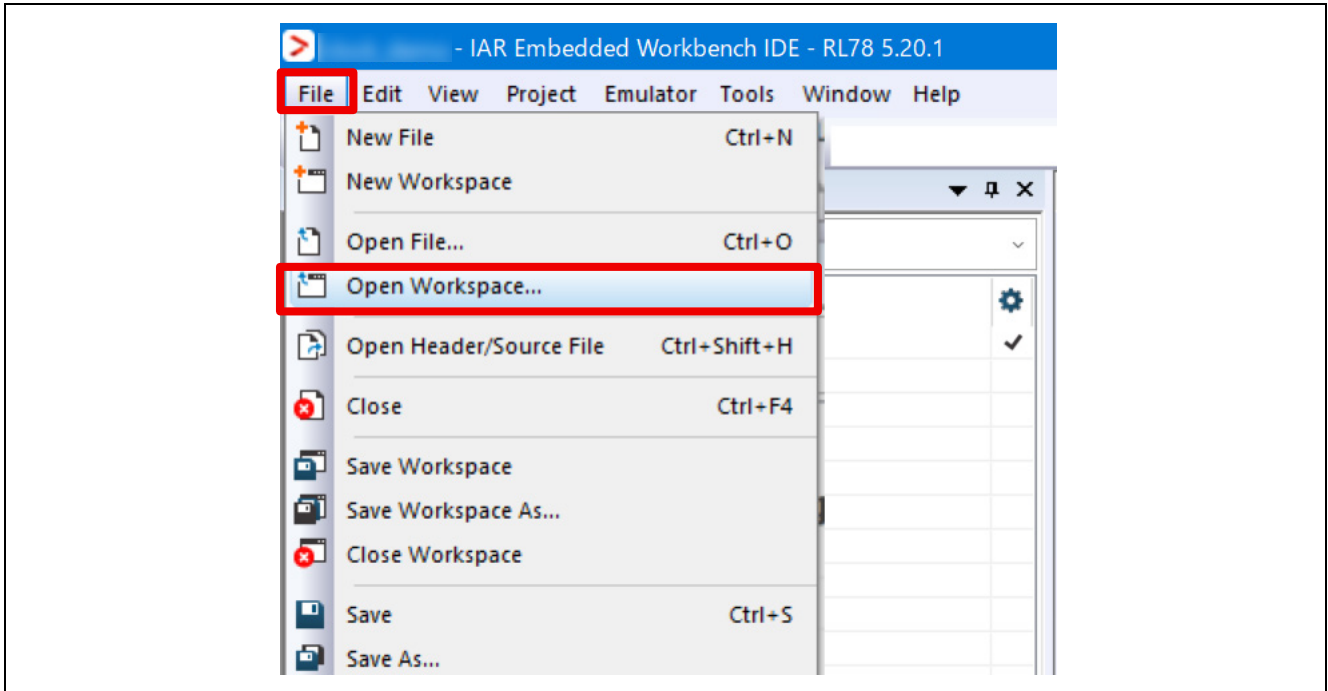


7.3 Importing with IAR

When using the sample code with IAR, open the eww file of the project by selecting [File] – [Open Workspace...] menu.

(The image shown in the figure may differ depending on the IAR version used.)

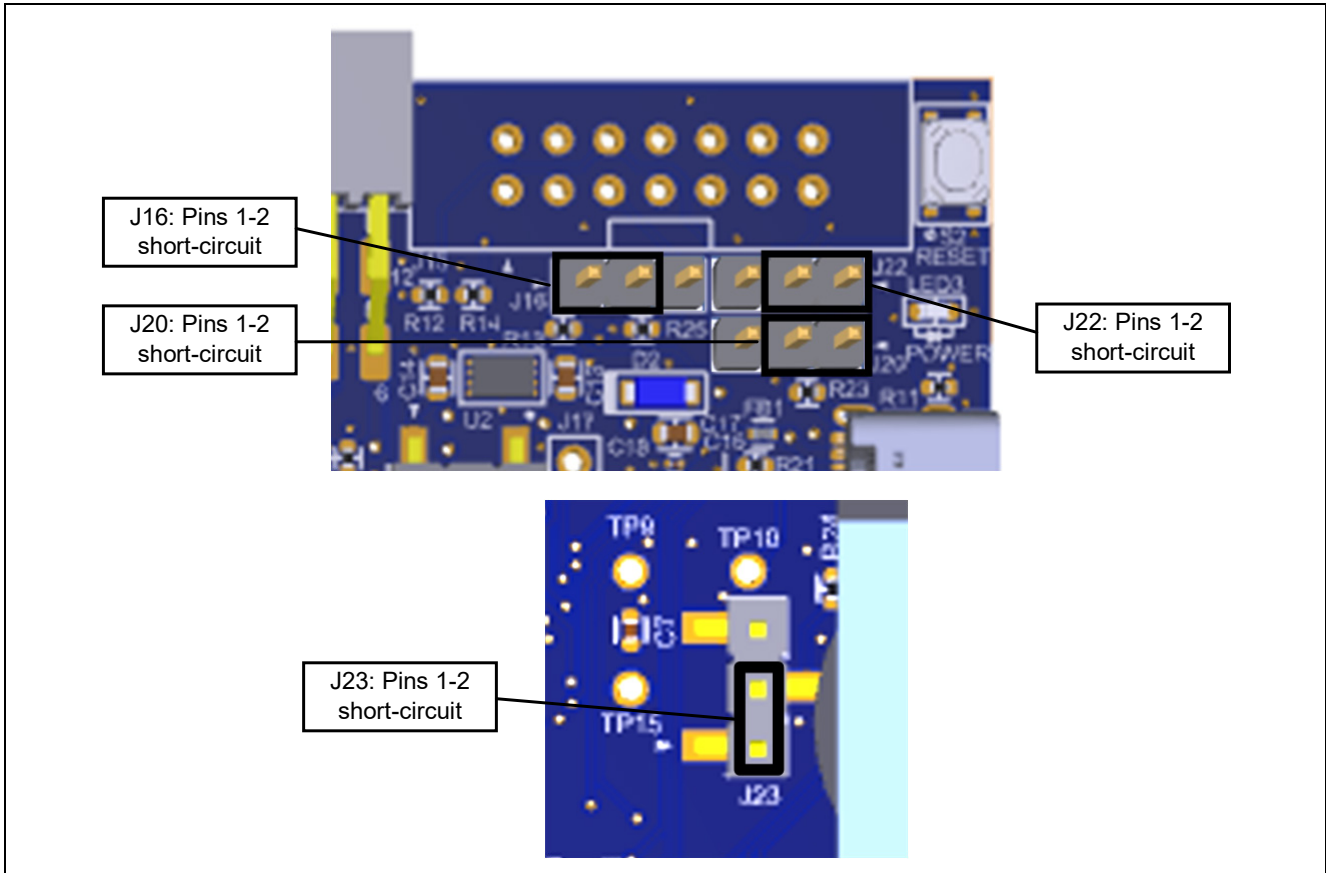
Figure 7.3 Importing the Project into IAR



8. Setting the Debug Tool

In the sample code, the USB-C port of RL78/L23 Fast Prototyping Board (RTK7RLL230S000001BJ) is used to perform debugging via the COM Port. When debugging via the COM port, make sure that jumper pins of RL78/L23 are configured as shown in Figure 8.1. For details, refer to 5.15 USB-to-Serial Converter and 5.21 Emulator Connector in RL78/L23 Fast Prototyping Board User's Manual (R20UT5544).

Figure 8.1 COM Port Setting When Using Debug

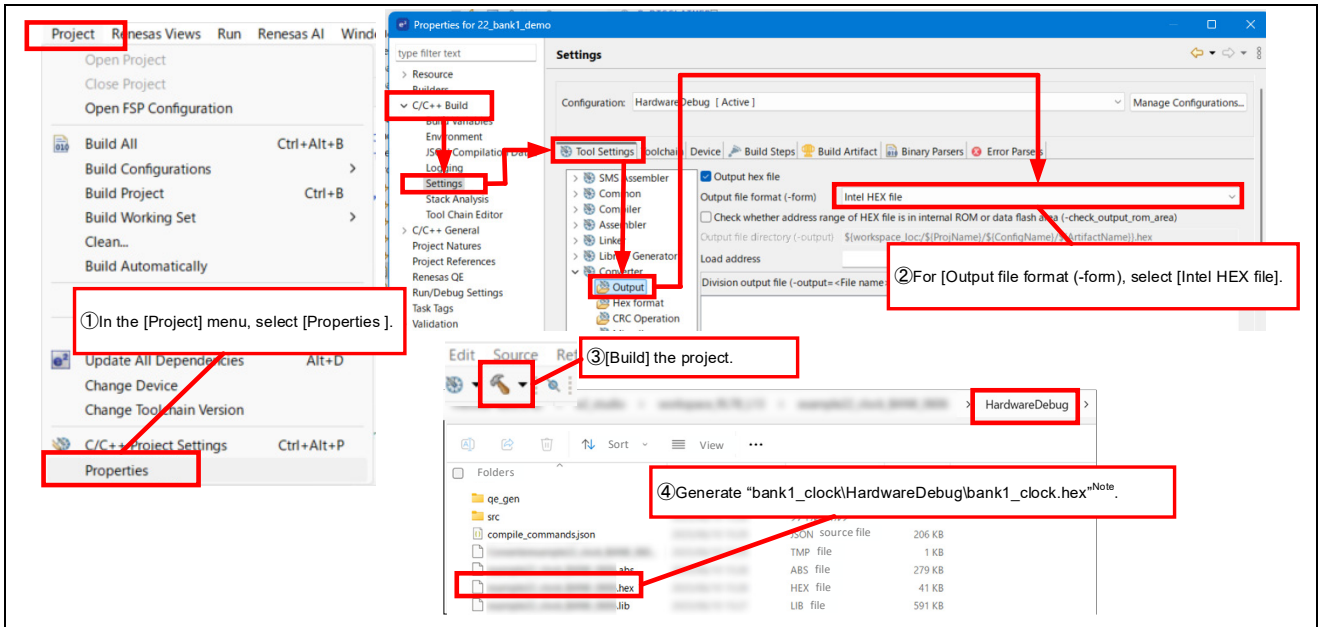


8.1 HEX File Generation Procedure in e² studio

The sample code is run by writing a HEX file using the Reness Flash Programmer.

Figure 8.2 shows the procedure for generating a HEX file for the sample code using the e² studio.

Figure 8.2 HEX File Generation Procedure (e² studio)



Precaution regarding Figure 8.2

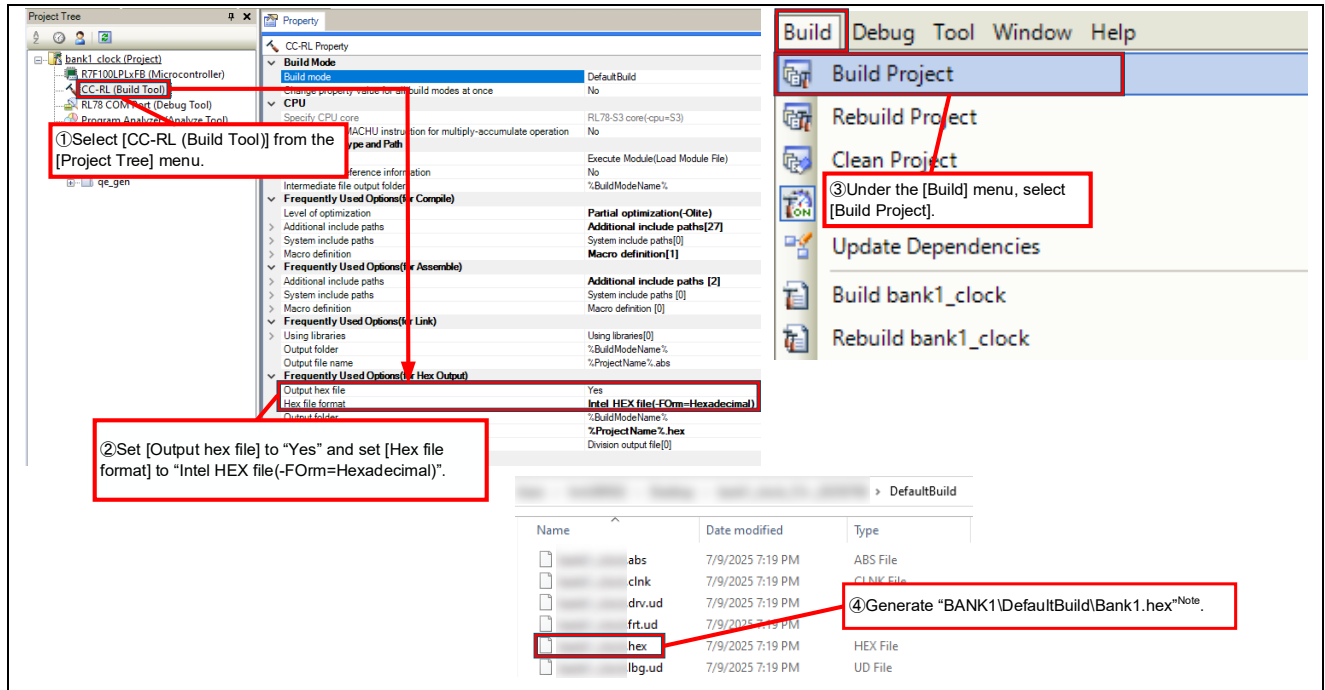
Note: The project name in the HEX file name varies according to application note.

8.2 HEX File Generation Procedure in CS+

The sample code is run by writing a HEX file using the Reness Flash Programmer.

Figure 8.3 shows the procedure for generating a HEX file for the sample code using CS+.

Figure 8.3 HEX File Generation Procedure (CS+)



Precaution regarding Figure 8.3

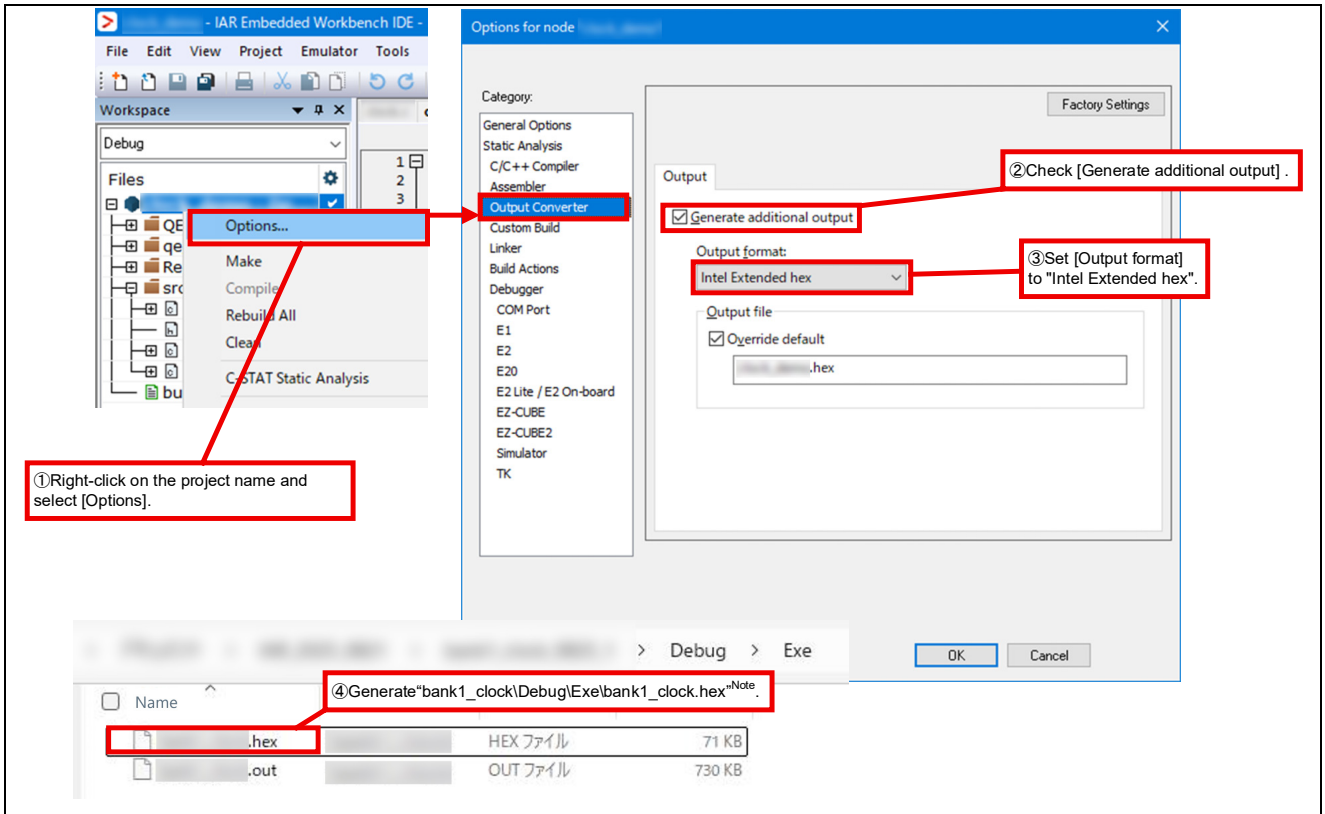
Note: The project name in the HEX file name varies according to application note.

8.3 HEX File Generation Procedure in IAR

The sample code is run by writing a HEX file using the Reness Flash Programmer.

Figure 8.4 shows the procedure for generating a HEX file for the sample code using IAR.

Figure 8.4 HEX File Generation Procedure (IAR)



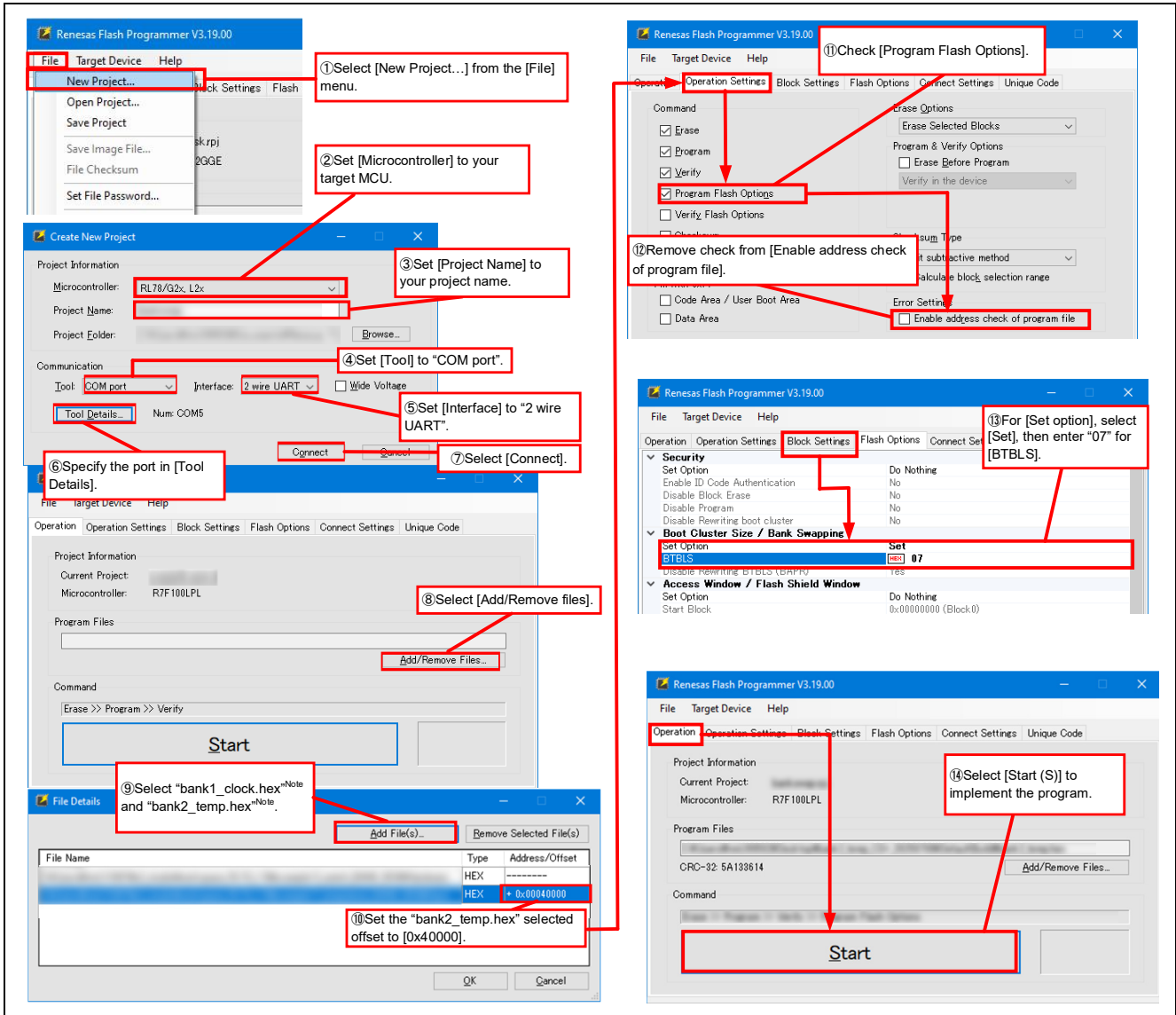
Precaution regarding Figure 8.4

Note: The project name in the HEX file name varies according to application note.

8.4 How to Program with the Renesas Flash Programmer

Download the Renesas Flash Programmer, connect the RL78/L23 board to your computer via the USB-C port, and then refer to the steps described in Figure 8.5 to write your program.

Figure 8.5 How to Program with the Renesas Flash Programmer



Precaution regarding Figure 8.5:

Note: The project name in the HEX file name varies according to application note.

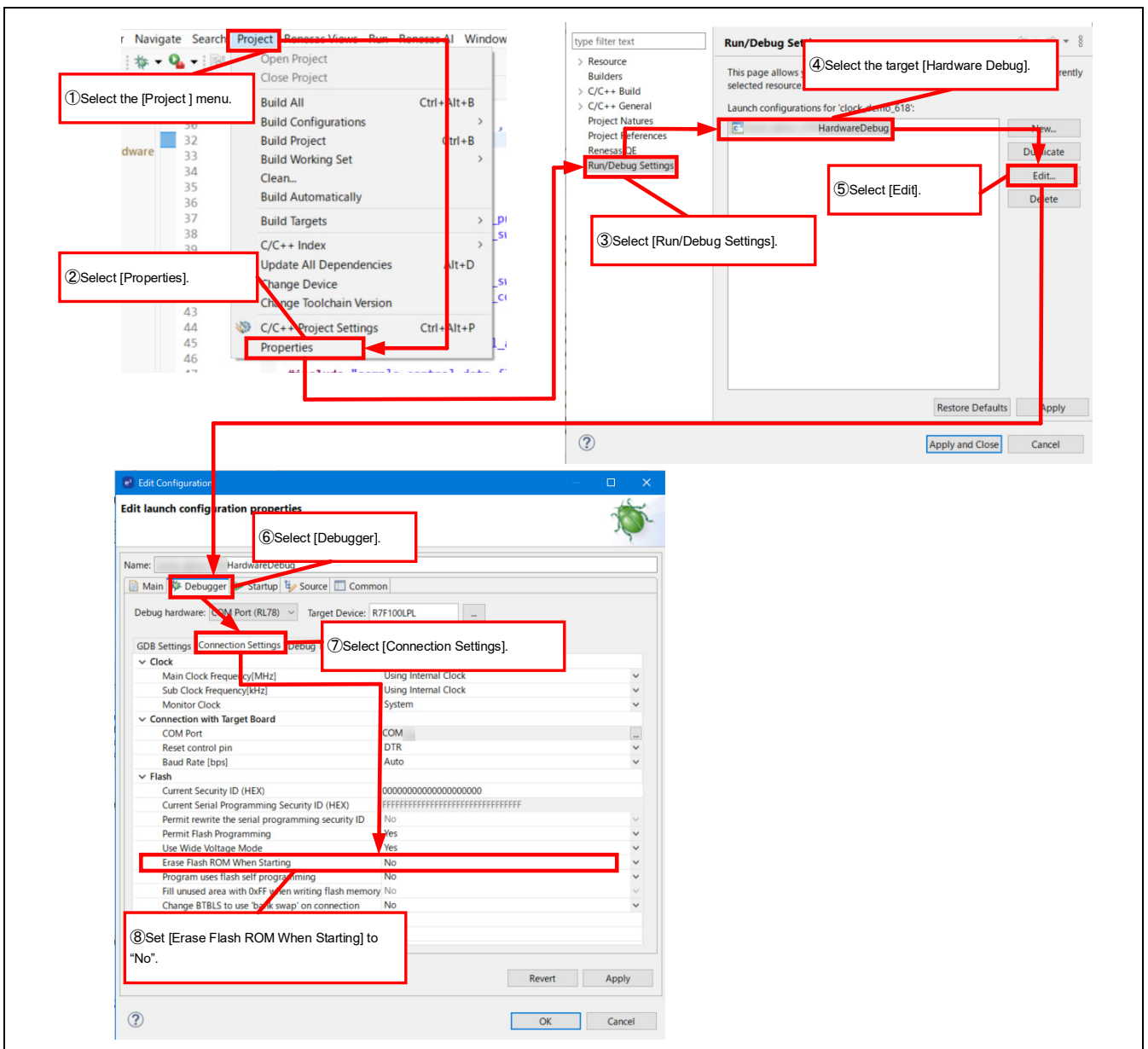
9. Precautions

9.1 Precautions regarding On-chip Debugger Connection after Bank Swap

When executing a bank swap, after Bank1 and Bank 2 have been switched, if the option bytes and on-chip security ID of the active bank have not been written, the on-chip debugger cannot be connected. Make sure you configure the integrated development environment (IDE) on both sides so that the program download during the bank swap control execution and debugger control does not erase the option bytes and on-chip security ID of the active bank.

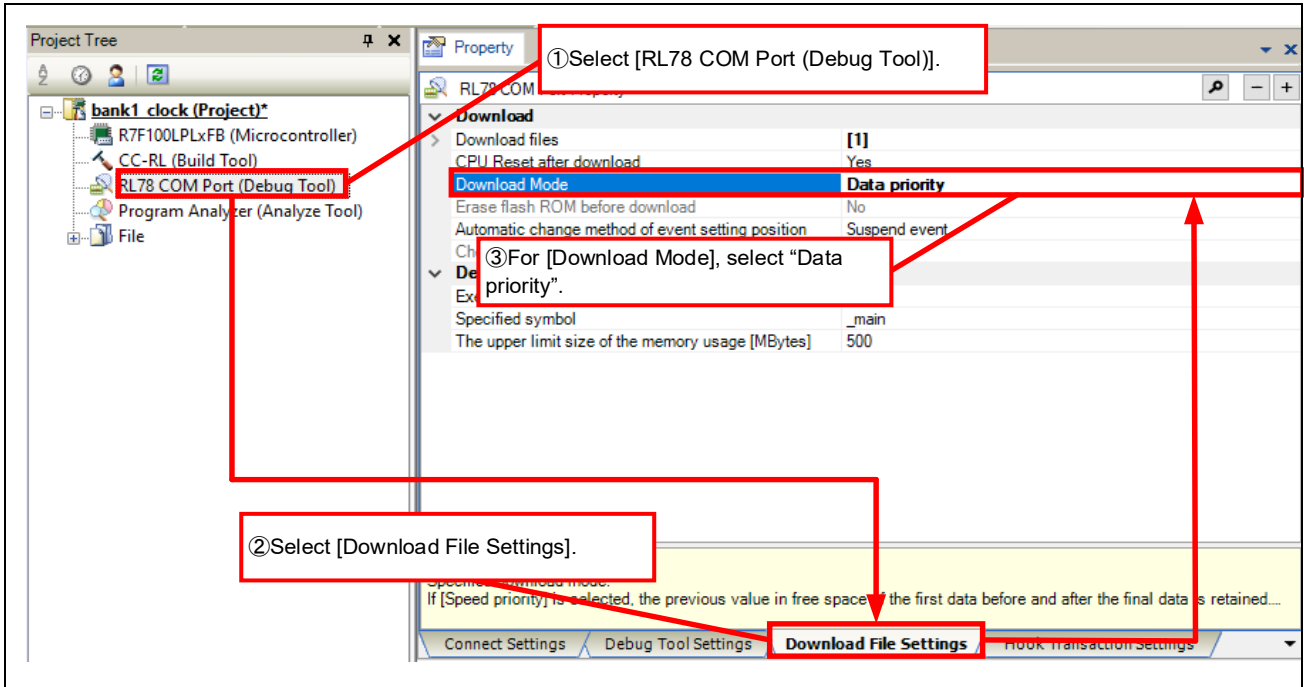
- Example of e² studio (CC-RL) setting: Select “Run/Debug Settings” from the project “Properties,” then edit the target “HardwareDebug” settings. After selecting the “Debugger” tab, select the “Connection Settings” tab, and set the “Erase Flash ROM at Start” under the “Flash” items to “No”. Figure 9.1 shows the example of the e² studio (CC-RL) setting.

Figure 9.1 Example of e² studio (CC-RL) Setting



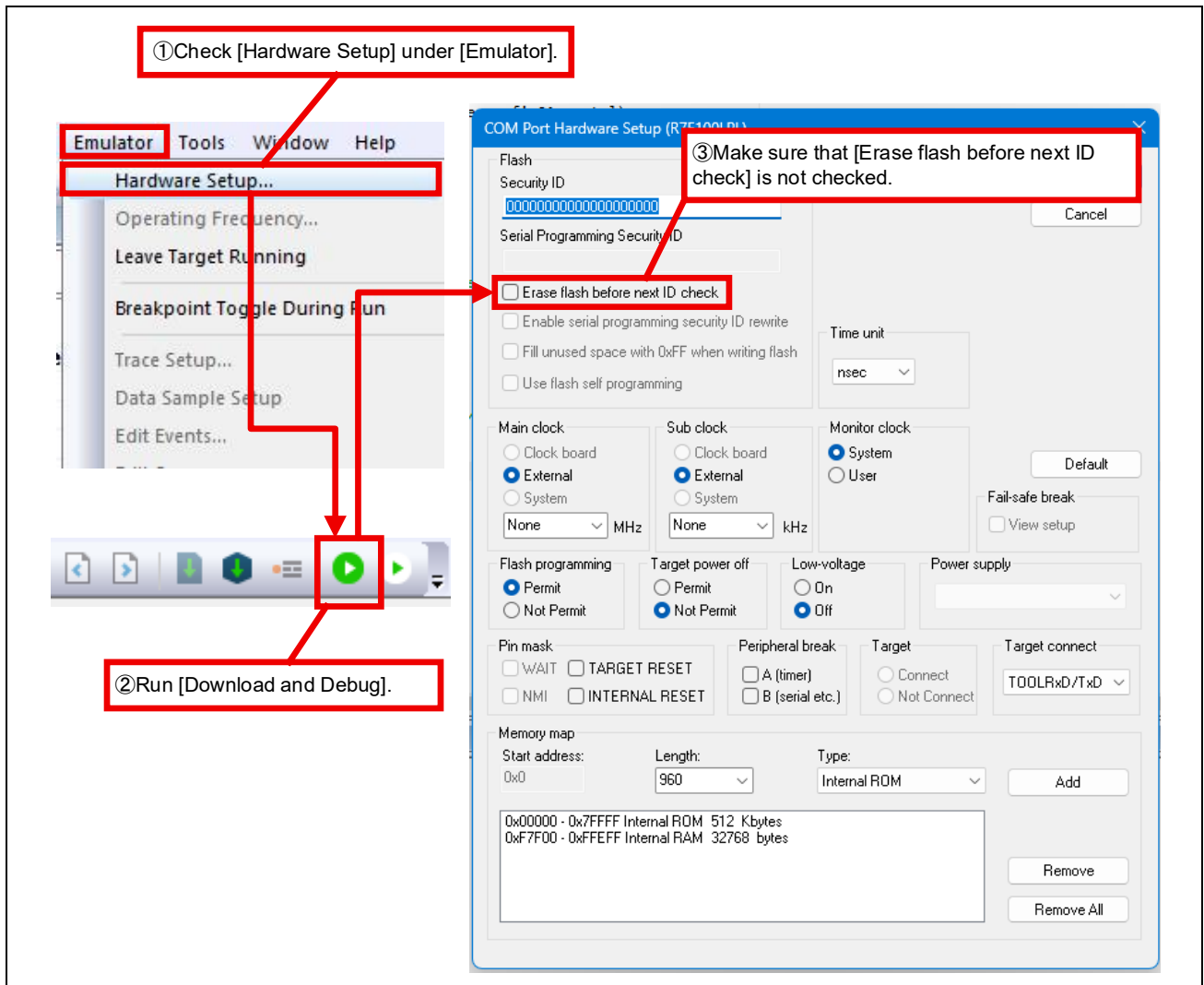
- Example of CS+ setting: Select the [Download File Settings] tab from the project's [RL78 COM Port (Debug Tool)]. Under [Download], go to [Download Mode], and select [Data priority]. Figure 9.2 shows an example of the CS+ setting.

Figure 9.2 Example of CS+ Setting



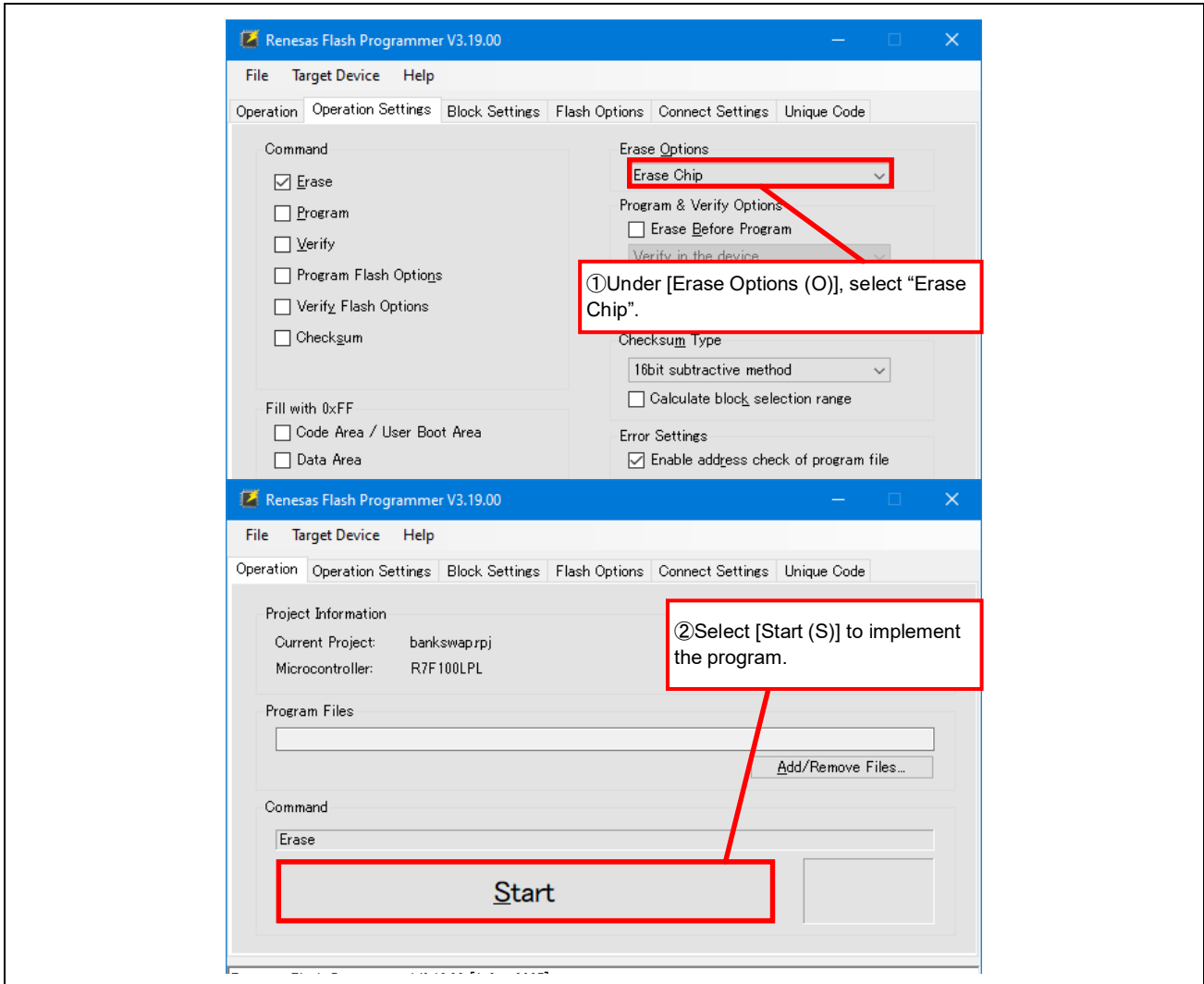
- Example of IAR setting: Remove the check mark to “Erase flash before next ID check” in an “Hardware Setup” window. Figure 9.3 shows an example of the IAR setting.

Figure 9.3 Example of IAR Setting



*If the option bytes and on-chip debug security ID are mistakenly erased from the active bank and a problem occurs with the debugger startup, execute a chip erase with the dedicated flash memory programmer (Renesas Flash Programmer in this app note), return the MCU to its initial state, and start the process from the beginning. Figure 9.4 shows the chip erase procedure.

Figure 9.4 Erase Chip with Dedicated Renesas Flash Programmer



10. Sample Code

Sample code can be downloaded from the Renesas Electronics website.

11. Reference Documents

RL78/L23 User's Manual: Hardware (R01UH1082)

RL78 Family User's Manual: Software (R01US0015)

RL78/L23 Fast Prototyping Board User's Manual (R20UT5544)

Capacitive Sensor Microcontrollers CTSU Capacitive Touch Introduction Guide (R30AN0424)

Renesas Flash Driver RL78 Type11 User's Manual (R20UT5539)

RL78 Smart Configurator User's Guide: e² studio (R20AN0579)

RL78 Smart Configurator User's Guide: CS+ (R20AN0580)

RL78 Smart Configurator User's Guide: IAREW (R20AN0581)

RL78/L23 LCD display (Clock demo) (R01AN7852)

RL78/L23 LCD display (Temperature display demo) (R01AN7853)

The latest information can be downloaded from the Renesas Electronics website.

Technical Update/Technical News

The latest information can be downloaded from the Renesas Electronics website.

REVISION HISTORY

Rev.	Date	Description	
		Page	Summary
1.00	Aug.18.25	-	First edition issued
1.10	Oct.24.25	6	Deleted the Item of 32-bit interval timer from Table 1-2. Deleted the description of SMS from the item of Capacitive Touch Sensing Unit from Table 1-2.
		9-10	2 Operation Confirmation Conditions Added description of the IAR environment.
		24	4.3 Capacitive Touch Sensing Unit Deleted description of SMS.
		30-31	Split Table 5-1 to create Table 5-2. Added the note about File Composition of IAR version.
		56	Modified flowchart in Figure 5-20.
		57	Modified flowchart in Figure 5-21.
		64	6.1 Operation Overview Deleted description of SMS.
		65	Modified state transition diagram in Figure 6.1.
		66,67	Split Table 6-1 to create Table 6-2. Added the note about File Composition of IAR version.
		70	6.3 Smart Configurator Settings Deleted following of setting of 32-bit interval timer.
		75	Changed CTSU driver settings in Figure 6.12.
		77	6.4 Capacitive Touch Setting Deleted setting procedures of external trigger.
		77	Unchecked the check box in Figure 6.15.
		78	Updated the values in Figure 6.16 with the re-tuned values.
		79	Changed variable name in Table 6-4.
		87	6.9 Flowchart Deleted flowcharts related to SMS.
		88	Modified flowchart in Figure 6.18.
		96	7.3 Importing with IAR Added description.
		104	9.1 Precautions regarding On-chip Debugger Connection after Bank Swap Added description of IAR.
		106	11 Reference Documents Deleted APN related to using SMS.
1.11	Feb.2.26	97	Modified missing display elements in Figure8.1
		106	11 Reference Documents Added User's guide of Smart Configurator

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

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